

Embedded Highlights



V4.0.1

Combine Technologies Realize EMBEDDED Designs

The perfect symbiosis for wireless internet connectivity, powerful mainboards, professional displays and innovative storage solutions.

RUTRONIK





Combine Technologies 4



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Committed to Excellence

Consult - Know-how. Built-in.

The Technical Competence from RUTRONIK

Worldwide and individual consulting on the spot: by competent sales staff, application engineers and product specialists.

Components – Variety. Built-in.

The Product Portfolio from RUTRONIK

Wide product range of semiconductors, passive and electromechanical components, displays & monitors, boards & systems, storage and wireless technologies for optimum coverage of your needs.

Logistics – Reliability. Built-in.

The Delivery Service from RUTRONIK

Innovative and flexible solutions: from supply chain management to individual logistics systems.

Quality - Security. Built-in.

Quality Management without Compromise

The integrated management system (IMS) encompasses quality control, information security, environmental protection, occupational health and safety.

Combine Technologies – Realize EMBEDDED Designs

RUTRONIK EMBEDDED – the most reliable option for future-orientated purchase of embedded components from one hand. We are well-known as distributor of embedded boards & systems, power supplies, storage components, TFT displays, passive LCDs, professional monitors, as well as wireless connectivity solutions, sensors and all needed electromechanical components to build up an intelligent embedded system for the emerging IoT market.



Boards & Systems

Embedded Boards & Systems

Whether industrial mainboards, single board computers, computer-on-modules or complete embedded systems, like panel PCs, box PCs, 19" rack systems, or industrial monitors for harsh environments, with our selected partners we cover almost any customers requirement.

Power Supplies

One of the most critical part in any embedded system is the power supply, so that a reliable partner is needed, to build up a reliable system. RUTRONIK EMBEDDED is taking care of this issue with its partners. So we can provide solutions with medical approvals as well as standard industrial power supplies in the well-known standards and as open frame solutions. More and more systems in the IoT market need to resist against power grid failures with an uninterruptable power supply. This can be realized by a classic battery driven UPS or by Super Caps. Our specialists can guide you through your system design, starting with the power supply and ending with the intelligent platform above.

Sensors

Embedded applications often collect environmental data or have to provide an HMI. The sensor portfolio includes magnetic, optical and MEMS sensors, e.g. from market and innovation leaders Bosch Sensortec and STMicroelectronics. So called application specific sensor nodes (ASSNs) running fusion software combine different sensor types in a single package with up to nine degrees of freedom (DoF). Integrated proximity and ambient light sensors in combination with infrared LEDs provide touchless gesture control functionality. With this portfolio and our sensor expertise, we are offering the optimum solution for your application.

Electromechanical Components

The whole world of IoT can't work without connectors and hard wiring, so at the end, RUTRONIK EMBEDDED is also taking care of your wired connectivity. Even inside an embedded system or DIN-rail mounted, we can provide you the needed solutions in combination with all the other components.



Storage

Flash memories become more and more important in industrial applications, even as a simple 2.5" SSD or as a flash card in different form factors. Also HDDs, RAM and ODDs for industrial and rough applications with high reliability in industrial grade quality and with a reasonable longevity, are still needed. With our partners we can provide all of the demanded solutions in a good balance between reliability and price.



Displays & Monitors

With our portfolio of active TFT solutions, passive LCDs, OLEDs and professional monitors, we can fulfill every demand for the visible front-end of an embedded system. Standards are also available, as well as fully customized or semi customized solutions. Especially with passive LCDs we still can offer different technologies to take care of the uncountable new and smart entry level designs for the IoT market. The latest touch technologies, as well as the best picture quality, RUTRONIK EMBEDDED is offering a huge portfolio for your embedded system design.



Nireless

Make your application embedded by connecting it wirelessly to the Internet of Things. RUTRONIK EMBEDDED has the newest solutions for using a smartphone, WiFi access point or a mobile communication network as gateway for your device. Our understanding of the right wireless solution covers hardware, drivers or transmission protocol, application profiles, security aspects, certifications, long-term considerations as well as political aspects regarding standards, compatiblity and consortia.























RUTRONIK EMBEDDED









Boards & Systems

Displays

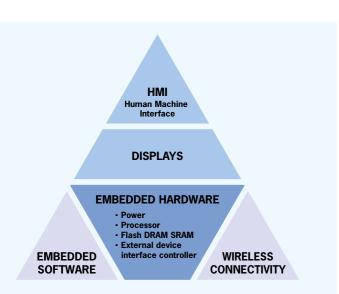
Individual System Solutions

Combine Technologies

The performance of embedded systems is growing disproportionately; one of the reasons for this is the improvement of intelligent sensors and actuators. There are more and more autonomous systems which record and process data, responding very specifically to it. When the systems are networked together wirelessly or wired via IP protocol this creates the Internet of Things. Machines, systems, appliances and small smart everyday objects will become part of the so-called Cyber Physical Systems (CPS) in the future.

All systems are characterized by certain common characteristics: Programming capability, storage capacity, functional user interfaces and communication links. Embedded systems require integrated vision when selecting the components because there are complex dependencies between the real physical and the virtual digital world.

RUTRONIK EMBEDDED complies stringently with this integrated analysis, enabling it to develop always the right solution.



Cyber Physical Systems (CPS) comprise the networking of

Boards & Systems

based on ever faster, more powerful, smaller and energysaving components. Suitable and standardized power supplies, sensors and electromechanical components which guarantee functional reliability even under extreme operating conditions

Storage

solutions in compact sizes with any number of read/write cycles with the highest storage density

Displays

and touch systems, which provide the user a perfect visualization and operation of the real world and facilitate intuitive operation and the interaction of extremely complex systems

Wireless

technologies facilitate the global linking of processes and databases in all conventional transmission standards and in a matter of seconds









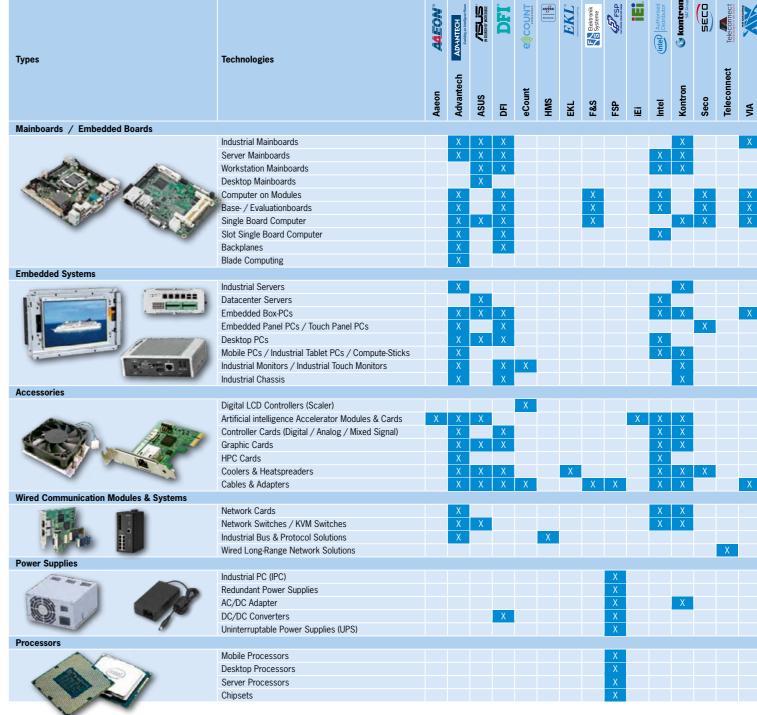






RUTRONIK EMBEDDED offers a huge portfolio of mainboards, specially designed for industrial and semi-industrial applications. The selection ranges from industrial mainboards, single board computers, computer-on-modules (COM), PC/104, blade computers, PICMG and backplanes, IPC and servers to box and panel PCs and HMI. These include ARM-based solutions as well as boards with the latest x86 processors.













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Industrial Mainboards by Kontron



For more than 30 years, mainboards have been developed and produced in our Augsburg factory. Kontron puts special emphasis on highest product quality, long-term availability and direct technical support by the manufacturer. Mainboards by Kontron reliably work in thin clients, servers and complete system solutions for industrial customers. With an annual production volume of around 2.5 million units, Kontron is the leading European manufacturer of mainboards.

R&D

- Design know-how based on more than 30 years of experience with mainboard design
- Synergy between other designs (industrial mainboards are derived from Kontron standard portfolio)

Quality

- 3-Level inspection after production (AOI, ICT, UFT) on each board
- Due to 96% automatic production we are able to assure low RMA-rates (0.3% at present!)

Reliability

- Optimized Motherboard designs (less components)
- less heat
- less power consumption
- less risks)
- 1st supplier qualified material only

Longevity

- Professional Lifecycle Management (ECN / PDN / LTB / EOL) announcements
- Longterm availability

Innovation

- Optimized Feature and design to reduce power comsumption
- Simplify product selection with new features (Dual Power Supply Option 12V DC & ATX)

Technical Support

- 1st level support: Distribution part-
- 2nd level support: Direct technical support from Kontron
- Competitive price models

Mainboard SMARTCASE™ Family

Flexible. Versatile. Long Term Availability.

The chassis kit solutions are available in different versions and designed for different mainboards. The thin and smart chassis allows the usage in horizontal and vertical position, partly even in enhanced temperature related environments.

Kontron Mainboards powered by the latest Intel® Technology Platforms





Smartcase[™] Series







Lake SoC

D3543-S D3544-S

Intel® 8th Gen Core™ i Processor Series

- Mini-STX ■ Intel® Gemini
- Mini-ITX ■ Intel® Gemini Lake SoC



D3634-S

■ Mini-ITX

Chipset

socket

LGA 1151

■ Intel® H310



- Mini-ITX
- Intel® Q370 Chipset LGA 1151 socket



μATXIntel® C246 Chipset LGÁ 1151

socket

■ ATX Intel® C246 Chipset LGA 1151 socket

D3646-S

Key Features

■ Intel® Gemini Lake SoC

Mini-STX

SMARTCASE™ S Series





- **Key Features** Mini-STX
- Intel® 8th Gen Core™ Technology (LGA1151)
- 0.871!



Key Features

Mini-ITX ■ Intel® Gemini Lake







- Mini-ITX
- Intel® 6th / 7th / 8th Gen Core™ Technology (LGA1151)
- 2.48











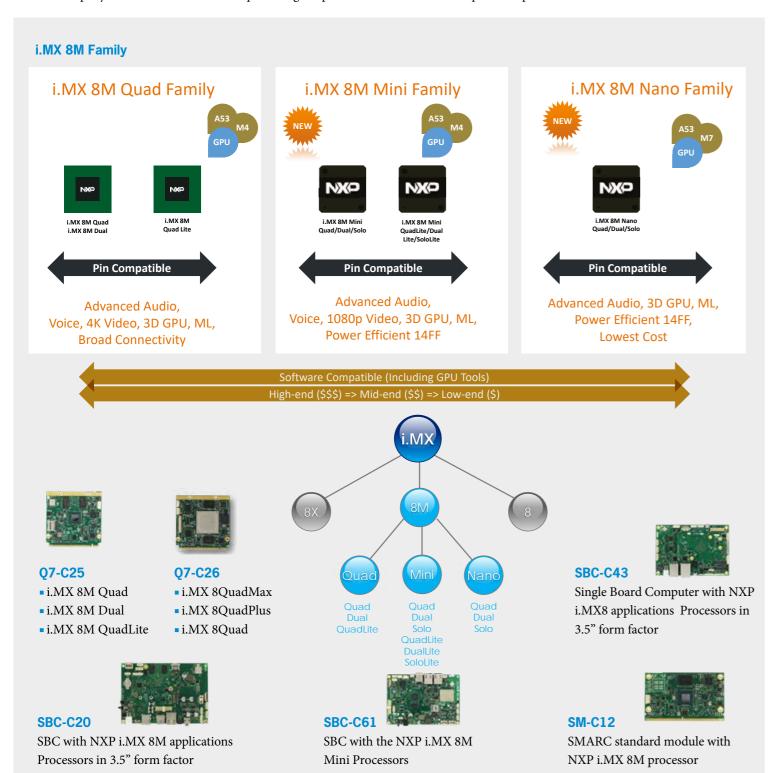


Embedded Boards & Systems by SECO

Ideal Technological Partner for Cutting-Edge Solutions

SECO is an Italian industrial group with a strong international presence that operates in the sector of high technology in the miniaturization of computers and the Internet of Things (IoT). They designs and produces in-house embedded systems and IoT solutions: from the single microcomputer to integrated and "ready-to-use" systems.

The company offers its customers a complete range of products and services with specific expertise in numerous industrial sectors





N-Series Intel Pentium / Celeron and x5-Series Atom SOCs





Qseven® Rel. 2.1 with the Intel® Atom™ E39xx family, Intel® Celeron® N3350 and Intel[®] Pentium[®] N4200 SoCs



SBC-A80-eNUC

Embedded NUC™ SBC with the N-series Intel® Pentium®/Celeron®



SM-B69

SMARC with the Intel® Atom™ E39xx Intel® Celeron® N3350 family,and Intel® Pentium® N4200 SoCs



SBC-B68-eNUC

Embedded NUC™ SBC with the Intel® Atom™ E39xx family, Intel® Celeron® N3350 and Intel® Pentium® N4200



COMe-C24-CT6

COM Express™ 3.0 Compact Type 6 Module with the Intel® Atom™ X Series, Intel® Celeron® J/N and Intel® Pentium® N Series



SBC-C41-pITX

Intel® Atom™ X Series, Intel® Celeron® I / N Series and Intel® Pentium® N Series Processors

Ryzen Series



COM Express™ Compact 3.0 Type 6 Module with the AMD Ryzen™ Embedded V1000 processors





COM Express™ Rel.3.0 Basic Type 7 module with the











AMD EPYC™ Embedded 3000 Series of SoCs

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Embedded Edge Computer Solutions by ASUS

Industrial Motherboards and Single Board Computers

ASUS offers a wide range of long-lifecycle industrial motherboards and & single board computer in various form factors to serve different applications from customers. ASUS industrial motherboards and & single board computer are manufactured with extremely durable, industrial-grade components to ensure 24/7 reliable operation in industrial settings and harsh environments like extreme temperatures, power fluctuations and high humidity. Also, ASUS provides the longevity supply guarantee, optimized service and completed reference documents for our customers. We not only provides international industry standard form factor models, but also offers customized hardware and software solutions for specific applications.

Wide Range Portfolio



ASUS Edge Computer Proposition

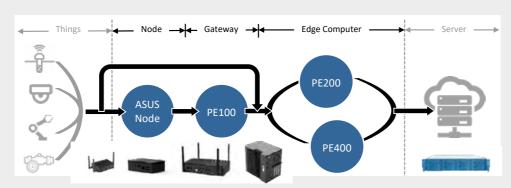
ASUS's offers a wide range of long-lifecycle industrial motherboards and & single board computer in various form factors to serve different applications from customers. This boards are manufactured with extremely durable, industrial-grade components to ensure 24/7 reliable operation in industrial settings and harsh environments like extreme temperatures, power fluctuations and high humidity. Also, ASUS provides the longevity supply guarantee, optimized service and completed reference documents for our customers.

PE200U

Intel[®] Core[™] i7/i5/i3 Processor, Intelligent Edge Computer with mini PCIe slot, DDR4 2400 MHz, DP, HDMI, Dual-LAN, Multiple COM, 12-24 V DC

PE200S

Intel®Atom® X Series Processor, Intelligent Edge Computer with mini PCIe slot, DDR3L 1866 MHz, DP, HDMI, Dual-LAN, Multiple COM, 12-24 V DC



Sensor Fusion

- Data aggregation
- Data normalization
- Data processing
- Data forwarding

Edge Inference

- Secure virtualization
- Workload consolidation
- Real-time analytics (AI)

Data Center

Data storage

- Data training
- Data analytics 4-Way NVIDIA® Quadro RTX™ support
 - ECC memory
 - Scale up & scale out
 - certification

Professional, ISV certified ESC/E series workstations have server-grade computing power, incredible expandability and advanced I/O, best suited for content creators, professional VR applications, and heavy entertainment loads.

Server and Workstation Motherboard

Workstation

ASUS Server and Workstations

Why ASUS for Server Business?

For AI and visual computing, the

ESC series accelerator servers deliver

with patterned electronic designs and

high availability (HA) thermal solu-

ASUS offers a comprehensive rack/

tower server product line featuring

high computing density, high expan-

dability, and high manageability, ideal

extreme performance and stability

Accelerator Server

Rack/Tower Server

for multi-workload.

ASUS offers the most reliable server and workstation motherboards with industry-leading performance, high power-efficiency, and complete IT infrastructure management.

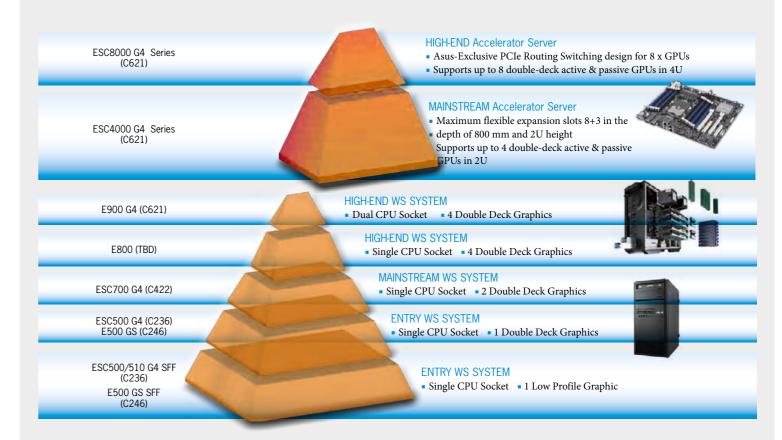
Accessories

OCP Mezzanine cards, high speed LAN cards, and ASUS-exclusive PIKE RAID cards provide the fastest interconnects and highest storage expandability for datacenter topology.

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Benefits

- Focused and unique flexibility
- + customization
- 5yr longevity supply
- NL hub operation fulfill demand 80+% in 1 week
- Warranty service
- 3 year advanced replacement service
- A local FAE team provide technical support in zero time difference



- Extreme 2P performance

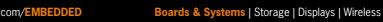
- Independent software vendor (ISV)

- Powerful performance and ECC memory
- Comprehensive IT infrastructure management software
- Multiple graphics card support
- Ultrafast storage and I/O options
- Dual Intel server-class Gigabit LAN

- Powerful performance with Intel® Xeon® E processor and ECC memory
- Supports up to three independent displays simultaneously via HDMI, DisplayPort, DVI-D and VGA
- High Speed USB 3.1
- Graphics card support, including NVIDIA® Quadro® M5000 (option)
- Independent software vendor (ISV) certification











Embedded Boards & Systems by DFI



Founded in 1981, DFI is a global leading provider of high-performance computing technology across multiple embedded industries. With its innovative design and premium quality management system, DFI's industrial-grade solutions enable customers to optimize their equipment and ensure high reliability, long-term life cycle, and 24/7 durability in a breadth of markets including factory automation, medical, gaming, transportation, smart energy, defense, and intelligent retail.

1.8" SBCs

DFI's 1.8" SBC board measuring only 84mm x 55mm, is fanless and is ideal for spaceconstrained applications such as factory automation.



- Intel Atom® Processor E3900 Series
- Single Channel LPDDR4 Memory Down up to 4GB
- 1 Mini DP++, 2 GbE, 1 COM, 3 USB
- 1 Mini PCIe, 1 SMBus
- Up to -40 to 85°C operating temperature

2.5" PICO-ITX

DFI's Pico-ITX SBC board (100 x 72 mm) support low power consumption and fanless design with rich I/O connectivity in order to target space-limited embedded applications like site management and IoT gateway.



- Intel Atom® Processor E3900 Series & N Series
- Single channel DDR3L, 1 SODIMM up to 8GB
- 1 VGA, DP++, 1 LVDS, 2 GbE, 1 COM, 4 USB
- 1 Mini PCIe, 1 M.2
- Up to -40 to 85°C operating temperature



- MX6 Cortex-A9 ■ 1GB/2GB SDRAM
- Memory Down
- 1 HDMI,1 LVDS, 2 GbE, 2 COM, 2 USB
- 1 Mini PCIe,
- 1 SDMini-ITX



AL05P

- Intel Atom® Processor E3900 Series
- Memory down LPDDR4 up to 4GB
- 1 mini DP++, 1 GbE, 1 COM, 4 USB
- 1 PoE PD 802.3AF
- Up to -20 to 70°C operating temperature

DFI's embedded Mini-ITX motherboard (measuring to only

for low power solution with passive cooling and DC input

features and for desktop solution with high performance.

170mm x 170mm) is designed with a variety of I/O connectors

This compact and highly integrated board delivers rich I/O and

expansion slots; which makes it an ideal solution for KIOSK,

CS100

Mini-ITX

• 8th Gen Intel ® Core™ Processors

gaming, and digital signage, etc.

- Dual channel DDR4, 2 SODIMM up to 32GB
- ■1 VGA, 1 LVDS, 1 DP++, 2 GbE, 2 COM, 12 USB
- 1 PCIe x16, 1 Full-size Mini PCIe (& mSATA)

GH171

- AMD® Ryzen™ V1000/ R1000 Mini-ITX
- 2 DDR4 3200MHz ECC SODIMM up to 32GB
- Four independent displays: 4 DP++
- Multiple expansion: 1 PCIe x16, 1 M.2 M Key
- Rich I/O: 2 GbE, 6 COM, 3 USB 3.0, 6 USB 2.0

Industry-Specific Embedded System

The industry-specific embedded system family is designed to meet diversified application-specific requirements including medical, digital signage, gaming, etc.

It is built with high quality industrial-grade components to enable durable and reliable 24/7 operation in computingdemanding surroundings.



VC230-BT

- · Anti-vibration and fanless In-Vehicle computer
- Supports ignition delay on/off function
- 1 mSATA, eMMC (optional), microSD (optional)
- Supports Wi-Fi, 3G, and GPRS application

MD711-SU

- 6th Generation Intel® Core™ Medical Computing System
- 2 DDR4 SODIMM up to 32GB
- 1x 2.5" SATA 3.0 drive bay
- Supports 1 PCIe 16, 1 Mini PCIe, 1 M.2 slot
- 4KV Isolated I/O ports: 2 Intel GbE, 2 COM, 2 USB 2.0

Module Panel PC

Adaptive Display Platform (ADP) Technology is an advanced configure solution for Panel PC. It is a flexible modular system which provides easy maintenance, installation and configuration for customers.

Configure by Demand



Different Requirements















Configure by Demand





Application Ready

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Fanless Embedded System

DFI's compact embedded systems, including fanless embedded computer and fanless embedded box pc powered by state-of-the-art processors, deliver low power consumption in an ultra-small size as well as efficient fanless thermal solutions. The systems are also designed with IP30-rating, wide voltage input, and extended operating temperature. Making them ideal candidates for industrial applications in harsh environments.



EC800-AL

- Intel Atom® Processor E3900
- 2GB/4GB/8GB LPDDR4-2400 memory onboard
- Triple independent displays: 1 VGA/DVI-D + 2 DP/HDMI
- Supports 1 Mini PCIe & 2 M.2 slots
- Rich I/O ports: 2 Intel GbE, 2 COM, 4 USB



- Intel Atom® Processor E3900 Series
- 2GB/4GB LPDDR4 memory onboard
- DP++ supports up to 4096x2160 @ 60Hz
- Rich I/O ports: 2 Intel GbE, 1 COM, 3 USB



EC900-FS6

- ARM-based Fanless Embedded System
- 1GB/2GB DDR3L memory onboard
- 8GB/16GB eMMC for storage ■ DIN Rail Mount
- Rich I/O ports: 2 GbE, 2 COM, 2 USB 2.0, 1 USB OTG









Embedded Boards & Systems by Advantech



Worldwide Leader in Embedded Design and Services

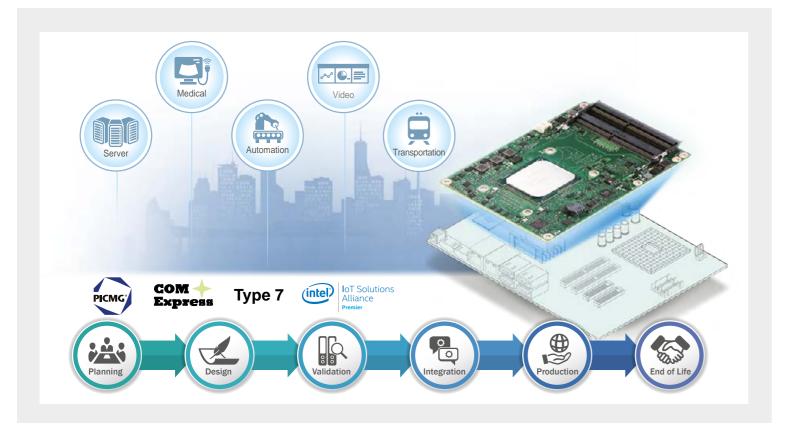


Computer On Modules

Accelerate Application Development with Dedicated Design-In Services

To help customers accelerate the development of their core competencies, computer-on-module (COM) systems can be utilized to reduce the time and effort involved in designing new carrier boards.

Advantech's COM series includes the COM-Express series, ETX, and Qseven, all of which offer additional design-in services that provide small form factor support while also supporting the latest Intel CPUs.



Fanless Embedded Computers

Modular System for Quick Equipment Integration

Advantech provides full customization services including a selection of offerings for I/O modules, OS software, and peripherals. You can choose from a flexible range of modular I/O options without concern for additional customization time, NRE, or costs. With our modular I/O design, you can rapidly implement your applications with maximal benefits.



Embedded Single Board Computers

Enabling Next-Generation Industrial Applications

Advantech offers compact industrial-grade embedded single-board computers (SBCs) with rugged design, high flexibility, and easy expansion capabilities. Our range of product offerings vary from the 2.5" Pico-ITX and 3.5" SBC, to PC/104 and 5.25" EBX. Moreover, our innovative multi-I/O expansion design, which features multiple integrated I/Os and flexible design can facilitate system development, maximize resource efficiency, and assist integrators in providing optimized solutions that are more cost-effective.











Embedded Boards with F&S





Intel® 1/2.5/10/25/40 GbE Ethernet Adapters

The Intel® Ethernet 800 Series with flexible Ethernet port configuration supports different link modes and speeds, includes powerful capabilities to accelerate network performance, and delivers workload-optimized performance and consistent application performance for latency-sensitive workloads. Move data faster with Intel® Ethernet 800 Series with throughput up to 100Gbp/s.

Board Strategy

If during development phase or a later redesign the requirement for higher processor power or more interfaces comes up, this can lead to serious problems. But this is not valid for boards by F&S Elektronik Systeme. Every board family by F&S Elektronik Systeme offers pin and software compatible boards. More boards are introduced annually and are added to the board family or replace faced out boards (not before 10 years). With this board strategy by F&S Elektronik, the customer has to take no risks. Depending on the customer's requirements, one of the board families can be employed, every board family meets different conditions.

F&S Project Guarantee

major customers all over Europe.

F&S Elektronik Systeme offers a project guarantee for all its customers. We will solve together all upcoming problems during development (hardware, as well as software) and fulfill your wishes. Aim is to complete the customer's project successfully and to continue supporting after the start of the series production and throughout the lifetime of the project. Another important feature of the project guarantee is the long-term availability of at least 10 years. Our project guarantee paved the way for F&S boards in numerous applications of



Boards - Overview

Board Family	armStone™	efus™	PicoCore™	QBliss	PicoCOM™	PicoMOD	NetDCU	PCOMnet
Board Type	SBC	COM	COM	COM	COM	COM	SOM	SBC
Baseboard Complexity	-	easy	easy	advanced	easy	easy	very easy	-
CPU Performance Up To (Cores)	Cortex-A9 (4)	Cortex-A53	Cortex-A53 (4)	Cortex-A9 (4)	Cortex-A9 (1)	Cortex-A9	Cortex-A9	Cortex-A9
Windows	~	~		V	V	V	~	V
Linux	~	~	V	V	V	V	V	V
Standard	PicoITX Formfaktor	FS	FS	Qseven second source	FS	FS	FS	FS
LCD Interface	RGB LVDS	RGB LVDS	RGB, LVDS, MIPI-DSI	LVDS	RGB	RGB LVDS	RGB	EDT RGB
Screen	DVI	DVI	-	DVI	-	DVI	-	-
Color Depth Up To	24Bit	24Bit	24Bit	24Bit	18Bit	24Bit	24Bit	18Bit
Resolution Up To	FullHD	FullHD	1080p60	FullHD	WXGA	WXGA	FullHD	WVGA
DATA-BUS	-	-	-	-	-	~	✓	-
Camera	-	v	v	V	-	V	-	-
Ethernet	2x	2x	2x	2x	2x	1x	2x	2x
Power Supply	5V	5V	5V	5V	3.3V	3.3V	5V	5V
Size (mm)	100x72	47x62.1	35x40	70x70	40x50	80x50	100x80	80x50
Plug Connector	66pin	MXM-2 230pin	2x 80pin	MXM-2 230pin	80pin	140pin	142pin	-

- Supports multiple port speeds with a single architecture: 100/50/25/10/1GbE
- Application Device Queues (ADQ)
- Dynamic Device Personalization (DDP)
- Enhanced Data Plane Development Kit (DPDK)
- iWARP and RoCEv2 Remote Direct Memory Access (RDMA)
- Intel® Ethernet Adaptive Virtual Function (Intel® Ethernet AVF)
- Enhanced server virtualizations: 256 VFs, 768 VSIs
- Optimized Advanced Transmission Scheduler
- Extensive Network protocol support
- IEEE1588/Precision Time Protocol

Intel® Ethernet products are customers' choice for extensive compatibility, performance assurance, broad product selection, and world-wide support.

Enterprise

 Broad physical interfaces support, thorough test and validation with ecosystem devices for compatibility

Overview Intel® Ethernet 800 Series supports up to

100Gb/s throughput for a variety of workloads.

Extensive Microsoft solution support

Communications

- Flexible Ethernet Port Configuration with link modes supporting different fan-in or fan-out connections
- DDP, with fully programmable pipeline, can add or modify protocols on-demand allowing for fast-paced innovations
- Enhanced DPDK for Network Functions Virtualization acceleration, advanced packet forwarding, and highly efficient packet processing
- IEEE1588 Precision Time Protocol (v1 and v2) with per-packet time stamping

Cloud

- Up to 100Gb/s throughput for diverse workloads in modern
- Support both iWARP and RoCEv2 RDMA, selectable via software per port for low-latency, high-throughput
- Application Device Queues (ADQ) to increase application predictability, reduce application latency and improve application throughput











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Intel® NUC Kits, Boards & Mini PCs High-End Computing, Low-Profile Style



Intel® NUC Elements



Intel® NUC Elements High-Performance, Modular Elements for a Range of Verticals

Start with an Intel NUC Compute Element with the exact processor you need and plug it into an Intel NUC Board Element, your own board, or another third-party board, then embed it into your solution to create unique solutions for your customers' needs. From embedded deployments to rugged systems in unique environments, to full systems in a business or vertical environment, the Intel NUC Elements let you deliver custom solutions with minimal R&D time.

Ultra Small Form Factor | Space Saving | Versatile Usage | Performance | Stunning Visuals | Low Power Usage

Pint-sized Power

The Intel® NUC is a mini PC with the power of a desktop, packing features for entertainment, gaming, and productivity in a 4x4 form factor.

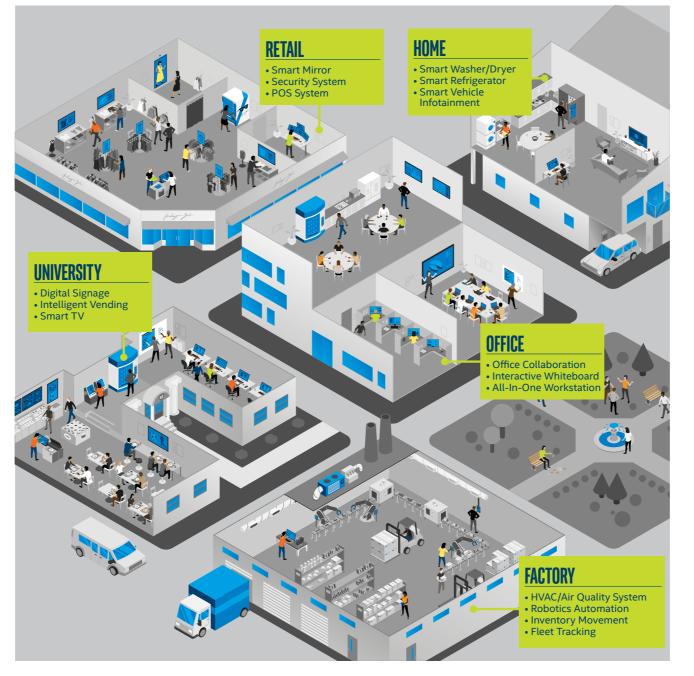
Energy Optimized, Media Savvy

With Intel® NUC, you get an immersive media experience and responsive interaction while consuming a small amount of power relative to a full-sized PC.

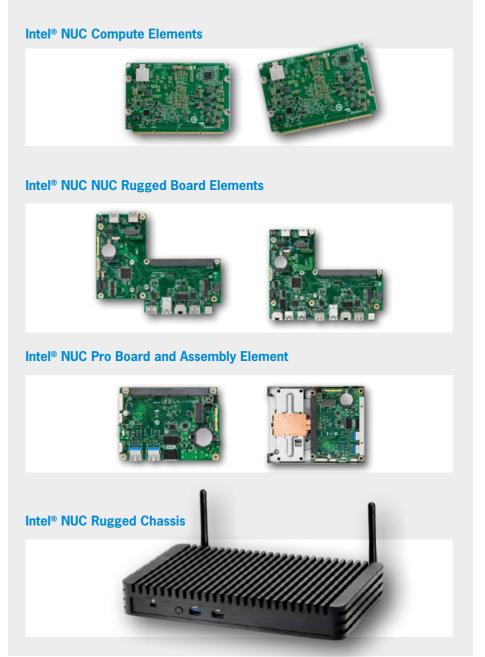
Flexibility for Future Growth

Due to its portable size and ease of installation, the Intel® NUC makes it easy to add devices and scale up rapidly based on changing productivity needs.





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Intel[®] RealSense™



Intel ® RealSense™ offers multiple products based on technologies like LiDAR, Stereo and Coded Light to experience and measure the world.





Camera Features	
Use Environment	Indoor
Technology	LiDAR
Depth FOV	70° x 55° (2 ±2°)
Depth Output Resolution & Frame Rate	Up to 1024×768 depth resolution. 30 fps
Minimum Depth Distance (Min-Z)	0.25 m
Maximum Distance	9 meters (VGA resolution, with a maximum Z error of 15.5 mm at that distance)
Max RGB Resolution & Frame Rate	1920 × 1080. 30 fps
Physical Parameters	
Form Factor	Camera Peripheral
Connectors	USB C* 3.1 Gen 1
Diameter × Height	61 mm × 26 mm
Major Components	
Optical Board	 Laser MEMS Mirror
Major Components	

Tracking Camera T265



Camera Features	
SLAM	V SLAM, part of Intel® RealSense™ Technology High precision Visual Inertial Odometry Simultaneous Localization and Mapping algorithms
VPU	Intel® Movidius™ Myriad™ 2.0 VPU Visual Processing Unit optimized to run V SLAM at low power
FOV	Two Fisheye lenses with combined 163±5° FOV The camera includes two 0V9282 imagers with fisheye lenses for a combined, close to hemispherical 163±5° field of view for robust tracking even with fast motion
Inertial Measure- ment Unit (IMU)	BMI055 IMU The Inertial Measurement Unit, allows for accurate measurement of rotation and acceleration of the device, to feed into the V-SLAM algorithms
USB	USB 3.1 Gen 1 Micro B
Physical Paramet	ers
Dimensions	108 mm x 24.5 mm x 12.5 mm

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Product Comparison

SKU	Baseline	Depth Sensors Shutter Type	Max. Depth Resolution Max. Frame Rate	Depth FOV (H × V)	Min. Depth Distance	Max. Range	MAX. RGB Resolution Max. Frame Rate	IMU	Dimensions
L515	N/A	Laser Scanning	Up to 1024 x 768, Up to 30 fps	70° × 55° (±2°)	0.25 m	Approx. 9 m	1920 × 1080 at 30 fps	N/A	(Diameter x H) 61 mm × 26 mm
D435i	50 mm	Global	Up to 1280 x 720, Up to 90 fps	87°±3° × 58°±1°	0.105 m	Approx. 10 m	1920 × 1080 at 30 fps	6DoF	(L x D x H) 90 x 25 x 25 mm
D435	50 mm	Global	Up to 1280 x 720, Up to 90 fps	87°±3° × 58°±1°	0.105 m	Approx. 10 m	1920 × 1080 at 30 fps	N/A	(L x D x H) 90 x 25 x 25 mm
D415	55 mm	Rolling	Up to 1280 x 720, Up to 90 fps	65°±2° × 40°±1°	0.16 m	Approx. 10 m	1920 × 1080 at 30 fps	N/A	(L x D x H) 99 x 20 x 23 mm

The Intel® RealSense™ Depth Camera is also available as Bulk Version for implementation in vending machines, robots, VR devices and other use cases,



Intel® Movidius™ & OpenVINO™

Accelerate Deep Learning Development At The Edge

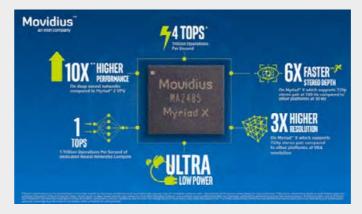


What is the Intel® Movidius™ Neural Compute Stick?

This tiny, fanless deep learning device allows you to learn AI programming at the edge. It is powered by the same high-performance Intel® Movidius™ Vision Processing Unit (VPU) that can be found in millions of smart security cameras, gesture controlled drones, industrial machine vision equipment, and more.

Learn What You Can Do with a Neural Compute Stick 2

Enable rapid prototyping, validation, and deployment of deep neural network (DNN) inference applications at the edge. The low-power vision processing unit (VPU) architecture enables an entirely new segment of AI applications that are not reliant on a connection to the cloud.





Neural Compute Engine: Hardware Based Acceleration for Deep Neural Networks

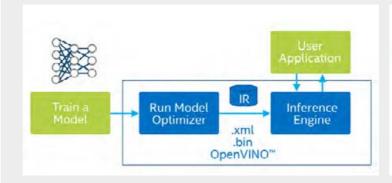
Myriad[™]X features the all-new Neural Compute Engine – a purpose-built hardware accelerator designed to dramatically increase performance of deep neural networks without compromising the low power characteristics of the Myriad VPU product line. Featuring an array of MAC blocks and directly interfacing with the intelligent memory fabric, the Neural Compute Engine is able to rapidly perform the calculations necessary for deep inference without hitting the so-called "data wall" bottleneck encountered by other processor designs. Combining the neural network performance of the 16 proprietary SHAVE cores with the neural compute engine, Myriad X delivers 10X the performance compared to previous generations*.

OpenVINO[™] – Develop Multiplatform Computer Vision Solutions

Make your vision a reality on Intel® platforms—from smart cameras and video surveillance to robotics, transportation, and more.

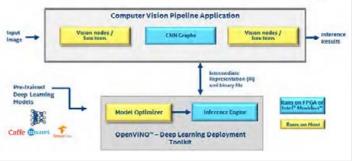
Your Computer Vision Apps...Now Faster

Develop applications and solutions that emulate human vision with the Open Visual Inference & Neural Network Optimization (OpenVINO[™]) toolkit. Based on convolutional neural networks (CNN), the toolkit extends workloads across Intel® hardware and maximizes performance.



Inference Support

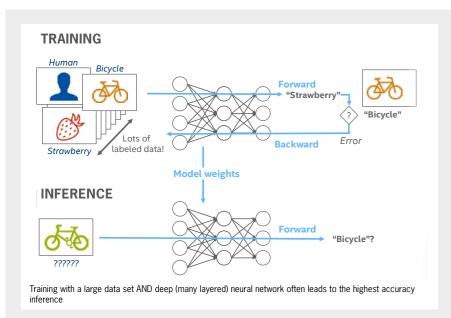
In addition to supporting processors with and without integrated graphics, this toolkit enables acceleration on an Intel® Programmable Acceleration Card and Intel® Movidius™ Vision Processing Unit. For the best experience, use the toolkit with the Intel® Movidius™ Neural Compute Stick and cards based on Intel[®] Arria[®] 10 FPGA GX.

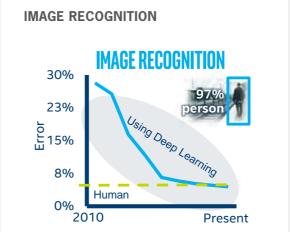


Artificial Intelligence Vision Accelerator Cards

Vision hardware is popular. Without difficulty it provides a wide range of information which can be extracted. What appears simple on the one hand can be difficult to manage on the other hand when it comes to requirements like:

- A minimum of processing time and power con- Possibility to deal with huge amounts of sumption when thinking of edge applications
 - data and scale with different workloads
- Maximum precision in image recognition is like to find a needle in the haystack





Machines are able to meet or exceed human image & speech recognition e.g. tumor detection, document sorting, oil & gas search, defect detction, genome sequencing

All cards are based on Intel Movidius Myriad X and Intel Arria FPGA. Cards are designed to run pretrained models (inference).

iEi

Туре	Mustang-M2AE-MX1	Mustang-M2BM-MX2	Mustang-MPCIE-MX2	Mustang-V100-MX4	Mustang-V100-MX8	Mustang-F100
						0.0
Chipset	1x Intel® Myriad X	2x Intel® Myriad X	2x Intel® Myriad X	4x Intel® Myriad X	8x Intel® Myriad X	1x Intel® Arria 10 1150GX
Formfactor	M.2 A+E Key	M.2 B+M Key	Mini PCle	PCle	PCle	PCle
Dimensions	22 x 30 mm	22 x 80 mm	50.5 x 30 mm	113 x 56 x 23 mm	169.54 x 56.16 mm	169.5 x 67.6 x 33.7 mm
Operating Temperature	-20 °C to 60°C	-20°C to 60°C	-20 °C to 60 °C	-20 °C to 60 °C	-20 °C to 60 °C	5 °C to 60 °C
Power Consumption	~ 4.5 W	~ 15 W	~ 7.5 W	~ 15 W	~ 25 W	~ 40 W

AD\ANTECH

Enabling an Intelligent Planet		
Туре	VEGA-320	VEGA-330
Chipset	1x Intel® Myriad X	2x Intel® Myriad X
Formfactor	M.2 A+E Key	Mini PCle
Dimensions	22 x 30 mm	30 x 50.95 mm
Operating Temp.	0°C to 45 °C	0°C to 45 °C
Power Consumption	~ 3.8 W	~ 7.6 W

44EON

Туре	Al Core X	Al Core XM 2280	Al Core XP4/ XP8
Chipset	1x Intel® Myriad X	2x Intel® Myriad X	4 / 8 Intel® Myriad X (via M.2 M Key Card)
Formfactor	Mini PCle	M.2 B+M Key	PCle
Dimensions	30 x 51 mm	22 x 80 mm	167 x 111 mm
Operating Temp.	0 ° to 60 °C	0 °C to 50 °C	0 °C to 50 °C
Power Consumption	< 4 W	~ 15 W	Depending on config.

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Embedded Systems & Industrial PCs



Founded 1989 in southern Germany, exone has established to a leading german manufacturer for PC Systems. With three brands, exone covers professional IT-Systems for the classical business field, industrial PCs, tablets, workstations and servers. Their fanless Box-PCs, Panels and Gateways are made for harsh environments and long time availability. With now over 30 years of experience, an own R&D department and two production lines, exone is proud to offer quality computer Systems made in germany.

Industrial Systems with Long Time Availability



Calmo Tiny - Small, Smaller, Tiny

The demand for small computer systems is constantly increasing in industrial environments. However, the performance of these systems must not be limited by the compactness of the housing dimensions. With the Calmo TINY series you can rely on the smallest PCs, with the latest and most powerful Intel CPU technology and 100% industrial quality. Designed for 24x7 continuous operation and stability in the temperature range of 0 - 55 °C, we offer additional functions such as TPM, GPIO, Watch Dog and a wide range input of 8 - 24 volts in addition to these two core features. The Calmo TINY - a mini industrial system at the highest level!

Highlights

- Latest Intel® Gemini Lake processor technology
- Two monitor operation with UDH possible
- Optional serial interface
- Optional USB 3.1 type C (fuse-proof)
- Wide range input from 8 to 24 V
- Suitable for digital signage

Calmo E

Calmo E can do both deskop and automation tasks. With up to 32 GB RAM and NVMe SSD it is providing enough power for nearly every usecase in business, production environment and even in digital signage. The simple design of the Calmo E is fanless and therefore noiseless, the integrated VESA-Mount makes it easier to fix the ipc to machines, displays or shelves. Calmo E is reduced to the essential interfaces, this is shown also by the price.

Highlights

- Only focused interfaces
- German case design
- Intel Core CPUs
- Passive cooling



Calmo XS – x-Trasmall Box-IPC with Professional Interfaces

Control-units, digital-signage-player and hardware-firewalls are getting smaller but smarter, Besides that, they are often installed in production invironments or badly reachable. Our new Calmo XS gives you all features of our Calmo TINY, but you get something on top! It is IP40 dustproof and gives you room for a 2.5" SSD, two serial ports, 8 - 24 V direct input and WiFi 6. Use the Power of its embedded Celeron and Pentium CPUs and benefit from their energy-saving architecture. Bring your display-solution, your dusty workspace and your machine-control-unit to the next level - with our new Calmo XS.

Highlights

- WiFi 6
- 1x RS485/422/232, 1x serial 4-wire
- Phoenixport or DC-Jack usable
- 8 to 24 VDC-In
- 2.5" SSD
- USB 3.1 Type C

















Embedded Systems & Industrial PCs



Pokini F2



Small, Powerful, Customizable

The Pokini F2 is a small and fanless PC with great performace, various interfaces and excellent graphics. The embedded Intel CPU has enough power for handling digital-signage an office apps as well as machine control programs. The full aluminum case is fanless and able to cool the unit. Trust in our experience, get 5 years of full warranty for free. Only rely on quality IPCs ready for 24/7 use, only rely on the Pokini F2.

Highlights

- Fanless case
- Intel embedded CPU
- Powerful and flexible
- Available through 2028



Panel-PC

Industrial Hardware - Made in Germany

On the way to unstoppable digitization, traditional production sites need high-performance and robust computers. Clear and brilliant images combined with intuitive operation using the latest touch technology, help to increase the degree of effectiveness in process flows. The classic operation of the computing unit with mouse, keyboard and a separate display is replaced and combined by the industrial panel-pc at the same time. A compact and inno-vative housing design for integration in standard production control cabinets or for mounting on corresponding mounting systems is assembled in our german factory. Our panel-PC series fit today's and tomorrow's requirements, we only offer exactly fitting solutions.

Highlights

- State-of-the-art capacitive P-CAP touch technology (10-point touch)
- Operation with latex, work and ESD gloves possible
- Fanless and attractive housing design
- Variety of interfaces through expansion options
- Concept, development and production in Germany
- Customizable, celeron up to Intel embedded CPU
- Available through 2028



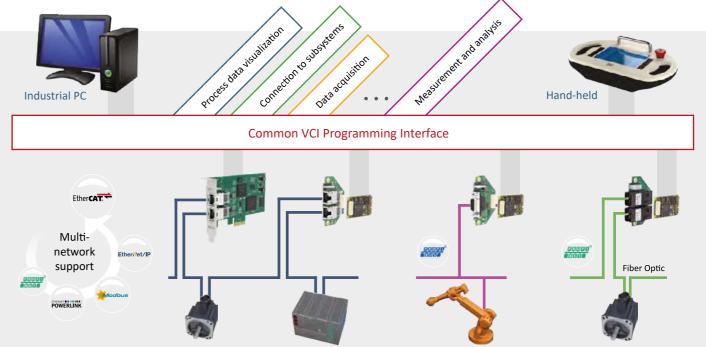
Ixxat INpact Multi-Protocol Technology

Ixxat INpact includes the Anybus CompactCom technology with the Anybus NP40 network processor – used within millions of industrial devices globally. The FPGA-based Anybus NP40 network processor provides all functions required to handle the communication between the different Industrial Ethernet and fieldbus networks and the PC-based application. The powerful multi-network approach of the NP40-based Ixxat INpact enables easy connection of PC-based or embedded slave applications to EtherNet/IP, EtherCAT, Powerlink, Modbus TCP, PROFINET IRT, PROFINET IRT Fiber Optic and PROFIBUS. Anybus NP40 provides high performance for real-time applications, making Ixxat INpact the ideal choice for demanding industrial applications.

Supported Protocols and Formats

Protocol /	Etheri\et/IP	Ether CAT.	POWERLINK	Modbus	pappo [®]		PROFU® 自由也含含
Interface Format	EtherNet/IP	EtherCAT	Powerlink	Modbus	Profinet IRT	Profinet IRT Fiber Optic	Profibus
Interface name	INpact EIP Slave	INpact ECT Slave	INpact EPL Slave	INpact EIT Slave	INpact PIR Slave	INpact PIRFO Slave	INpact DPV1 Slave
PCIe (standard slot-brackets)	4	4	4	✓	~	~	4
PCIe (low-profile slot-brackets)	4	4	4	✓	4	~	4
PCIe Mini	~	✓	✓	4	✓	✓	4
M.2	~	~	~	4	4		4

Uniform Driver Interface for all INpact Cards













Intel® Processors for Every Usage



All embedded products based on Intel's 14nm technology are available for 15 years from launch, helping to minimize engineering, maintenance and support costs.







Intel® AtomTM Processors

The Intel® Atom™ x5 and x7 processors offer 2 to 4 cores with a clockrate of up to 1.6 GHz. The development of this CPU was focused on power saving and an extended temperature range. This makes this an ideal processor for a wide range of industrial use cases. Thanks to the BGA socket it can be used in extreme working conditions.

Extended Temperature Range

The Intel® Atom™ x5 and x7 processors support the industrial extended temperature range of -40 to +85 °C with a junction temperature of up to 110 °C. They can be used outdoors in public applications like digital signage or vending machines.

Stunning Visual Experiences

Intel[®] Atom[™] x5 and x7 support up to 24MP still image capture and 1080p60 video encode/decode. It could be used for entry-level single-display surveillance devices like body cams or mobile streaming devices.

Long-Lasting Performance

Enhanced battery life and Intel® Display Power Saving Technology (DPST) and Intel® Display Refresh Rate Switching Technology (DRRS Technology) allow you to keep working and playing by reducing panel backlight and refresh rate opportunistically. The TDP range from 5 to 12W makes this an ideal energy saving processor to reduce your costs

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Intel Atom® C Processor

Intel Atom® C processor, a system-ona-chip (SoC) design, delivers efficient intelligence into smaller spaces at the network edge. Used in a variety of light scale-out workloads that require very low power, high density and high I/O integration including network routers, switches, storage, security appliances, dynamic web serving, and more. With a junction temperature of up to 100 °C this processor is also ready for the use in extreme environmental conditions.

Atom® C3000 Processors - Use Less Energy

Atom® C3000 processors deliver a range of Thermal Design Power from 8.5 watts to 32 watts.

Flexible Design To The Edge

From 2 to 16 cores with speeds up-to 2.2 GHz, these processors allow you to deploy light scale-out workloads to the network edge. Integrated Intel® QuickAssist Technology (Intel® QAT) and Intel® Ethernet deliver additional value-add throughput in data transmission, security and compression acceleration.











The Intel® Xeon® Scalable processor family provides the foundation for a powerful data center platform that creates an evolutionary leap in agility and scalability. Disruptive by design, this innovative processor sets a new level of platform convergence and capabilities across compute, storage, memory, network, and security. Enterprises and cloud and communications service providers can now drive forward their most ambitious digital initiatives with a feature-rich, highly versatile platform.

Higher Per-Core Performance:

Higher Per-Core Performance: Up to 56 cores (9200 series) and up to 28 cores (8200 series), delivering high-performance and scalability for compute-intensive workloads across compute, storage, and network usages.

Greater Memory Bandwidth/Capacity:

Support for Intel® Optane™ DC persistent memory. Support for six memory channels and up-to 4 TB of DDR4 memory, per socket, with speeds up-to 2933 MT/s (1 DPC)

Intel® Ultra Path Interconnect (Intel® UPI):

Four Intel® Ultra Path Interconnect (Intel® UPI) (9200 series) and up to three Intel® Ultra Path Interconnect (Intel® UPI) (8200 series) channels increase scalability of the platform to as many as two sockets (9200 series) and up to eight sockets (8200 series). Intel® Ultra Path Interconnect (Intel® UPI) offers the perfect balance between improved throughput and energy efficiency

48 lanes of PCIe 3.0 bandwidth and throughput for demanding I/O-intensive workloads

Intel® Deep Learning Boost (Intel® DL Boost) with VNNI:

New Intel® Deep Learning Boost (Intel® DL Boost) with Vector Neural Network Instruction (VNNI) bring enhanced artificial intelligence inference performance, with up to 30X performance improvement over the previous generation4, 2nd Gen Intel® Xeon® Scalable processors help to deliver AI readiness across the data center, to the edge and back

Intel® Advanced Vector Extensions 512 (Intel® AVX-512):

With double the FLOPS per clock cycle compared to previous-generation Intel® Advanced Vector Extensions 2 (Intel® AVX2), Intel® AVX-512 boosts performance, and throughput for the most demanding computational tasks in applications, such as modeling and simulation, data analytics and machine learning, data compression, visualization, and digital content creation

Intel® Xeon® D-2100 Processor

The Intel® Xeon® D-2100 processor delivers Intel's most transformative and ground-breaking data center processor architecture in a form factor optimized for flexible, scalable, high-density network, storage, and cloud edge solutions. It brings the architectural innovations of the Intel® Xeon® Scalable platform to a system-ona-chip (SoC) processor for lower-power, high-density solutions,



integrating essential network, security, and acceleration capabilities. The 4-16 Cores that run with up to 3,00GHz offer an impressive performance level in every network based scenario. Thanks to it's high core count and the amazing performance this CPU is optimal for big data analytics, cloud services or all other demanding applications in data centers for example.











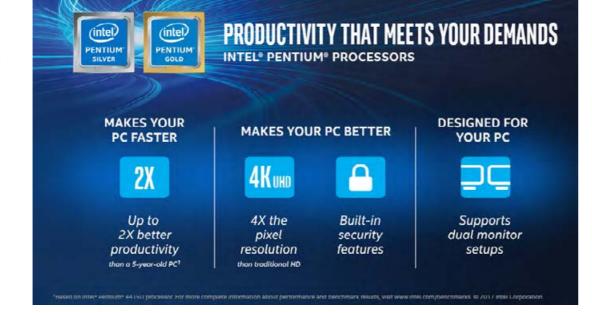












This processors are great options for value-segment buyers who need basic functionality at an affordable price. The processors are ideal for everyday computing like basic productivity, browsing visually stunning webpages, streaming 4K Ultra HD video, and editing photos. Whether it's a notebook, convertible, Chromebook*, All-in-One, mini PC or desktop PC, Intel* Pentium* and Celeron* processor-based PCs offer reliable performance at an affordable price for value-oriented buyers. With 2 to 4 cores and clockrates of up to 3.7 GHz this processor offers a wide field of applications in the entry-level segment.

Intel[®] Core[™] Processors

8th Generation - Exceptional Platform Performance

The 8th Generation Intel® Core™ processors with up to six cores for more processing power and Turbo Boost Technology 2.0 to increase the maximum turbo frequency up to 4.7 GHz, and up to 12 MB of cache memory. Intel® Hyper-Threading Technology (Intel® HT Technology) delivers up to 12-way multitasking support in the 8th generation of Intel® Core™ processors.

Features

- An impressive portfolio of standard and unlocked systems for a broad range of usages and performance levels
- New system acceleration when paired with Intel® Optane™ memory to deliver amazing system responsiveness
- Intel[®] Turbo Boost Technology 2.0 to give you that extra burst of performance when you need it
- DDR4 RAM memory technology support, which allows systems to have up to 64 GB of memory and up to 2666 MT/s memory transfer speeds
- The ability to set an overclocked ratio per core with unlocked processors, when paired with select chipset SKUs, to provide you more control and more granularity for overclocking your platform







9th Generation - Latest Processors

Intel's Coffee-Lake-S architecture is the 9th generation of Intel's Core processors. The i5 top model Core i5-9600K offers 6 cores with a basic clock of 3.7 GHz, which reaches up to 4.3 GHz in turbo mode. It has 9 MB L3 cache available. The eight cores of the Core i7-9700K use 12 MB L3 cache and come in turbo mode at a whopping 4.9GHz. This is only topped by the front-runner Core i9-9900K, which clocks up to 5 GHz in Turbo mode and has 16 MB L3 cache. Its 8 cores, which can handle 16 threads, will establish an unprecedented level of performance in the consumer market. The TDP remains at a moderate 95 watts. To keep the temperatures of this high-performance processor at a moderate level, the cores were soldered directly to the heatspreader. So the best possible performance level is delivered to the consumer market. This processor is optimal for entertainment based applications. You could use it for elaborate gambling machines or other demanding use cases like Virtual Reality and 3D gaming or rendering. It's also well equipped for other demanding applications like video editing.

Power Supply – the Heart of the System



Since Rutronik understands its role in the embedded market as a provider of all components that are needed to build an embedded system, power supplies round off our portfolio to meet the demands for one stop sourcing.

The field of industrial power supplies is huge and it is the job of an embedded partner to support customers from the beginning of a project to its mass production stage.

In the following we are providing an overview of the different fields of power supplies to show our competence and to give our customers an idea what they can expect.

FSP Product Conversion Notice

According to the implementation date of the new norm EN62368-1:201 (valid on 20.12.2020) for Audio/Video, Information and Communication technology equipment, FSP Group has started the transition of its complete range of power supply products for the safty standard EN62368-1.



Boards & Systems | Storage | Displays | Wireless

Uninterruptable Power Supplies (UPS)

If a system has to be available also in cases when the power grid is down and if there is demand for taking care of a reliable system shutdown in power failure situations an UPS is needed. We can propose also typical UPS solutions for the industrial market and we will show you in the following the range of available designs.

Line Interactive Solutions

As a typical solution with pure sine wave AC output, line interactive UPS systems are recommended for various applications to take care of power failures in industrial power grids. It stabilizes the power in any IT installation.

- Wattage: 880W / 1.6kW / 2.4kW
- Chassis Designs: Rack / Tower
- Typical applications: systems with demand for availability in case of power failures (Industrial Workstations, Industrial Servers, Medical Systems)

Online Solutions

For higher demands in case of reliability, throughput and for Input Power Factor Correction and if it is necessary to also cover current fluctuations in the power grid, online systems are the more powerful and more reliable solutions. Such systems can also be used in combination with generators and are recommended in real industrial power grids, like factories with many different machines with high lagging loads or even in generator grids.

- Wattage: 800W / 1.6kW / 1.8kW / 2.4kW / 2.7kW / 4.8kW / 5.4kW 8.0kW / 9.0kW / 16kW / 24kW / 30kW - 210kW
- Chassis Designs: Rack / Tower
- Typical applications: systems with demand for highest availability in case of power failures (Industrial Networks, Industrial Servers, Server Farms, Complete Networks)











Power Supply – the Heart of the System





Industrial PC (IPC) Power Supplies

A typical IPC Power Supply is converting AC or DC voltage into the ATX standard output voltages, so that it can power up a standard Industrial Mainboard in mini-ITX, micro-ATX or ATX form factor used in all possible industrial applications.

Under FSP IPC Power Supply portfolio, there are a lot of different form factors and power levels available. We also supply fanless ATX PSU, DC/DC ATX PSU, and specially designed PSU for POE or medical applications. The power consumption of the target system has to be investigated and calculated well. Also the chassis dimension and the cooling solution has to be considered in order to match with the Power Supply.

1U Form Factor

A 1U PSU is designed for 1U rack mount server or desktop chassis with a maximum height of 40.5 mm.

- Wattage: 250 W 750 W
- 80 Plus Efficiency Levels: Standard/Bronze/Gold/Platinum
- Cable assembly: project based customization possible
- Medical versions available
- Typical applications: 1U 19" rack mountable systems (Industrial Servers, Telecom Devices)

2U Form Factor

With a height of max 70 mm, the 2U PSU is designed for 19" rack mountable systems with demand for more internal drive bays and more interface cards.

- Wattage: 300 W 750 W
- 80 Plus Efficiency Levels: Standard/Bronze/Gold/Platinum
- Cable assembly: project based customization possible
- Typical applications: 2U 19" rack mountable systems (Industrial Servers, Network Appliances, Data Center)

Flex Form Factor

The Flex format is often used in small computer cases and sometimes called "mini-ITX" PSU. It can be used with a mini-ITX board, to reduce the system dimensions and so it is better for custom designs with its compact size. Now with Flex form factor we could achieve to supply up to 400W power max.

- Wattage: 100 W 500 W
- 80 Plus Efficiency Levels: Standard/Bronze/Silver/Gold
- Cable assembly: project based customization possible
- Medical versions available
- Typical applications: small systems with mini-ITX boards (POS/POI, Digital Signage, Small IPC, KIOSK)

ATX PS/2

- The most popular form factor in the IT market is the typical ATX PSU, also called PS/2. Here we have the biggest portfolio up to 1.200 W for high performance workstations.
- Wattage: 250W 1.200W
- 80 Plus Efficiency Levels: Standard/Bronze/Silver/ Gold/Platinum
- Cable assembly: project based customization possible
- Medical versions available
- Typical applications: typical PC Systems and Workstations, mainly combined with ATX Boards (IPC's, Industrial Automation, Industrial Workstations, Gaming)

Redundant Solutions

For a better fail-safe performance sometimes it is necessary to use a redundant PSU to take care of the system runtime in the maintenance of the PSU itself. So the second (redundant) part can take over the job from the down one. Therefor we provide several designs from slim compact 1U (1HE) form factor up to solutions for high performance servers or workstations with high power load up to 1.400 W. Interesting are also the versions in standard ATX PS/2 format with 190x150x86 mm, that can be used in standard ATX chassis.

- Wattage: 80 W 1.400 W
- 80 Plus Efficiency Levels: Standard/Silver/Gold/Platinum
- Cable assembly: project based customization possible

Boards & Systems | Storage | Displays | Wireless

 Typical applications: systems with demand for redundancy (Data Center, Networking, Surveillance, Storage Server, Broadcasting)

















Power Supply – the Heart of the System

AC/DC Adapter

Even when the PSU shouldn't be integrated into the system itself, an AC/DC adapter is recommended. So the variety of possible applications is huge, same as our adapter provided by FSP Group. In your daily life we can find external AC/DC power supplies everywhere e.g. for mobile phones, tablets or notebooks. Also a lot of medical devices are getting their power from AC/DC adapters. FSP AC/DC adapter wide range portfolio offers high efficiency, high altitude and slim size for special applications & medical application.







The easiest and lightest way to bring the converted DC power to a system is a Wall Mount Adapter that is plugged into an AC wall socket with only one DC cable to the device.

- Wattage: 10W 65W
- Output DC Voltages: 5V / 6V / 9V / 12V / 15V / 24V
- Medical versions available
- Typical applications: typical transportable systems and systems with special demands regarding EMC (Tablets, Charger, Medical Devices, Set-top Box)

Desktop Adapters

If more power is needed and if it is useful for the environment and the application itself, a Desktop Adapter is the more sufficient way to drive a device without integrating a PSU with DC voltages.

- Wattage: 15W 250W
- Output DC Voltages: 5V / 9V / 12V / 15V / 19V / 24V / 30V / 36V / 48V
- Medical versions available
- Typical applications: systems without an integrated PSU and a demand for more than 24W (Notebooks, Medical Devices, POS/POI, Digital Signage, Thermal Printer)





To convert a Single voltage DC power into the ATX voltages for a Mainboard, a DC/DC converter might be the smallest and easiest solution. It can be mounted into small cases and approved together with the whole system. In combination with one of our AC/DC Adapters it could be an interesting solution to drive a mini-ITX board with ATX voltage input with an external PSU to reduce the size of the chassis.

- Wattage: 67W 150W
- Input DC Voltages: 12V
- Output Voltages:
- ATX (+3.3V / +5V / +12V / -12V / 5V Stdby)
- Typical applications: systems without an integrated PSU and the demand for ATX voltages (POS/POI, Digital Signage, Industrial Printer Systems)

ITX Solutions

To integrate a PSU into a small custom chassis without external converters an ITX solution can fulfill the requirements better than any other solution. It combines the AC input with the ATX output voltages in an efficient way in one solution, suitable in small chassis.

- Wattage: 55W 150W
- Output Voltages:
- ATX (+3,3V / +5V / +12V / -12V / 5V Stdby)
- Typical applications: systems with the demand for ATX voltages and less on space, where the PSU can't or shouldn't be external (Industrial Printer Systems, Small IPC's, Portables)

Other Open Frame Solutions

The more specific a system solution is designed, the more specific the PSU has to be. To cut down the costs for a fully custom design for an AC/DC converter, we offer a broad range of open frame solutions in 2" by 4" and smaller, with or without a metal case around. Many solutions are also available for the medical market.

- Wattage: 25W 1.100W
- Output Single DC Voltages: diverse from 3.3V to 48V
- Output Multi DC Voltages: diverse from 3.3V to 48V in dual or triple voltage designs
- Typical applications: custom system designs with integrated PSU to drive Boards and peripheral components, like TFT's, thermal printers or FAN's (Medical Systems, Industrial Automation, Gaming, Specific Systems with demand for DC voltages)

Open Frame Solutions

When it comes to specific custom chassis designs or voltage combinations, it can't be served from one of the former shown standards, an Open Frame PSU could be the best solution compared to a complete separate and fully custom designed PSU. The field of available solutions is various and there are many different combinations between AC or DC input and DC output possible. To give an idea about this area of PSU solutions we show in the following only the big range in general. To find the best compromise between size, power and availability, we support you in your projects as detailed as possible.









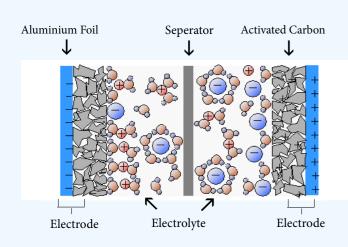


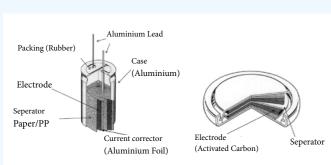
www.rutronik.com/E



Electric Double Layer Capacitors (EDLC) by SECH

Electric Double Layer Capacitors (EDLC) also known as Ultracapacitors or Supercapacitors are proven rechargeable alternative energy storage devices. The EDLC-technology is not a new one and was developed in the middle of the last century, but now the technology becomes more and more important and the number of different applications are uncountable. The Electric Double Layer Capacitors are mainly used in tandem with a battery but in some cases the real option is to replace the battery. The EDLCs are an ideal source of back-up and peak-power.





The charge in an Ultracapacitor is stored electrostatically by separating positive and negative charges. This means it is not a chemical reaction to store energy.

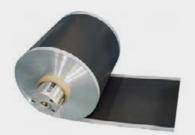
That is the reason why an Electric Double Layer Capacitor can be charged and discharged up to 1,000,000 times and much faster than a battery.

Basically, there are two different types of constructions: On the one hand the stacked and on the other hand the wound construction forms. The construction of the wound types is similar to the construction of ordinary radial electrolytic capacitors. Available with a maximum cell voltage between 2.1 and 3.3 V, capacities of up to 3400 F can be reached with these cells.

The stacked construction form called "coin types" generally offers a capacitor voltage of 5.5 V (integrating cells in row). Available with capacities of up to 1.5 F, these cells are used especially in RTC applications and as memory backup.



The key point of this technology is the special electrode with its surface coated with activated carbon. The porous structure of this coating expands the surface significantly and allows a capacity up to thousands of Farad. The Electric Double Layer Capacitor does not have a typical dielectric rather it uses the electrolyte solution as a function of the dielectric.



Benefits

- Fast charge-/discharge cycles (only a few seconds)
- High charge-/discharge currents (up to hundreds of Amps)
- Long lifetime (up to over 1 million cycles)
- Very long operating lifetime (up to 10 years and even more)
- No memory effect
- Reliable operation in harsh environments
- Wide operating temperature range (-40 °C up to +85 °C)
- Virtually maintenance free
- Higher energy vs. electrolytic capacitors
- Higher power vs. batteries
- Series- and parallel-connection possible

Comparison to Batteries

Companison to Datteries			
Туре	Batteries	EDLC	Conventional Capacitors
	COLUMN TO THE PARTY OF THE PART	Capacitors 9.4am Silvy Emploiny Shapeness	100 M 33000
Time of Charge	1 to 5 h	0.3 to 30 s	10 ⁻³ to 10 ⁻⁶ s
Time of Discharge	0.3 to 3h	0.3 to 30 s	10 ⁻³ to 10 ⁻⁶ s
Spec. Energy [Wh/kg]	20 to ~ 100	< 10	< 0.1
Lifetime [Cycles]	1,000	~ 1,000,000	~ 1,000,000
Spec. Power [W/kg]	< 1000	> 10,000	> 100,000
Efficiency	0.7 to 0.85	0.9 to 0.98	> 0.95









www.rutronik.com/E

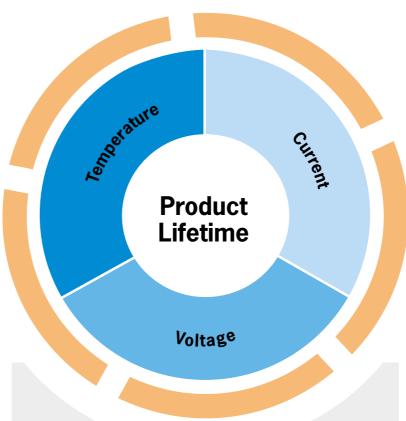


Electric Double Layer Capacitors (EDLC)

Typical Shapes Flatpacks / Pouch Cells Screw / Weldable Technology SMD Radial / Leaded Capacitance 0.0068F-600F 0.020F - 0.47F 650F - 3400F -25/-40 -60/65/85°C -25/-40 --25/-40 --20/-25 --25/-40 - 70/85°C -40 - 60/65°C -10/-25 - 60/70°C Temperature 70/75/85°C mA / A μA / mA mA / A **Operating Currents**

Portfolio

Technology	Flatpacks / Pouch Cells	Coin	Radial / Leaded	Snap-In	Screw / Weldable	Module
				WEST WE A	4 6	
AVX						
Eaton						
Korchip						
Maxwell						
SECH						
Samwha						
Vishay						
Examples	 Barcode scanner Metering Personal locators (GPS/GSM) Wireless modems 	 Backup of CMOS microcomputers Memory backup RTC Metering 	 UPS Garden light Toys Solar battery operated circuits Metering Emergency light 	UPSWind millElectric carElectric scooterPower tools	UPSWind millElectric carElectric scooterPower tools	UPSWind millElectric carElectric scooterPower tools



Lifetime Advantage over Batteries

The lifetime of an Electric Double Layer Capacitor is significantly affected by three factors: voltage, temperature and current. Due to its construction and the very low-viscosity state-of-the-art electrolytic acetonitrile, electric double layer capacitors operate at very low voltages of 2.3V- 3.3V. Since overvoltages can decompose the electrolyte and thus irreversibly damage the capacitor, the EDLC should be operated only within its specifications. In order to obtain a positive influence on the service life over the voltage, it is recommended to operate the capacitor below its rated voltage. Another critical factor related to the lifetime is the temperature the ambient temperature and the resulting self-heating. The selfheating depends largely on the strength of the currents and the cycle frequency (charging and discharging). The higher the currents are and the higher the frequency of the cycles, the higher is the self-heating, which must be added to the ambient temperature in order to estimate the actual temperature load of the supercaps. In a supercap, high temperatures lead to a decrease in capacity and an increase in the ESR over time. The higher the temperature (ambient temperature + self-heating), the faster the aging process progresses and the faster the so-called end-of-life criteria (ie 30% loss of capacity, doubling of the ESR) are achieved. It is important to know that the EDLC is functional even after reaching the endof-life criteria.

Compared to batteries, the technology of the supercaps has a higher current carrying capacity as well as a higher cycle stability, which allow a significantly longer life of up to 10 years compared to batteries.







Product Available

www.rutronik.com/El

Focus Supplier



Linecard Storages & Memories

Rutronik offers hard disks, flash memory, DRAM modules and optical drives in all technologies and sizes which are explicitly suitable for industrial applications. Hard disks still remain a popular medium for storing data securely for long periods. However, flash-based memory solutions are the first choice for applications which are exposed to stronger vibrations or shocks. A number of factors determine selection of the appropriate memory.















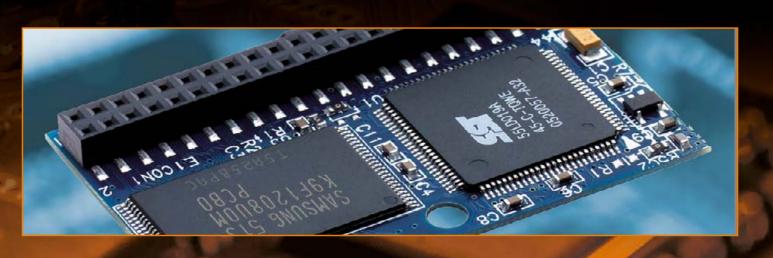
Storage Technologies

ype	Technology	Apacer	GoodRam	Intel	Kioxia	Panasonic	Swissbit	Teac	Toshiba	Transcend
Memory Modules										
and the last of th	SDRAM		✓							
Wa 0000	DDR1	✓	✓							✓
	DDR2	✓	✓							✓
	DDR3	✓	✓							✓
	DDR4	✓	✓							✓
lash Memory										
	SD/microSD	✓	✓			✓	✓			✓
	Compact-Flash	✓	✓				✓			✓
16GB	CFast	✓	✓				✓			✓
	Flash-Module (USB/PATA/SATA)	✓					✓			✓
	USB-Sticks	✓	✓				✓			✓
Remort Forder	SSD 2.5"	✓	✓	✓	✓		✓			✓
	mSATA	✓	✓				✓			✓
	M.2	✓	✓	✓	✓		✓			✓
	EDSFF			✓						
	AiC			✓	✓					
lard Disk Drives										
	HDD 2.5"								✓	
	HDD 3.5"								✓	
	Extern USB								✓	✓
Optical Drives										
(10)	CD Drives							✓		
	DVD Drives							✓		
	BluRay Drives							✓		
	Medical Recorder							✓		
Accessories										
Card Reader										✓

























Memory Technologies















Serial Serial Serial/Parallel Serial NOR Parallel NOR NAND e-MMCTM Compact Flash/Cfast Flash Module (USB/PATA/SATA) SSD (2.5"/mSATA/M.2) Add-in Card USB Sticks DDR DDR4 LPSDE SDRAM LPDDR2 LPDDR3 LPDDR4 Pseudo SRAM/IoT RAM SDRAM Module DDR Module DDR2 Module DDR3 Module DDR4 Module Low-Power Fast Synchronous NVRAM









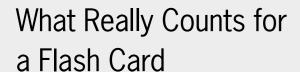




swissbit[®]







Unfortunately, it happens far too often that flash cards from one and the same manufacturer sometimes fail in an application. How is it possible, that one card works in an application and another one suddenly fails in the same application, although according to the product code, it is the same card?

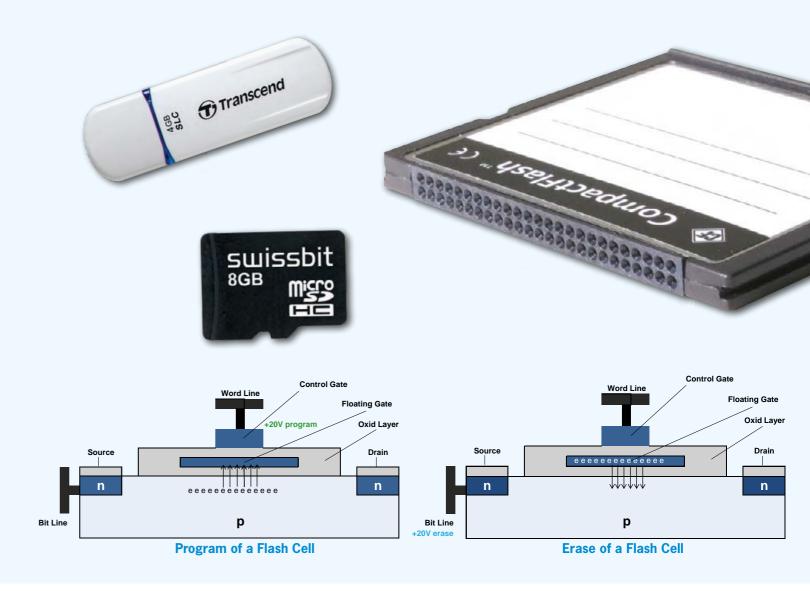
There is a simple and plausible answer to this question.

A flash card's function has four main characteristics which must be considered: The PCB, the Flash Chips, the controller and the firmware. The so-called bill of materials (BOM). When these 4 components are put together you have a finished flash card that is ready for use.

In the industry, before an application goes into production, a sample is tested to establish the functionality. If the tests are successful, the item will be approved for purchase by the development department. If a batch should suddenly have a BOM that differs from the tested sample, the card may completely fail in the application owing to incompatibility. This can be compared with a small faulty cog in a large mechanism.

In other words: production stops and significant costs result. This is not just a theoretical scenario. Almost all manufacturers frequently change their BOM to reduce costs, without publishing this or marking the items. Without further ado, new firmware is introduced for example, or a new controller, which can have catastrophic consequences in certain applications. Cards from manufacturers like these are not suited for industrial applications.





The leading manufactures Swissbit and Apacer have by contrast addressed this problem and have focussed on the industrial market.

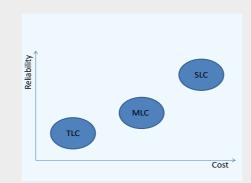
They offer special industrial compact flash cards and guarantee a fixed bill of materials, so that all of the cards supplied will be identical to the tested samples with no changes being made without a published product change notification (PCN).

To guarantee and check this continuity, Swissbit item designations, specify exactly which controller and which flash chips etc. are used. If anything in the BOM is changed, the item designation is also changed.

In addition to the fixed BOM, Swissbit and Apacer exclusively use flash chips with SLC technology as, in contrast to the cheaper MLC technology, these are suitable for industrial use due to longer life, higher speed, lower error rate and lower power consumption.

Flash Type	SLC	pSLC	MLC	TLC	pSLC	TLC	QLC
	2D	2D	2D	2D	3D	3D	3D
Bit per cell	1 Bit	1 Bit	2 Bit	3 Bit	1 Bit	3 Bit	4 Bit
ECC requirement (up to)	40bit	48bit	48bit	72bit	120bit	120 bit	160 bit
Program/Erase PEcycle	60k - 100k	20k	3k	500	20k - 50k	300 - 3k	250
Industrial Temperature Range		х	х		х	х	
Fixed BOM (Bill of Materials		х	х		х		
Cost advantage per GB		+	++		++		+++++
Longevity products		+	+		++		
Write Performance	+++++	++++	++		+++++	+++	

NAND Flash Technology (Reliability vs. Cost)



Boards & Systems | Storage | Displays | Wireless

SLC	PSLC	MLC	TLC	QLC	
			111	1111	
	1	11	111	1110	
	1	11	110	1101	
1			110	1100	
1		10	101	1011	
			101	1010	
		10	100	1001	
			100	1000	
			011	0111	
		01	011	0110	
		01	01	010	0101
0			010	0100	
U			001	0011	
	0	00	001	0010	
	U	00	000	0001	
			000	0000	









Founded in 1997 **Headquartered in Taiwan** Offices in 6 countries 580+ employees worldwide Production in own manufactory ISO 9001, ISO 14001, OHSAS 18001, IECQ CQ080000



Apacer – Industrial Memory Solutions

Market studies show that Apacer offers reliable, innovative, trendy and youthful products, fully living up to its promise. Using its witty slogan "Access the Best" to represent its effort to enhance brand value, Apacer dedicates itself in providing the best products and services. "Access" literally suggests total convenience and freedom in data reading, sharing and communication, while "Best" represents unparalleled quality. Apacer in fact promises users improved digital experiences with its line of memory modules and peripherals.

Storage Technologies - Overview



































DRAM Module

Apacer's DRAM module technology development is focused on vertically integrating know-how in the semiconductor industry, which allows it to manufacture memory modules that satisfy the requirements of both quality and performance, yet can be easily integrated into various platforms. As leading memory module maker, Apacer has long been devoted to the industrial computer field, particularly the embedded systems.

Anti-Sulfuration

environment.

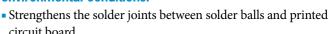
system lifespan







Underfill



- Increases the product's resistance against shock and vibration
- Reduces thermal stress damage
- Complies with MIL-STD-810G
- Increases product reliability and lifespan

Conformal Coating



Enhances reliability of products by applying coatings on the surface of printed circuit boards. The protective film can safeguard devices from dust ingression and liquid immersion.

Uses automated spraying to maintain precise

Anti-sulfuration memory modules are mainly

World's first anti-sulfuration memory modules

Ensures product reliability and durability

used in equipment exposed in highly contaminated

Solves corrosion problems effectively and increases overall

Widely recognized and awarded patents in many countries

- coating thickness
- Enhances product reliability
- Prolongs DRAM modules lifespan

Wide Temperature



Especially designed for harsh climates and special environmental conditions.

- Operating temperature range: $-40 \, ^{\circ}\text{C} \leq \text{TC} \leq 85 \, ^{\circ}\text{C}$
- All industrial-grade components
- (DRAM, resistors and capacitors) ensure stability
- and reliability
- High/Low temp. test/Temp.cycling test
- Power cycling test











Industrial SSD Solutions



Industrial Flash Disc Modules



Features

- SMART Read Refresh™ (Optional)
- Support TCG Opal 2.0/AES 256-bit encryption (Optional)
- Global Wear Leveling
- DataRAID[™] (Optional)
- DataDefender[™] (Optional)
- Flash bad block management
- S.M.A.R.T.
- Power Failure Management
- TRIM

Model Name	SV250-25	SM130-25	SV250-25
Interface	SATA 3.0 (6Gb/s)	SATA III (6 Gb/s)	SATA 3.0 (6 Gb/s)
Form Factor	2.5"	2.5"	2.5"
Capacity	30GB to 480GB	512 GB to 2 TB	30GB to 480 GB
NAND Support	3D TLC	TO 15 nm MLC	3D TLC
External DRAM	No	Yes	No
Est. R/W Speed (MB/sec)	560/520	530/510	560/520
Wide Temperature (-40 °C to 85 °C)	Yes	Yes	Yes

Double-Barreled Solution (DBS)

Apacer's latest innovation, Double-barreled Solution Cloud Edition, assists the development of industrial intelligence and enables the digital transformation of many industries. It provides an excellent solution for remote device management (RDM), so that the status of equipment and resources in an automated factory can be monitored and controlled in real-time, and turns reams of collected data into easy-to-understand dashboard readouts. Apacer's Double-barreled Solution (DBS) was named after its two separate components. The first was CoreAnalyzer2, a tool for real-time recording and accurate analysis of platform usage behavior to help customers understand which SSD and firmware was most suitable for their application. The second was SSDWidget 2.0, a smart monitoring solution that can monitor the health status of multiple SSDs in real time and effectively predict the end of a product's lifespan. The combined result of these two components working together meant that SSDs had longer lifetimes and no downtime.

DBS Cloud Edition Dashboard



SATA Disc Modu	le			
Туре	SV250-7LP2	ST170-7LP2	ST170-7LP2	SDM7-M 7P180D DP
Interface	SATA 3.1 (6Gb/s)	SATA 3.1 (6Gb/s)	SATA III (6Gb/s)	SATA III (6Gb/s)
Capacity	30GB to 120GB	30GB to 120GB	1GB to 16GB	32GB to 256 GB
NAND Support	3D TLC	3D TLC		
External DRAM	No	No		DRAM Cache for Enhanced Random Perform.
R/W	560/510	335/235	Up to 44/40 MB/s	Up to 525/355 MB/s
Wide Temp. (-40~85°C)	Yes	No		
VA Options	 Low-Density Parity-Check (LDPC) Code Global Wear Leveling Flash bad-block management Flash Translation Layer: Page Mapping 	S.M.A.R.T.Power Failure ManagementATA Secure EraseTRIM	S.M.A.R.T.	SMART UtilityCore TechnologyWide Temperature / HW write protect

M.2 Disc Module



M.2 Disc Module

Boards & Systems | Storage | Displays | Wireless

			Apokar	Apacer
Туре	UDM2A (Type C)	UDM2A (Type D LP)	UV110-UFD1	UT110-UFD2
Interface	USB 2.0	USB 2.0	USB 3.1 Gen1	USB 3.1 Gen1
Capacity	256 MB~32 GB	256 MB~32 GB	16GB to 256GB	32GB to 64GB
Connector	10-pin (2x5) female I	neader in 2.54 mm		
R/W	Up to 44/41 MB/s	Up to 44/41 MB/s	Est. 260/120 MB/s	255/115 MB/s
Form Factor			USB flash drive	USB flash drive
Wide Temp. (-40~85°C)			Yes*	No
VA Options	SMART UtilityWide Temp.	SMART UtilityWide Temp.		

PATA Disc Module

Туре	ADM5S 44P/2700-M	AFD257
Interface	ATA/IDE	PATA
Capacity	8 GB to 64 GB	8 GB to 128 GB
NAND Support		SLC
Form Factor		2.5"
R/W	Up to 100/46 MB/s	Est. R/W: Up to 100/95 MB/s
VA Options	Smart Utility / ConformalCoating	SMART UtilityWide Temp.









swissbit[®]

- Founded in 2001
- Headquartered in **Bronschhofen, Switzerland**
- 10 countries
- 200+ employees worldwide
- Production Made in Germany
- Certificates: ISO 9001, ISO 14001, ISO/TS 16949



Swissbit Market Segmetns

Industry



Netcom



IoT









240GB



Swissbit System Competency

Swissbit owns all core processes from the conception to volume production of our products. This allows us to design and produce optimal solutions for demanding applications.

Conception Market analysis

Development

Hardware Firmware

- Product definition
- Product features
- Feasibility studies
- Prototyping
- Software tools
- Test development

Design for test/production

Verification

- Product verification (DVT)
- Debugging
- Optimization
- Compliance testing
- Compatibility testing

Production and Test

swissbit[®]

- In-House
- Life time calculation production & test Joint customer

Qualification

Reliability (RDT)

qualification

- 100% final test $(-40 \text{ to } +85^{\circ}\text{C})$
- Yield management
- Subcontractor management
- Logistics

Swissbit – Reliable Storage & Embedded IoT Solutions

Data is the fuel of the future and is driving global growth and change. Swissbit takes care of data by storing and protecting data reliably. As a leader in industrial storage and embedded IoT (Internet of Things) solutions, Swissbit drives the development of demanding industrial and IoT applications to make our lives easier, safer, and more comfortable. More than 5,000 customers around the world including Fortune 500 companies and the world's leading OEMs already rely on Swissbit for their critical data storage and security requirements.

Storage Technologies - Overview



2.5" SSD



















SlimSATA SSD



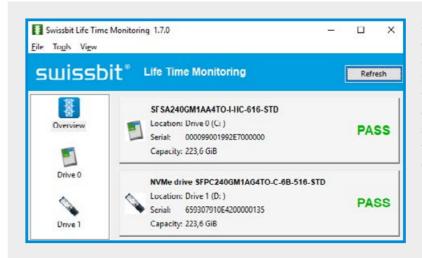
CFast Cards



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Swissbit Life Time Monitoring

(Swissbit Lifetime Monitoring) for Windows is a utility program that reads status information from Swissbit products. It uses S.M.A.R.T. (Self-Monitoring, Analysis and Reporting Technology) and USB vendor specific commands to gather life time information. Swissbit delivers a Windows/Linux tool (free of charge). A SBLTM software library/API for Windows and/or Linux is available for a small one-time fee.



Swissbit supports a realistic evaluation of the WAF and the endurance of their SSDs and storage cards with help of the Swissbit Life Time Monitoring Tool and statistical data stored in the flash by the firmware. This tool can read out the real usage data, such as the number of writes and erase cycles, the bad block statistic, and successful ECC correction, and provides all the data necessary to extrapolate the life time of the device. All Swissbit products provide a high level of detailed information, by far exceeding industry standards.











Swissbit 3D NAND Products



Besides continuation of released products in the well known SLC and MLC technology Swissbit has released a wide range of real industrial grade products based on 3D TLC NAND. The Swissbit 3D NAND products support full industrial temperature range from -40 to 85°C with a cross temperature of 125K. This allows to write and read at any temperature combination within the specified range. Something that you can't expect from consumer grade products. All 3D NAND products are designed to withstand frequent temperature changes, are equipped with a strong error correction, thermal management and data encryption options. The Swissbit 3D NAND products are designed for high endurance and reliability. For demanding applications with a high endurance requirements Swissbit offers nearly each product family also in 3D NAND pSLC technology.

The Swissbit 3D NAND products comprise following products:

	3D TLC	3D pSLC	TLC range	pSLC range	Features
PCIe M.2 2280	N-10m2	N-16m2	120-960 GB	40-320 GB	x2 PCle 3.1 / NVMe 1.2
PCle M.2 2230-22110	N-20m2	N-26m2	15-240 GB	5-80 GB	x4 PCle 3.1 / NVMe 1.3
2.5" SATA	X- 73	X- 76	30-960 GB	10-320 GB	Industrial SATA Gen3
2.5" SATA	X- 75		60-1920 GB		High end SATA Gen3
SATA M.2 2242 & 2280	X-75m2	X- 76m2	30-960 GB	10-320 GB	Industrial SATA Gen3
SATA mSATA	X-75m	X- 76m	30-960 GB	10-320 GB	Industrial SATA Gen3
SATA SlimSATA	X-75s	X-76s	30-960 GB	10-320 GB	Industrial SATA Gen3
SD Memory Card	S- 30		32-256 GB		SD for Read Mostly Apps
microSD Memory Card	S- 30u		32-256 GB		uSD for Read Mostly Apps
SD Memory Card	S- 50		32-128 GB		Industrial grade SD
microSD Memory Card	S- 50u		32-256 GB		Industrial grade uSD
embedded USB		U- 58		8- 16 GB	USB module
PCIe BGA 1620	EN- 20	EN- 26	15-240 GB	5-80 GB	x4 PCle 3.1 / NVMe 1.3

Chip Capacity	SLC	everbit™ pSLC	durabit™ MLC	3D pSLC	3D TLC	3D QLC
Cost per Bit		707	200	***	- 11	
Reliability & Endurance	1010	9345	***	****	AVA	8.0
Industrial Temperature	1010	+×+	***		4.0	- 4
Write Performance	3757	1222	***	***	440	-
ECC Requirement		7.0	1.0	****	****	****
Data Retention	***	***	+×+	***	2.44	*
Longevity	1414	44	49	**	46	

**** maximum; *** highest; ** high; ** medium; * low

Swissbit Security Products

MLC



MLC / pSLC

PS- 45 / 45u PS- 46 / 46u PS- 450 / 450u PU- 50n / 56n GENERAL INFORMATION SD 3.0 SD, ASSD V1.1 COMPLIANCE USB 3.1 **DATA TRANSFER** UHS-1 Speed class 10 USB 3.1 SuperSpeed **TEMPERATURE** - 25°C to 85°C - 25°C to 85°C COMPATIBLE TO S-46 / 46u S-450 / 450u S-45/45u U-50n / U- 56n

SLC

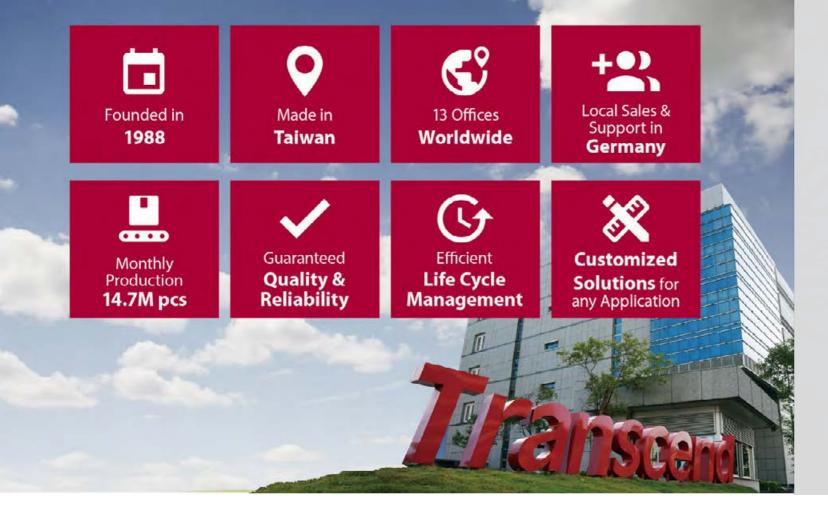
pSLC

SECURITY PRODUCT MATRIX		SE Standard Edition	PE Premium Edition	Audit Trail / Fiscal	DP Data Protection
	PS- 45 SD	8 GB - 16 GB	8 GB - 16 GB	8 GB	8 GB – 64 GB
	PS- 45u microSD	8 GB - 16 GB	8 GB – 16 GB	8 GB	8 GB – 32 GB
	PS- 46 SD	4 GB - 8 GB	4 GB - 8 GB		4 GB – 32 GB
DEVICE	PS- 46u microSD	4 GB - 8 GB	4 GB - 8 GB		4 GB – 16 GB
	PS- 450 SD	4 GB - 32 GB	4 GB - 32 GB		4 GB – 32 GB
	PS- 450u microSD	0.5 GB - 2 GB	0.5 GB - 2 GB		0.5 GB - 2 GB
	PU-50n		8 GB - 16 GB*	8 GB	8 GB - 64 GB
SECURITY		Infineon / NXP smart card chip CC EAL 5+/6+ HW and OS Java card 3.0.1/ 3.0.4 Global Platform 2.2.1 / 2.2.2 Infineon JTOP/ NXP JCOP 3 RSA up to 2048 bit optional ECC up to 512 / 521 bit AES up to 256 bit SHA2 up to 512 bit RNG AIS31, FIPS-140 Compatible Middleware: •AET SafeSign •Cryptovision SCinterface		NXP smart card chip BSI TR-03153 certified TSE SMAERS:EAL2 CSP: EAL4 384 bit encryption Validity of signature certificate: 5 or 7 years + 6 months for shelf storage Guaranteed 20 Mio signatures Signature processing time < 250 ms	Partitioning: •CD-ROM •Private •Hidden/WORM AES 256 bit flash encryption User and administrator PIN Configurable retry counter Unique ID Fast crypto wipe
DRIVERS / API		Windows Linux Android SDK available PKCS#11 Middleware		Windows Linux Android Embedded on request SDK available	Windows Linux RaspBerry Pi Arduino SDK available





FLASH TYPE



ISO Certificates

Transcend®

IATF 16949

ISO 9001

ISO 14001

IECO OC080000













■ IATF 16949: Automotive Quality Management System

ISO 9001: Quality Management System

• ISO 14001: Environment Management System

Hazardous Substances Process Management System

OHSAS 18001: Occupational Health & Safety Management System

Transcend – Good Memories Start Here

Transcend Information. Inc. was founded in 1988 by Mr. Chung-Won Shu, Peter, with its headquarters in Taipei, Taiwan. Today, Transcend has become a leading global brand of digital storage, multimedia and industrial products with 13 offices worldwide. Not only do we design, develop, and manufacture all of our own products, but we also market and sell them. At Transcend, we uphold the highest quality and believe in professional service. As a customer-focused company, Transcend has the ability to quickly respond to the market's changing needs.

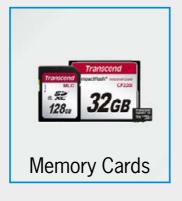
Complete Product Portfolio

Our Products Fulfill All Your Storage Needs











Advanced Services

Durability









Wear Leveling





Reliabilty

Thermal Sensor

Bad Block

Management







Conformal Coating

Intelligent Power

Shield & Power Shield

3D NAND Flash

Stability

Security



TCG Opal

Specifications

AES Encryption

Management

Underfill

SSD Scope Pro











DRAM Modules





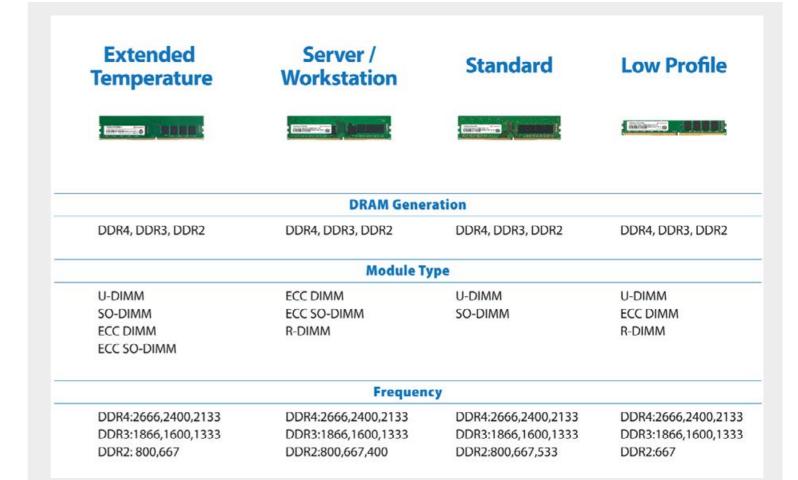
Transcend Flash Types



	3D TLC 96-layer	3D SLC Mode 96-layer	MLC	Super MLC	SLC
Endurance (P/E Cycles)	ЗК	50K - 100K	3K	30K	50K
Bit per Cell	3	1	2	1	1
Performance		•••	••	•••	•••
Cost	-				
Features	Suitable for SSDs and most industrial applications	High endurance solution that will substitute SLC in future	Majorly used in SSD and most industrial applications	More affordable than SLC, better performance than MLC	Where cost may be less important than disk lifetime

Applications











Toshiba Memory is now KIOXIA

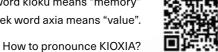
Our company name has changed. But our product range, quality, service and reliability are still the same.

KIOXIA Europe GmbH (formerly known as Toshiba Memory Europe GmbH) is the European based subsidiary of KIOXIA Corporation, a worldwide leading supplier of Flash Memory, Solid State Drives (SSDs) and Retail Products (USB, Memory Cards, SSDs).

Toshiba Memory is known as the inventor of NAND flash memory in 1987 and was the first in the world to begin mass-producing it in 1991. Under its new name, KIOXIA remains a storage leader today with its BiCS FLASH™ 3D technology, focusing on innovation, quality and reliability. This technology is an important component in almost all electronic devices where data need to be stored. KIOXIA is leading a new era by providing advanced memory solutions to enrich people's lives. By evolving "memory", KIOXIA creates uplifting experiences and changes the world.

A new start with a new unique name

The name KIOXIA is a merger of two different words: the Japanese word kioku means "memory" and the Greek word axia means "value".







KIOXIA

BG4 Series

Client SSD

The BG4 series is a line-up of compact single package NVMe™ SSDs with capacities up to 1,024 GB, and leverages a PCle® Gen3x4 interface and KIOXIA's 96-layer TLC BiCS FLASH™. With higher bandwidth and improved flash management and Host Memory Buffer (HMB) technology, BG4 SSDs deliver best-in-class read performance in single package SSDs, of up to 2,300 MB/s (sequential read) and up to 390K IOPS (random read), with active power consumption of up to

The BG4 series is available in four capacities of 128 GB, 256 GB, 512 GB and 1,024 GB in surface-mount M.2 1620 single package or removable M.2 2230 module form factor options, making them suitable for thin and light system designs for ultra-thin PCs, as well as embedded devices and server boot in data centers.

The BG4 series is with the option of a Self-Encrypting Drive (SED) model* supporting TCG Opal Version 2.01.

*Availability of the SED model line-up may vary by region. The specification of BG4 self-encrypting drive (SED) will be released Q3 calendar year of 2019.

XG6 Series

Client SSD

The XG6 series utilizes KIOXIA's latest 96-layer, 3D TLC (3-bit-percell) flash memory. With 4th generation BiCS FLASHTM and SLC cache features, XG6 SSDs reach up to sequential read/write speeds of 3180 MB/s and 2960 MB/s respectively and deliver up to 355,000 random read and 365,000 random write IOPS. In addition to high performance, XG6 carries on the low power design of the XG family, consuming 4.7 W or less in active mode and less than 3 mW in

The new XG6 series is optimized for power-sensitive mobile PCs, performance-oriented gaming PCs, as well as data center environments for server-boot, caching and logging.

Available in a compact M.2 2280 single-sided form factor, the XG6 series comes in three capacity models of 256 GB, 512 GB and 1,024 GB, each with the option of a Self-Encrypting Drive (SED) model supporting TCG Opal Version 2.01.

Product image may differ from the actual product.

Product image may differ from the actual product

The Inventor of Flash Memory

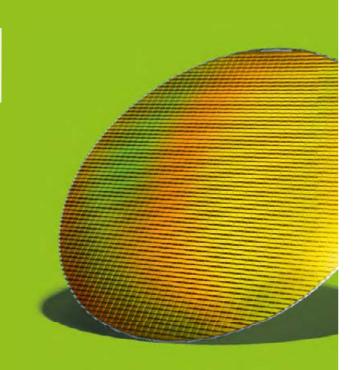
Made in Japan

WORLD'S LARGEST FABRICATION

All KIOXIA flash memory wafer manufacturing is done in Japan (Yokkaichi and Kitakami).

HIGH QUALITY & RELIABILITY

With stringent quality control, we are dedicated to providing high quality products.



100% IN-HOUSE FLASH MEMORY

KIOXIA flash memory is used in 100% of our consumer memory and storage products.

Key Features

KIOXIA 96-Layer BiCS FLASH™ PCle® Gen3 x4 NVMe™ Capacities up to 1,024 GB M.2 1620 single package and M.2 2230 single-sided form factor TCG OPAL 2.01 Optional for SED

Key Applications

Ultra-mobile PCs 2-in-1 notebook PCs IoT/embedded devices Server and storage array boot drives

Key Features

KIOXIA 96-Layer BiCS FLASH™ PCle® Gen3 x4, NVMe™ Capacities up to 1,024 GB M.2 2280 Single-sided TCG OPAL 2.01 Optional for SED*

Key Applications

Thin performance notebook PCs High-performance desktop PCs Gaming PCs Server-boot, caching & logging use in data centers

* Availability of the SED model line-up may vary by region.











Client SSDs

Leveraging state-of-the-art BiCS FLASH™ 3D flash memory with in-house designed controllers and firmware, KIOXIA client SSDs come in a variety of form factors, including a compact and lightweight "single-package SSD." They also offer a variety of capacities, performance and security options, and are well-suited for mobile computing, desktop PCs and workstations.











Product image may differ from the actual product

XG6 Series

Utilizing 96-layer BiCS FLASH" 3D flash memory, the XG6 Series is available in an M.2 2280, single-sided form factor with a PCIe® Gen3 x4 interface, supporting the NVMe® command set. This provides a powerful combination power efficiency and high performance, consuming 4.7 W or less with over 3,000 MB/s sequential read performance, respectively. The XG6 Series offers a Selfencrypting Drive (SED) option that supports TCG Opal version 2.01, under a different model number.

Madal Number	Security		Form Factor	*1 User Capacity – (GB)	Performan	ice (up to) *2	Typical Power	Operating	Dimensions	Typical	Power Supply	
Model Number	Feature	Interface			Sequential Read (MB/s)	Sequential Write (MB/s)	Consumption (W)	Temperature (°C)	H/W/L (mm)	Weight (g)	Voltage (V)	
KXG60ZNV256G				256	3,050	1,550	4.0			7.0		
KXG60ZNV512G	-	PCIe® Gen3 x4	M.2 2280	512	3,100	2,800	4.1	0 to 85	5 2.23 / 22.15 / 80.15	80 15	7.0	3.3
KXG60ZNV1T02			1,024	3,180	2,960	4.7			7.3			

XG6-P Series

Utilizing 96-layer BiCS FLASH" 3D flash memory, the XG6-P Series is available in capacities up to 2,048 GB and has higher sequential write bandwidth than the previous generation. This series is designed for high-end workstations, gaming systems and for cost-optimized composable data center infrastructures. The XG6-P Series offers a Self-encrypting Drive (SED) option that supports TCG Opal version 2.01, under a different model number.

		Security	Interface	Form Factor	*1 User Capacity	Performan	ce (up to) *2	Typical Power	Operating	Dimensions	Typical	
		Feature			(GB)	Sequential Read (MB/s)	Sequential Write (MB/s)	Consumption (W)	Temperature (°C)	H/W/L (mm)	Weight (g)	Voltage (V)
	KXG60PNV2T04	-	PCIe® Gen3 x4	M.2 2280	2,048	3,180	2,920	4.7	0 to 85	2.23 / 22.15 / 80.15	7.3	3.3

BG4 Series

In a compact, single-package form factor and based on 96-layer BiCS FLASH™ 3D flash memory, the BG4 Series is designed for thin and light performance-oriented use cases, such as ultra-mobile PCs. IoT devices and data center server boot. Available in capacities up to 1 TB, this series features Host Memory Buffer (HMB), PCIe® Gen3 x4 interface and supports the NVMe™ command set. The BG4 Series offers a Self-encryoting Drive (SED) option that supports TCG Opal version 2.01, under a different model number.

	Security			*1 User Capacity	Performan	nce (up to) *2 Typical Powe		Operating	Dimensions	Typical	Power Supply
Model Number	Feature	Interface	Form Factor	(GB)	Sequential Read (MB/s)	Sequential Write (MB/s)	Consumption (W)	Temperature (°C)	H/W/L (mm)	Weight (g)	Voltage (V)
KBG40ZNS128G				128	2,000	800	3.4				
KBG40ZNS256G			M.2 2230	256	2 200	1 400	3.6		2.23 / 22.15 / 30.15	2.5	3.3
KBG40ZNS512G			IVI.2 2230	512	2,200	1,400	3.5				3.3
KBG40ZNS1T02	_	PCIe®		1,024	1,024 2,300		3.7	0 to 85	2.38 / 22.15 / 30.15	2.6	
KBG40ZPZ128G	_	Gen3 x4		128	2,000	800	3.0	(Tsmart)			
KBG40ZPZ256G			M.2 1620	256	2,200	1,400	3.2		1.30 / 16.15 / 20.15	0.85	3.3 / 1.8 /
KBG40ZPZ512G			IVI.2 1620	512	2,200	1,400	3.1				1.2
KBG40ZPZ1T02				1,024	2,300	1,800	3.4		1.50 / 16.15 / 20.15	1.00	

*Tsmart: Composite Temperature in SMART/Health Information

- *1:Definition of capacity: KIOXIA defines a megabyte (MB) as 1,000,000 bytes, a gigabyte (GB) as $1,000,000,000\,\text{bytes} \text{ and a terabyte} (TB) \text{ as } 1,000,000,000,000\,\text{bytes}. A computer operating system, however, reports storage capacity using powers of 2 for the definition of 1 GB = <math>2^30 = 1,073,741,824$ bytes and therefore shows less storage capacity. Available storage capacity (including examples of various media files) will vary based on file size, formatting, settings, software and operating system, such as Microsoft Operating System and /or pre-installed software applications, or media content. Actual formatted
- *2: Read and write speeds may vary depending on the host device, read and write conditions, and file size.
- Optional security feature compliant drives are not available in all countries due to export control and local regulations.

All information provided in this catalog is subject to change without any prior notice. For the latest and detail specification, please send an inquiry through the "Contact us" form in each region's website https://business.kioxia.com/

- PCIe® and PCI Express® are registered trademarks of PCI-SIG.
- NVMe[™] and NVM Express[™] are trademarks of NVM Express, Inc.
- their respective companies.

Data Center SSDs

Leveraging state-of-the-art BiCS FLASH™ 3D flash memory with in-house designed controllers and firmware, KIOXIA data center SSDs are designed for cloud-based applications running on scale-out cloud and traditional server deployments. These data center SSDs are optimized for a balance of performance, low latency and data protection, and provide power loss protection (PLP)*1 to safeguard data in case of unexpected power loss.







HK6 Series SATA SSD



Product image may differ from the actual product

XD5 Series

Based on 64-layer BiCS FLASH™ 3D flash memory, the XD5 Series of PCIe® Gen3 x4 / NVMe™ SSDs is available in an M.2 Type 22110 or a 2.5 inch (7mm Z-height) form factor with capacities up to 3.84 TB and <7 W of active power consumption

	*3		Form Factor	User Capacity (GB)		Performa	nce (up to)		Typical		
Model Number	DWPD	Interface			Sequential (128 KiB) (MB/s)		Random (4 KiB) (KIOPS)		Power Consumption	Operating Temperature (°C)	Dimensions H / W / L (mm)
				(==,	Read	Write	Read	Write	(W)	(- ,	(,
KXD5YLN13T84	< 1	PCIe® Gen3 x4	M.2 22110	3,840	0.700	815	240	04	- 7 \//	0 +- 70	3.88 /
KXD51LN11T92	\ \ 1	Pole® Gens x4	IVI.2 22110	1,920	2,700	895	250	21	< 7 W	0 to 70	22.15 / 110.15
KXD51RUE3T84			2.5 inch	3,840		815	240				7.2 /
KXD51RUE1T92	1	PCIe® Gen3 x4	(7 mm	1,920	2,700	895	050	21	< 7 W	0 to 70	70.1 /
KXD51RUE960G			Z-height)	960		095	250				100.75

*KXD5YLN13T84 (3,840GB) is Sanitize Instant Erase (SIE) model. Regarding SIE feature, please refer to *2 note. *Regarding XD5 series performance, please refer to *9 notes

HK6-R Series / HK6-V Series

The HK6-R Series of 6 Gbit/s SATA SSDs is built with 64-layer BiCS FLASH** 3D flash memory, and comes in a 2.5 inch (7 mm Z-height) form factor and capacities up to 7.68 TB. The HK6-R Series delivers a balance of reliability, performance and low power, and is designed for read-intensive workloads running on servers. The HK6-V Series of 6 Gbit/s SATA SSDs is built with 64-layer BiCS FLASH** 3D flash memory, and comes in a 2.5 inch (7 mm Z-height) form factor and capacities up to 3.84 TB. The HK6-V Series delivers a balance of reliability, performance and low power, and is

	*3					Performar	nce (up to)		*8 Typical		
Model Number	DWPD	Interface	Form Factor	User Capacity (GB)		al (128 KiB) *5*6 B/s)	Random (4 KiB) *5 *6 *7 (KIOPS)		Power Consumption	Operating Temperature (°C)	Dimensions H / W / L (mm)
				(45)	Read	Write	Read	Write	(VV)	(5)	()
KHK61RSE7T68				7,680			83	23			
KHK61RSE3T84			2.5 inch	3,840		530	84	24	5.5		7.2 /
KHK61RSE1T92	1	SATA 6 Gbit/s	(7 mm	1,920	550	330	04	22		0 to 70	70.1 /
KHK61RSE960G			Z-height)	960			85	18	5.0		100.4
KHK61RSE480G				480		450	82	20	4.0		
KHK61VSE3T84				3,840			83	54	5.5		
KHK61VSE1T92	3	SATA	2.5 inch (7 mm	1,920	550	530	94	55	5.5	0 to 70	7.2 / 70.1 /
KHK61VSE960G	3	6 Gbit/s	Z-height)	960	550		84	54	5.0	0 10 70	100.4
KHK61VSE480G				480		450	82	43	4.0		

*There is no optional lineup which has security features in the HK6-V and HK6-R series

*1 : PLP (Power Loss Protection): PLP supports the recording of data in buffer memory into flash memory, utilizing back up power of a capacitor in case of unexpected power loss

- PM5 and 2.5 inch of CM5 Series offer a range of security options; Sanitize Instant Erase (SIE), Self-Encrypting Drive (SED), and Self-Encrypting Drive (SED) with FIPS 140-2 validation or compliance. The Add-in card version of the CM5 has SIE and SED options.

Drive models with different security options have different part numbers

-The Sanitize Instant Erase (SIE) option supports Crypto Erase, which is a standardized feature defined by the technical committees (T10) of INCITS (the Inter National Committee for Information Technology Standards) or by NVM Express Inc..

- SED (Self-Encrypting Drive) SSDs support TCG Enterprise SSC or TCG Opal SSC (Unsupported features are included in CM5 / SED optional model).
- FIPS drives are designed to comply with FIPS 140-2 Level 2, which defines "Security Requirements for Cryptographic Modules" by NIST (the National Institute of Standards and Technology). PM5 Series is validated, CM5 series is planning to make FIPS 140-2 validated drives available.

For more details and the latest validation status of CM5 Series, please send an inquiry through the "Contact us" form in each region's website, https://business.kioxia.com Optional security feature compliant drives are not available in all countries due to export control and local regulations.

- *3: DWPD: Drive Write Per Day. One full drive write per day means the drive can be written and re-written to full capacity once a day every day for five years, the stated product warranty period. Actual results may vary due to system configuration, usage and other factors.
- *4: Definition of capacity: 1 terabyte (1 TB) = 1,000 gigabytes (GB), 1 GB = 1,000,000,000 (10^9) bytes

*5 : A kibibyte (KiB) means 2^10, or 1,024 bytes.
*6 : The performance specifications of the PM5 Series is based on testing in dual-port mode, running at 14 W of power. The performance of the CM5 Series is based on single-port mode (1x4).

- *9: The PM5 Series can operate in a range of power modes: 9 W, 12 W, 14 W, 18 W (for MultiLink). The CM5 Series can operate in a range of power modes: 9 W, 11 W, 14 W, 16 W, 18 W.
- *7: Read and Write speeds may vary depending on the host device, read and write conditions, and file size
 *8: IOPS: Input Output Per Second (or the number of I/O operations per second)

Customers must refer to and comply with the latest versions of all relevant KIOXIA information, including without limitation, this document, the specifications, the data sheets and application notes for Product and the precautions and conditions set forth in the KIOXIA Reliability Handbook and the instructions for the application with which the Product will be used with or for.

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- PCIe is registered trademark of PCI-SIG. NVMe is trademark of NVM Express, Inc.
- MultiLink SAS is a trademark of the SCSI Trade Association.
- All other company names, product names and service names mentioned herein may be trademarks of their respective companies











Enterprise SSDs

Leveraging state-of-the-art BiCS FLASH™ 3D flash memory with in-house designed controllers and firmware, KIOXIA enterprise SSDs optimize high performance, endurance and reliability to run mission critical applications in enterprise data center environments. To meet the demands of highly transactional and high-bandwidth workloads, these SSDs feature high levels of performance and data protection with power-loss-protection (PLP)*1. KIOXIA enterprise SSDs offer a range of security options*2 designed for business critical data storage.







PM5 Series

Based on 64-layer BiCS FLASH™3D flash memory, the PM5 Series of dual-port 12 Gb/s SAS SSDs is available in a 2.5 inch (15 mm Z-height) form factor with capacities up to 15.3 TB. These SSDs feature Power Loss Protection (PLP) and offer a range of security/encryption options.*2.

	*3			*4		Performanc	e (up to)		*9 Typical		
Model Number	DWPD	Interface	Form Factor	User Capacity (GB)	apacity Sequential (128 KIB) "5 "6 "/		Random (4 KiB)*5 *6 *7 *8 (KIOPS)		Power Consumption	Operating Temperature (°C)	Dimensions H / W / L (mm)
				(3.2)	Read	Write	Read	Write	(W)	(- ,	(,
KPM51MUG3T20				3,200			385				
KPM51MUG1T60	40	SAS-3.0, single/dual port and	0.5.	1,600	0.100	2,100	370	230	0/10/14	2. 22	15.0 /
KPM51MUG800G	10	MultiLink SAS™ support	2.5 inch	800	2,100		340		9/12/14	0 to 60	70.1 / 100.45
KPM51MUG400G		опри		400		1,260	270	150			
KPM51VUG6T40				6,400			385				
KPM51VUG3T20		SAS-3.0,	2.5 inch	3,200	0.400	2,100	370	120			450/
KPM51VUG1T60	3	single/dual port and MultiLink SAS™		1,600	2,100		340		9 / 12 / 14	0 to 60	15.0 / 70.1 /
KPM51VUG800G		support		800		1,260	270	80			100.45
KPM51VUG400G				400	1,470	680	180	70			
KPM51RUG15T3				15,360			300	35			
KPM51RUG7T68				7,680			385				
KPM51RUG3T84		SAS-3.0, single/dual port and		3,840	2,100	2,100	370	55	. , ,		15.0 /
KPM51RUG1T92	1	MultiLink SAS™	2.5 inch	1,920			340		9/12/14	0 to 60	70.1 / 100.45
KPM51RUG960G		support		960		1,260	270				
KPM51RUG480G				480	1,470	680	180	45			

CM5 Series

Based on 64-layer BiCS FLASH™ 3D flash memory, the CM5 Series of dual-port PCle® / NVMe™ SSDs is available in 2.5 inch form factor. These SSDs feature Power Loss Protection (PLP) and offer a range of security/encryption options¹². The CM5 series is also available in 3 DWPD.

	*3	Interface	Form Factor	*4		Performan		*9 Typical		Dimensions	
Model Number	DWPD			User Capacity (GB)			Random (4 KiB) *5 *6 *7 *8 (KIOPS)		Power Consumption	Operating Temperature (°C)	Dimensions H / W / L (mm)
	M51RUG15T3		Read		Write	Read	Write	(W)	()		
KCM51RUG15T3				15,360			590	35	18		
KCM51RUG7T68		DOL-® C04		7,680	3,350	3,040	770	80	16		150/
KCM51RUG3T84	1	PCIe® Gen3 x4, single/dual port	2.5 inch	h 3,840		750	70	15	0 to 60	15.0 / 70.1 /	
KCM51RUG1T92		support		1,920	0.050	2,460	650	65	13		100.45
KCM51RUG960G				960	3,250	1,250	370	50	11		

- *1: PLP (Power Loss Protection): PLP supports the recording of data in buffer memory into flash memory, utilizing back up power of a capacitor in case of unexpected power loss.
- PM5 and 2.5 inch of CM5 Series offer a range of security options; Sanitize Instant Erase (SIE), Self-Encrypting Drive (SED), and Self-Encrypting Drive (SED) with FIPS 140-2 validation or compliance. The Add-in card version of the CM5 has SIE and SED options.
- Drive models with different security options have different part numbers
- The Sanitize Instant Erase (SIE) option supports Crypto Erase, which is a standardized feature defined by the technical committees (T10) of INCITS (the Inter National Committee for Information Technology Standards) or by NVM Express Inc..
- SED (Self-Encrypting Drive) SSDs support TCG Enterprise SSC or TCG Opal SSC (Unsupported features are included in CM5 / SED optional model).
- FIPS drives are designed to comply with FIPS 140-2 Level 2, which defines "Security Requirements for Cryptographic Modules" by NIST (the National Institute of Standards and Technology). PM5 Series is validated
- CM5 series is planning to make FIPS 140-2 validated drives available. - For more details and the latest validation status of CM5 Series, please send an inquiry through the "Contact us" form in each region's website, https://business.kioxia.com,
- Optional security feature compliant drives are not available in all countries due to export control and local regulations. *3: DWPD: Drive Write Per Day. One full drive write per day means the drive can be written and re-written to full capacity once a day every day for five years, the stated product warranty period. Actual results may vary due to
- *4: Definition of capacity: 1 terabyte (1 TB) = 1,000 gigabytes (GB), 1 GB = 1,000,000,000 (10^9) bytes
- *5 : A kibibyte (KiB) means 2^10, or 1,024 byte
- 6: The performance specifications of the PMS Series is based on testing in dual-port mode, running at 14 W of power. The performance of the CM5 Series is based on single-port mode (1x4).
- *7: Read and Write speeds may vary depending on the host device, read and write conditions, and file size.
 *8: IOPS: Input Output Per Second (or the number of I/O operations per second)
- *9: The PM5 Series can operate in a range of power modes: 9 W, 12 W, 14 W, 18 W (for MultiLink). The CM5 Series can operate in a range of power modes: 9 W, 11 W, 14 W, 16 W, 18 W.
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- PCIe is registered trademark of PCI-SIG.
- NVMe is trademark of NVM Express, Inc.

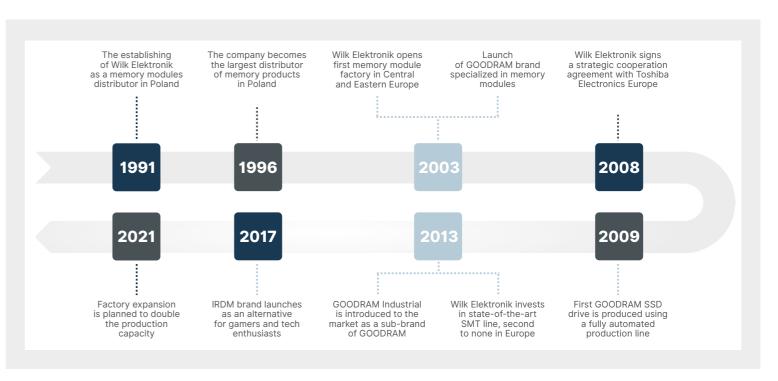
- Founded in 1991
- 200 employees
- Certificate: ISO 9001

- Headquartered in Poland
- Own production line

Wilk Elektronik – About Company



GOODRAM Industrial is a brand of Wilk Elektronik SA - Polish memory manufacturer and distributor with nearly 30 years of experience in the memory business. Known for its strict quality policy, flexibility and post-sales support, GOODRAM is the only European memory manufacturer with its own lab, R&D department, state-of-the-art production site, test field and support team. All in-house, under one roof. GOODRAM stands for quality, reliability and support - we believe the industry needs customized solutions for very specific needs. Designing our own testing procedures ensures the modules we produce are tailored to match our customers needs perfectly. Add low MOQ's, fixed BOM and long-term post-sales support to the mix to achieve the highest possible quality of customer service. It all boils down to guaranteeing our partners the highest reliability possible throughout the module's lifetime.





Boards & Systems | Storage | Displays | Wireless

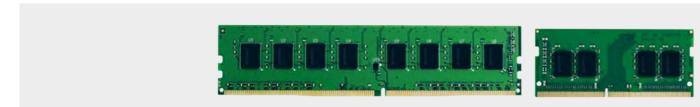






DRAM

DRAM (Dynamic Random Access Memory) modules are easy to install components, available for wide range of industrial applications including IPC, Rugged PC, Barebone systems etc. GOODRAM DRAM memory modules are available in all the most popular types (DDR1-DDR4) and form factors (DIMM, VLP DIMM, SODIMM), as well supporting ECC Register or ECC, standard (0/+70°C) or extended (-40/+85°C) temperature range. During the production process all DRAM memory modules are tested in motherboards using our state-of-art testing software, ensuring 100% of modules leaving our production line are working.



DRAM Memory Modules

Туре	DDR1*	DDR2	DDR3	DDR4							
Form Factors	184-pin DIMM 200-pin SO-DIMM	240-pin DIMM 200-pin SO-DIMM	240-pin DIMM 204-pin SO-DIMM	288-pin DIMM 260-pin SO-DIMM							
Capacity	512MB to 1GB	1GB to 2GB	1GB to 8GB	4GB to 16GB							
Peak Transfer Rate (MB/s)	Up to 3,200	Up to 6,400	Up to 14,900	Up to 25,600 (3,200MHz)							
Voltage (V)	2.5	1.8	1.5/1.35	1.2							
ECC option		Ye	es								
Operating Temperature (°C)	Standard grade: 0 to 70 Industrial grade: -40 to 85	Stano	dard grade: 0 ÷ 85 Industrial grade: -40	to 85							
Storage Temperature (°C)		-40 t	to 85								
Key Features & Options		Single/Double Rank configuration DDR3/4 Very Low Profile size 100% functional tests High/Low temempartaure testing Build from major IC grades Long lifetime project support FIX BOM option PCN and EOL notification									

*DDR1 modules only for special request

NAND Base Solutions

SSD drives (Solid-state drives) for industrial usage are available in all mainstream form factors (2.5", mSATA, M.2 SATA). FLASH product group include SD/microSD, CompactFlash*, CFast and eMMC cards. MicroSD cards are currently the smallest standard memory form factor with implemented controller. It is widely used in industrial solutions because of small dimensions and relatively low cost. The smallest capacities are usually enough for industrial SDK and OS like Linux. The Industrial FLASH cards, beside the form factor, vary from consumer cards. Most important differences is NAND grade, which is the same as used in SSD's - so called Major Grade and they have fixed list of components.

Industrial cards based on wide range of NAND technologies:

- 3D TLC: 3,000 P/E cycles MLC: 3,000 P/E cycles
- pSLC: 20,000 P/E cycles
 SLC: 60,000 P/E cycles

The industrial cards controller is more complex, with available options helping to increase the endurance and reliability - software power loss protection and general FLASH management.

Features

- Static and Dynamic Wear Levelling
- Bad Block Management
- TRIM
- S.M.A.R.T.
- NCQ
- Over-provisioning
- Low Power Management





Our products support standard (0/+70°C) and extended (-40/+85°C) temperature range. Depending on customer's requirements we can offer 3D TLC, MLC, pSLC, SLC type flash solutions, which provide a range of Program/Erase cycles between 3,000 and 60,000.

GOOD





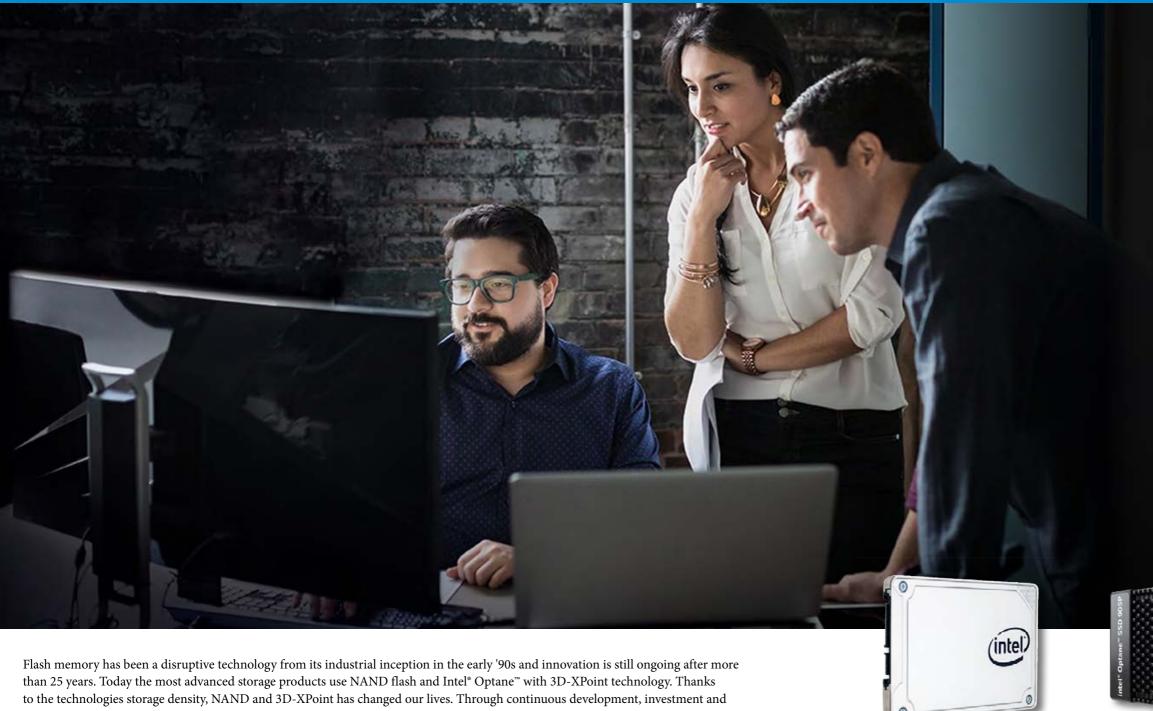






Intel® Solid-State Drive Product Families

Solid-State Drives - Client





Key Advantages

- Boost your PC performance by replacing your HDD or SATA with an Intel® PCIe SSD
- Reliable Quality Every Intel* SSD is subject to rigorous testing standards above and beyond the standard quality
- Easy Upgrade or Install With Intel® Data Migration Software, you can conveniently copy data form your old drive to a new SSD
- Industry leading innovation the 665p features 96-Layer 3D NAND technology
- Intel® quality and reliability backed by 5 years warranty

Target Applications

- High-end computing
- Performance gaming
- Workstation
- Digital content creation
- Engineering: FEA, fluid dynamics, CAD
- Mobile computing
- Digital Signage
- POS, Kiosk, Vending machines





riash memory na	teen a disruptive technology from its industrial inception in the early 90s and innovation is still ongoing after more
than 25 years. Too	the most advanced storage products use NAND flash and Intel® Optane™ with 3D-XPoint technology. Thanks
to the technologie	storage density, NAND and 3D-XPoint has changed our lives. Through continuous development, investment and
improvement by	el®, 3D NAND and Intel® Optane™ deliver outstanding value and capabilities to consumers and businesses alike.

Series	660p	665p	905p	900p	800p	Intel Optane Memory M10	Intel Optane Memory H10 with Solid State Storage
Interface	PCle 3.0x4	PCle 3.0 x4	PCle 3.0 x4	PCle 3.0 x4	PCle 3.0 x2	PCle 3.0 x2	PCle 3.0 x4
Technology	3D NAND QLC 64-Layer	3D NAND QLC 96-Layer	3D X-Point	3D X-Point	3D X-Point	3D X-Point	3D X-Point
Form Factor	M.2 x 80mm	M.2 x 80mm	U.2 x 15mm AIC M.2 x 110mm	U.2 x 15mm AIC	M.2 x 80mm	M.2 x 42mm M.2 x 80mm	M.2 x 80mm
Capacity	512GB 1TB 2TB	1TB 2TB"	380GB 480GB 960GB 1.5TB	280GB 480GB	58GB 118GB	16GB 32GB 64GB	16GB + 256GB 32GB + 512GB 32GB + 1024GB

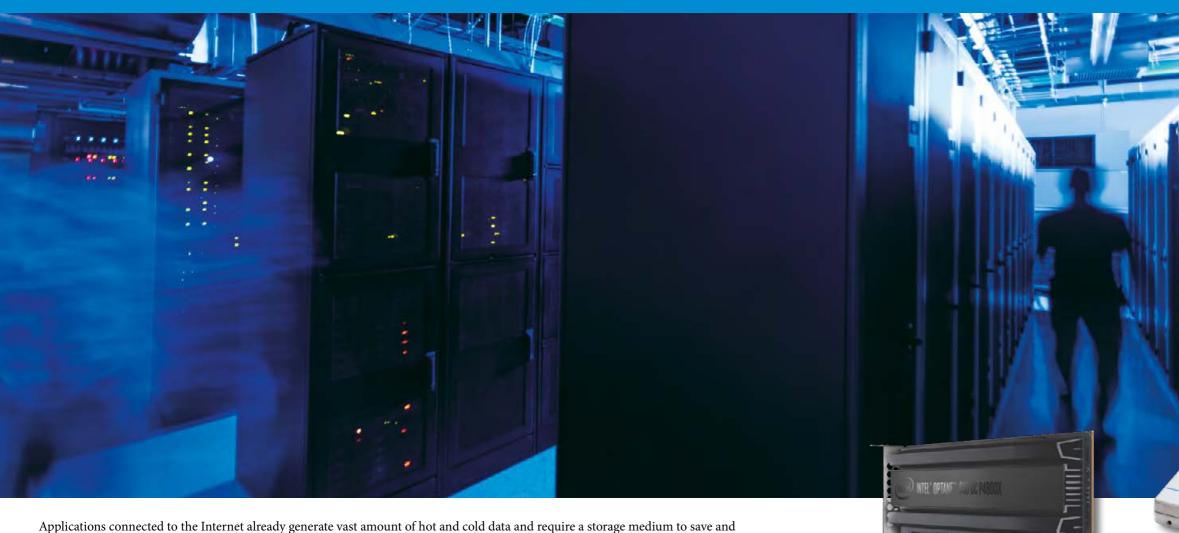
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2,5"

U.2

Intel® Solid-State Drive Product Families

Solid-State Drives - Data Center





Key Advantages

- High capacity per drive, server and rack
- Improved manageability and serviceability
- Efficient thermal design
- Reduced maintenance cost and total cost of ownership
- High throughput (IOPS/s)
- Ultra-low latency
- Excellent quality of service
- Ultra-high endurance

Target Applications

- Cloud storage
- Scale out storage
- Hard drive replacement
- Virtualization
- In-memory database





access the data. Intel® provides future proof solutions for enterprise infrastructure with extraordinary performance, reliability and endurance. Intel® SSDs enable you to keep up with the ever-increasing demands of the data center with products that provide drive reliability, uncompromised data integrity and consistent performance in critical working environments.

Series	DC P4800X	DC P4800X with IMDT	DC P4801X	DC P4801X with IMDT	DC P4618	DC P4610	DC P4511	DC P4510	DC P4420	DC P4326	DC P4320	DC \$4610	DC \$4510	DC D4800X
Interface	PCle 3.0 x4	PCIe 3.0 x4	PCIe 3.0 x4	PCIe 3.0 x4	PCle 3.1 x8	PCIe 3.1 x4	PCle 3.1 x4	PCIe 3.1 x4	PCle 3.1 x4	PCle 3.1 x4	PCle 3.1 x4	SATA 3.0 6Gb/s	SATA 3.0 6Gb/s	PCle 3.0 x2 x2
Technology	3D-Xpoint	3D-Xpoint	3D-Xpoint	3D-Xpoint	3D NAND TLC 64-Layers	3D NAND TLC 64-Layers	3D NAND TLC 64-Layers	3D NAND TLC 64-Layers	3D NAND QLC 64-Layer	3D NAND QLC 64-Layer	3D NAND QLC 64-Layer	3D NAND TLC 64-Layers	3D NAND TLC 64-Layers	3D-Xpoint
Form Factor	AIC U.2 x 15mm	AIC U.2 x 15mm	M.2 110mm U.2 x 15mm	M.2 110mm U.2 x 15mm	AIC	U.2 x 15mm	M.2 110 mm E1.S 5.9mm	U.2 x 15mm E1.L 9.5mm	U.2 x 15mm	U.2 x 15mm E1.L 18mm E1.L 9.5mm	U.2 x 15mm	2.5" x 7mm	2.5° x 7mm M.2 x 80mm	U.2 x 15mm
Capacity	375GB 750GB 1.5TB	375GB 750GB 1.5TB	100GB 200GB 375GB	100GB 200GB 375GB	6.4TB	1.6TB 3.2TB 6.4TB 7.68TB	1TB 2TB 4TB	1TB 2TB 4TB 8TB 15.36TB	7.68TB	15.36TB	7.68TB	240GB 480GB 960GB 1.92TB 3.84TB 7.68TB	240GB 480GB 960GB 1.92 3.84TB 7.68TB	375GB 750GB 1.5TB







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HD Medical Video Recorder

Based on many years of experience and product knowledge of medical imaging and recording, TEAC introduces the UR-4MD and UR-50BD, the solution for undiluted high-definition medical recording.

Excellent quality recording provided by TEAC UR-4MD and UR-50BD

maximizes the efficiency of studies.



UR-4MD

- Intuitive & Easy To Use
- Auto-sensing detects I/O & Video Resolution "automatically"
- Wide range of recording resolutions
- 640x480~1920x1080 (30Hz/29.97Hz): Undiluted recoding resolution
- 1920x1200 (Resize to 1728x1080): Supported Input resolution
- Multiple HD & SD inputs/outputs (SDI, DVI-D, S-Video and Composite)
- Simultaneous recording to multiple media (up to 2 External USB drives & 1 Internal HD)
- Networking (FTP & CIFS) RJ45 10/100/1000 Ethernet
- Remote control, Foot-switch, Card/Barcode reader and Keyboard (Optional)
- Compliance with Medical Standards



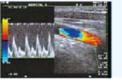


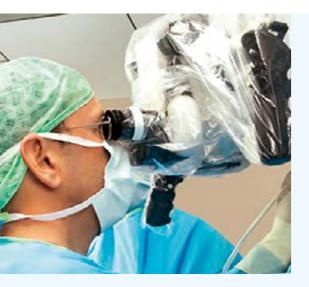


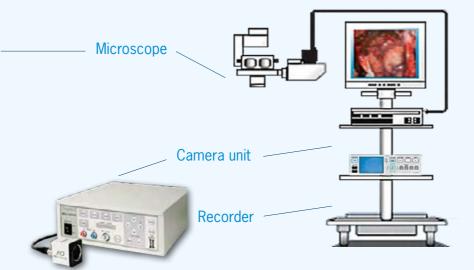
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Optical Drives -Ideal for Industrial Applications

Advantages at a glance

- Space-saving "SlimLine" housing
- Attractive design
- Innovative technology
- Has been on the market as long as the PC
- Very high quality standard
- Long life cycle
- High compatibility
- Modified to industrial standards
- Custom solutions possible



DV-W5600 -**Industrial Writer**

TEAC's new professional DV-W5600 is the world's most efficient and accurate CD/DVD recorder and verifier for qualified applications. It offers hundred per cent quality control for all discs. Originally designed for PC use, DV-W5600 has some special functions added to fulfil requirements in industrial use.

Equipped with TEAC's typical very long product lifecycle a stable and reliable platform is assured.

Features

- SATA Interface
- High accuracy of try open position
- Reduces the mis-loading of the disc by Auto-Loader
- Improving the throughput by immediate transition to verify mode
- Very quick verify mode
- Fast tray operation
- Improvement of reliability and maintenance system
- Support new discs by adjusting new write strategies
- Error report by blinking LED
- Accumulative turn-on time on Laser Diode
- Measure PI/PO error
- Total Power-on-Hour, CD/DVD write/read accumulate time

DV-W28SS-B93 -Slim Slot Loading DVD / CD Recorder

TEAC's slimline 8x DVD-Recorder DV-W28SS-W offers the most comfortable slot-in mechanism for your convenience. DV-W28SS-W combines fast DVD-recording, smooth DVD video playback with impressive CD-ROM performance.

Whether you are watching high definition movies, listening music or playing DVD title, the TEAC 8x slimline DVD-

Recorder DV-W28SS-W with its robust and extremely reliable slot-in mechanism is the perfect multimedia companion for your note

ebook or PC.	
Diameter	12cm
face	SerialATA Revision 3.1
ess Time	140ms typ CD-ROM 150ms typ DVD-ROM
Buffer	1MB
ling Mechanism	Slot Loading Type
ient Temp.	Operating: 5 to 45 °C
tive Humidity	Operating: 10 to 80% (non-condensing) Non Operating: 10 to 95% (non-condensing) Transportation: 10 to 95% (non-condensing)

Standby/Sleep: 50mA (Avarage current max.) During starting / Seek: 1500mA

Approved by UL, CUL, TÜV, CE and BSMI

60.000POH (10% duty)









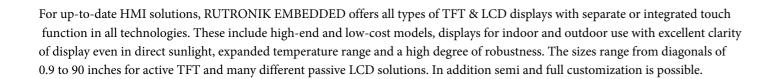
Current

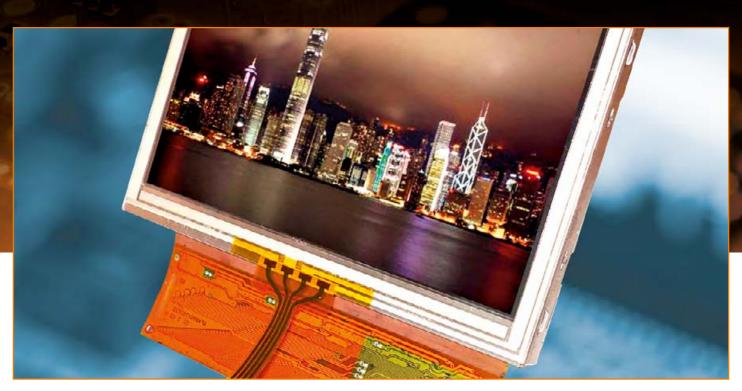
Safety Standards



RUTRONIK EMBEDDED

Linecard Displays





























Displays & Accessories TFT-Displays TFT-Displays Smart Panels incl. Controller SKD-Kits incl. Controller, Cable, Power Supply **Professional Monitors** Passive LC-Displays Character and Graphic Modules **Customized Modules** Turn Key Solutions OLED's Bi-Stable Displays Accessories Cables and Connectors



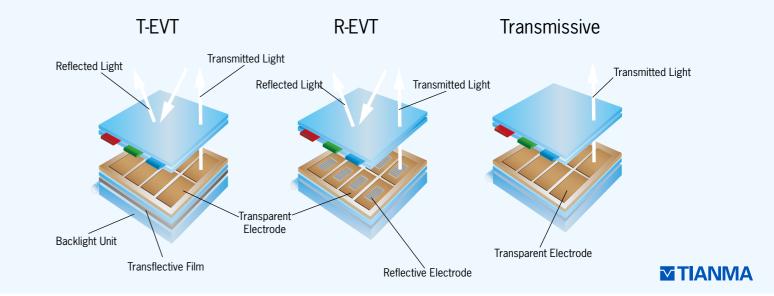


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▼TIANMA









TFT Technology by Tianma

Standard Industrial Line

- Long-term availability
- Long time phase-out-strategy for industrial applications
- Low power consumption
- 3.3 V operation
- True Colour with brilliant colours
- Dual clock interface for EMI reduction
- Flicker-free
- Fast response times
- Wider viewing angle with Super-Fine technology (up/down ±85°)

TFT Standard Industrial Line

Displa	y Size		Interfac	e:e	Tech	nology		Touch incl.
Inch	Cm	RGB	LVDS	eDP	SFT	EVT	Resolution	PCAP
5.7	15	х	х				QVGA / VGA	
6.5	17	Х	Х			Х	VGA / XGA	XX
7.0	18		Х			х	WVGA	XX
8.0	20		Х				WVGA	
8.4	21	х	Х		Х	х	VGA / SVGA / XGA	XX
8.9	22		х				WSVGA	
9.0	23		Х		Х		WVGA / Full HD	
10.1	25		Х		Х		WXGA	
10.4	26	Х	Х		х	Х	VGA / SVGA / XGA	XX
10.6	26.5		х		Х		WXGA	XX
11.6	29			Х	Х		Full HD	
12.1	31	х	Х		Х	х	SVGA / XGA / WXGA	XX
15.0	38		Х		Х		XGA	XX
15.3	39		Х		х		WXGA	XX
15.6	40		Х	Х	Х		FWXGA / Full HD	
17.0	43		Х				SXGA	
18.5	47		Х	Х	Х		Full HD	
19.0	48		х		Х		SXGA	
21.3	53		Х		Х		QXGA	
30.0	76			Х	Х		WQSXGA	

Basic Line

Dis	play Size	Int	erface	Resolution	Touch incl.
Inch	Cm	RGB Interface			PCAP
7	18	Х	Х	WVGA	
8.4	21		Х	SVGA	
10.4	26		X	SVGA	
12.1	31		X	SVGA / XGA	
15	38		Χ	XGA	XX

SFT Technology (Super Fine TFT)

High Luminance, Wide Color Gamut

With the SA-SFT and UA-SFT technologies Tianma has achieved improved panel transmissivity, resulting in higher luminance and wider color gamut displays allowing customers to view clear and vivid color images in bright environments.

High Definition

Tianma offers products with pixel density of up to 200 pixels/ inch and resolution of up to 5M pixel displays. That means customers enjoy faithful reproduction of high-precision images down to the finest details - from the fine text and lines of CAD and DTP to the delicate nuances of nature images and imaging data for medical purposes.

Quick Response

Tianma is developing the SFT technology, which features low dependence on response time between gray-scale levels, to achieve uninterrupted full-motion video.

Ultra-wide Viewing Angle, Reduced Color Shift

LCDs with SFT Technology feature a new ultra-wide 170° (right/left and up/down) viewing angle while minimizing the color shift phenomenon that occurs as luminance changes with viewing angle. The result is a new and definitive benchmark in image quality with virtually no color deviation a great picture no matter how you look at it.

EVT Technology (Enhanced View TFT)

R-EVT Guarantees High-visibility in All Outdoor Light Environments

R-EVT maximizes the high ambient light visibility features of a reflective-type LCD along with the low ambient light visibility features of a transmissive-type LCD to deliver high picture quality in all possible light environments.

R-EVT: Reflective EVT T-EVT: Transmissive EVT

T-EVT Brings You the Clearest, Sharpest Pictures Under the Sun

This revolutionary new T-EVT is a transmissive type that guarantees bright, easy-viewing displays even in bright sunlight. It's the history-making forerunner of a new generation of LCDs unaffected by changes in natural light - for bright, vivid color displays anytime.

Projected Capacitive Touch Panel

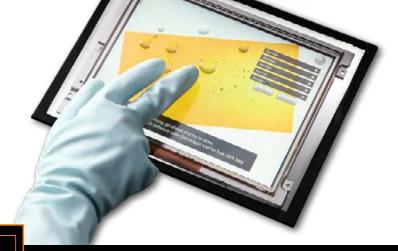
PCAP by Tianma as a One-stop Shop Solution

Tianma provides factory installed touch panels which have an external touch controller as option. Thanks to the in-house design and manufacturing capabilities they are able to offer high quality, integrated PCAP products direct from the factory as a one stop shop solution with full factory warranty.

Tianma provides factory tuned PCAP products, drivers and offer special tuning software as part of Tianma total PCAP solutions, in order to better support customer's needs and help ease adoption of Tianma's PCAP based modules.

Due to the fact that the requirements of the customers are very individually, most requests need to be handled as a custom solution. Customized options are different surface film, optical bonding and customized cover glasses.















TFT Color Modules

TFT Color Modules

The following TFT Color graphic modules are produced in their own TFT factory in Shanghai. This will greatly benefit Tianma and their customers by guaranteeing long-term availability of the products. With currently three 4.5 TFT production lines and one 5.0G TFT production line Tianma Group is now one of the largest manufacturers of small and medium size TFT modules worldwide. Tianma's products offer a lot of technical advantages such as wide viewing angle, high contrast, high brightness and fast response time and are produced for industrial, telecommunication and automotive applications.

Focus Products

Displa	y Size		Interface		Danahatian	Taskaslama	Lifetime in Hours	Touch incl
Inch	Cm	RGB	LVDS	Others	Resolution	Technology	Lifetime in Hours	Touch incl.
2.0	5.1			CPU	QCIF	TN	20k	
2.2	5.6	XX			QVGA	R-EVT	20k	
2.4	6.1			CPU	QVGA	TN	20k	
2.8	7.1	XX			QVGA	TN	30k	
3.0	7.6			CPU	QVGA	R-EVT	20k	
3.5	8.9	XX		CPU / SPI	QVGA / HVGA	TN	20k / 30k	RTP
4.0	10.2			MIPI	WVGA	SFT	20k	
4.3	11.0	XX			WQVGA	TN	20k / 30k	RTP / PCAP
5.0	12.7	XX			WVGA	TN	20k	RTP
5.7	14.5	XX			QVGA / VGA	TN	50k	
7.0	17.8	XX	XX		WVGA / WSVGA / WXGA	TN / SFT	20k / 30k / 50k	RTP / PCAP
8.0	20.3	XX			SVGA	TN	25k / 40k	
8.4	21.3	XX	XX		SVGA	TN	30k / 50k	
9.7	24.6		XX		XGA	TN	30k	
10.1	25.6		XX		WSVGA / WXGA	TN / SFT	30k / 50k	
10.4	26.5	XX	XX		SVGA	TN	30k	
12.1	30.8		XX		SVGA / XGA / WXGA	TN / SFT	30k / 50k	
15.0	38.1		XX		XGA	TN	30k / 50k	

Foster Products

Display	y Size		Interface		Resolution	Technology	Lifetime in Hours	Touch incl.			
Inch	Cm	RGB	LVDS	Others	nesolution	recimiology	Lifetine III Hours	ioudil IIIdi.			
2.3	5.8			CPU	QVGA	TN	20k				
2.4	6.1			CPU/SPI	QVGA	SFT	20k				
3.3	8.4			MIPI	320x320 round	TN	20k				
3.5	8.9	XX			QVGA	TN	20k	PCAP			
4.3	11.0	xx			WQVGA / WVGA	TN / SFT	20k / 30k	RTP / PCAP			
4.6	11.7			MIPI	WXGA	SFT	20k				
5.0	12.7	XX		MIPI	WVGA / WXGA	TN / SFT	20k / 50k	PCAP			
5.7	14.5	xx			QVGA	TN	50k	RTP / PCAP			
7.0	17.8		xx		WVGA / WSVGA / WXGA	TN / SFT	20k / 30k / 50k	PCAP			
8.0	20.3		xx		XGA	TN / SFT	30k				
10.1	25.6		XX		WSVGA / WXGA	TN / SFT	20k /30k / 50k	PCAP			
10.4	26.5		xx		XGA	SFT	50k				
12.1	30.8		xx		SVGA / XGA / WXGA	TN / SFT	50k	PCAP			
15.0	38.1			eDP	XGA	TN	30k				





TFT Technology by U.R.T.

U.R.T. products are widely applied in a broad range of applications and markets.

With advancing technologies in digital, dot matrix and graphic LCD panels and modules, U.R.T. is always committed to produce LCD products with the highest level of contrast, wide viewing angles, long life, and high reliability.

Bartype TFT Portfolio

Siz	ze	Resolution	Interface	Touch Panel	
Inch	Cm	Resolution	illeriace	Touch I allei	
2,9	7,37	320x120	RGB	Optional	
3,9	9,91	480x128	RGB	Optional	
4,6	11,68	800x320	RGB	Optional	
5,8	14,73	800x320	RGB	Optional	
6,1	15,49	800x240	RGB	Optional	
6,5	16,51	800x320	RGB	Optional	
8,8	22,35	1280x320	LVDS	Optional	
9	22,86	1280x240	LVDS	Optional	
12,3	31,24	1920x720	LVDS	Optional	

Product Portfolio TFT

Si	ze	Resolution	Interface	Touch
Inch	Cm	Resolution	interrace	Panel
2,4	6,10	QVGA	MPU	PCAP, RTP
2,8	7,11	QVGA	MPU	PCAP, RTP
3,5	8,89	QVGA, VGA	RGB, MPU	PCAP, RTP
4,3	10,92	480RGBx272, 800x480	RGB	PCAP, RTP
5,0	12,70	800x480	RGB	PCAP, RTP
5,7	14,48	QVGA, VGA	RGB, MPU, LVDS	PCAP, RTP
7,0	17,78	800RGBx480, 1024x600	RGB, LVDS	PCAP, RTP
10,1	25,65	1280x800	LVDS	PCAP, RTP
10,4	26,42	XGA	LVDS	Optional
12,1	30,73	XGA, 1280x800	LVDS	Optional
15	38,10	XGA	LVDS	Optional
15,6	39,62	1366x768	LVDS	Optional
18,5	46,99	1366x768	LVDS	Optional









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Yeebo with the headquarter located in Hong Kong is producing with multiple, highly automated production lines which have latest state of the art equipment to meet the requirements of most applications.

With their experienced and professional design team they are able to tailor their service to meet every individual need from the customers. With a portfolio with a focus on 1,44" up to 7" and some additional panels up to 12,1" they meet the requested sizes and features for the European industrial market.



TFT Portfolio

Si	ze		Interface		Danahatian	Traburatana	lifetime in Herma	Touch in al
Inch	Cm	RGB	LVDS	Others	Resolution	Technology	Lifetime in Hours	Touch incl.
1.44	3.6			CPU	128x128	TN	20k	
1.77	4.5			MCU	128x160	TN	50k	
2.0	5.1	XX		MCU	160x240 / 176x220	TN	20k / 50k	
2.4	6.1	XX		MCU / SPI	240x320	TN / IPS	20k / 50k	PCAP
2.8	7.1	XX		MCU / SPI	240x320	TN / IPS	20k / 50k	RTP / PCAP
3.2	8.1			MCU / SPI	240x320	TN	50k	
3.5	8.9	XX		MCU / SPI	320x240 / 320x480	TN / IPS	20k / 50k	RTP / PCAP
3.97	10.1	XX			480x800	IPS	20k	
4.3	10.9	XX	XX		480x272	TN / IPS	20k / 50k	RTP / PCAP
4.5	11.4			MIPI	480x854	IPS	50k	RTP
5.0	12.7	XX			800x480	TN	20k	RTP / PCAP
5.5	14.0			MIPI	720x1280	IPS	50k	
7.0	17.8	XX			800x480	TN	50k	PCAP
9.0	22.9	XX			800x480	TN	20k	
10.1	25.6		XX		1280x800 / 1024x600	IPS	50k	PCAP
12.1	30.7		XX		1024x768	TN	50k	







E-Papers

1- Dot- Matrix E-Papers

Matrix displays are intended for applications requiring the display of many different forms of text and images. These displays comprise of a large array of pixels. These individual pixels are controlled by a TFT array.

Holitech offers a range of standard products for 1.5" up to 42". Most of the sizes are available in:

- Black white | Black White Red | Black White Yellow
- Frozen (supports temperatures below 0°C)

Tooling for Dot-Matrix displays should be discussed case by case and could only be done for big volumes if we get the needed TFT support.

Segmented E-Papers

Segmented displays are intended for applications where the display requirements can be met using predefined segments that can be turned on or off. Segmented Displays are in general customized solutions. Only one or two displays are available as standard products.

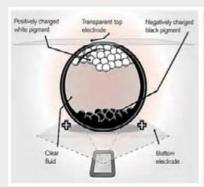
Tooling for segmented displays can be made for small quantities (starting from 10kpcs) and costs between 8k\$ ~ 10k\$

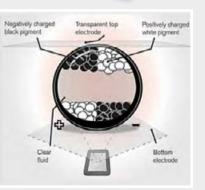


The two pigment electronic ink system is made up of millions of tiny microcapsules, each about the diameter of a human hair. Each microcapsule contains negatively charged white particles and positively charged black particles suspended in a clear fluid.

When a positive or negative electric field is applied, corresponding particles move to the top of the microcapsule where they become visible to the viewer. This makes the surface appear white or black at that spot.

Boards & Systems | Storage | Displays | Wireless





Standard Product List

Size (Inch)	Color	Resolution	OD (mm)	AA (mm)	DPI (mm)	IC
1.5	Black white/red/yellow	200×200	31.8×37.32	27×27	188	SSD1681
2.13	Black white/red/yellow	212×104	29.2×59.2	23.8×48.55	110	SSD1675
2.13	Black white/red/yellow	250×122	29.2×59.2	23.8×48.55	130	SSD1675
2.66	Black white/red/yellow	152×296	36.3×71.82	30.7×60.09	125	SSD1675
2.7	Black white/red/yellow	176×264	45.8×70.42	38.192×57.288	117	JD79651AA
2.9	Black white/red/yellow	128×296	36.7×79	29.06×66.9	112	SSD1675
3.7	black white red	240×416	53×92.99	47.04×81.536	130	HT0001
4.2	black white	400×300	91×77	84.8×63.6	119	SSD1608×2
4.2	Black white/red/yellow	400×300	91×77	84.8×63.6	119	SSD1619/UC8176
4.3	Black white/red/yellow	152×522	36.7×117.17	30.7×105.44	125	EK79686
7.5	Black white/red/yellow	640×384	170.2×111.2	163.2×97.92	99	UC8159
7.5	Black white/red/yellow	880×528	170.2×111.2	163.2×97.92	137	SSD1677
10.2	Black white/red/yellow	960×640	224×157	215.52×143.68	113	SSD1677
13.3	black/white	680x960	286.32x212.26	275.52x195.16		SSD1677
32	black/white	2560x1440	697.2x402.8	691.2x388.3		SSD1677
42	black/white	2160x2880	872.5x650	856.8x642.6		SSD1677











TFTs & OLEDs

Rutronik's new partner DLC offers monochrome, TFT and OLEDs including further components related to displays. DLCs convinces with its wide range of products, especially in the field of TFTs and OLEDs. We are able to offer a big choice of transflective, high-brightness and IPS technologies and guarantee excellent viewing angles and high temperature ranges. Our collection boasts more than 200 TFT and monochrome displays, as well as over 20 models of monochrome OLED displays, all of which are available in sizes ranging from 1.4 to 19 inches.

Size				Touch Donal	
Size (Inch)	Cm	Resolution	Interface	Touch Panel	
0.9	2.29	80RGBx160	SPI	Optional	
1.3	3.30	240RGBx240	SPI	Optional	
1.44	3.66	128RGBx128	CPU	Optional	
1.77	4.50	128RGBx160	CPU	Optional	
1.9	4.83	170RGBx320	CPU	PCAP	
2.0	5.08	QVGA, 480x360	CPU, RGB, MIPI	Optional	
2.2	5.59	QVGA	CPU	Optional	
2.4	6.10	QVGA	CPU	Optional	
2.45	6.22	272RGBx480	RGB	Optional	
2.83	7.19	QVGA	CPU/RGB	Optional	
3.2	8.13	QVGA	RGB	Optional	
3.5	8.89	320RGBx480, QVGA	SPI, MCU, RGB,	PCAP, RTP	
3.95	10.03	480RGBx480	MIPI	Optional	
4.3	10.92	480RGBx272, 800x480	RGB, MCU	PCAP, RTP	
5.0	12.70	480x272, 640RGBx480, 800x480	RGB	PCAP, RTP	
5.6	14.22	640RGBx480	RGB	Optional	
5.7	14.48	QVGA, VGA	RGB, TTL, LVDS	PCAP, RTP	
6.5	16.51	800RGBx480	RGB	PCAP	
7.0	17.78	800RGBx480, 1024x600	RGB, TTL, LVDS	PCAP, RTP	
8.0	20.32	800RGBx480, 800x600, 1024x600	RGB, LVDS	PCAP, RTP	
8.4	21.34	800xRGBx600	LVDS	Optional	
9.0	22.86	800RGBX480	RGB	Optional	
10.1	25.65	1024RGBx600, 1280x800	RGB, LVDS	PCAP, RTP	
10.2	25.91	800RGBx480	RGB	Optional	
10.25	26.04	1920RGBx720	LVDS	Optional	
10.3	26.16	1280RGBx480	LVDS	Optional	
10.4	26.42	VGA, SVGA, XGA	TTL, LVDS	Optional	
12.1	30.73	SVGA, XGA, 1280x800	LVDS	PCAP, RTP	
12.3	31.24	1920RGBx720	LVDS	Optional	
15	38.10	XGA	LVDS	Optional	



OLEDs Offer Many Advantages over Both LCDs and LEDs

The plastic, organic layers of an OLED are thinner, lighter and more flexible than the crystalline layers in an LED or LCD. Because the light-emitting layers of an OLED are lighter, the substrate of an OLED can be flexible instead of rigid. OLED substrates can be plastic rather than the glass used for LEDs and LCDs. OLEDs are brighter than LEDs. Because the organic layers of an OLED are much thinner than the corresponding inorganic crystal layers of an LED, the conductive and emissive layers of an OLED can be multi-layered. Also, LEDs and LCDs require glass for support, and glass absorbs some light. OLEDs do not require glass. OLEDs do not require backlighting like LCDs. LCDs work by selectively blocking areas of the backlight to make the images that you see, while OLEDs generate light themselves.



Because OLEDs do not require backlighting, they consume much less power than LCDs. This is especially important for batteryoperated devices such as cell phones.

OLEDs are easier to produce and can be made to larger sizes. Because OLEDs are essentially plastics, they can be made into large, thin sheets. It is much more difficult to grow and lay down so many liquid crystals.

OLEDs have large fields of view, about 170 degrees. Because LCDs work by blocking light, they have an inherent viewing obstacle from certain angles. OLEDs produce their own light, so they have a much wider viewing range.

DLC P/N	Size (Inch)	Dot Format	A.A. (mm)	Outline Size (mm)	Interface	Colors	Remarks
DLC0049AZOG-W-1	0.49	64x32	11.18x5.58	14.50x11.60	I2C	White	Monochrome
DLC0066ANOG-3	0.66	64x48	13.42x10.06	18.46x18.10	Parellel/SPI/I2C	Blue	Monochrome
DLC0066ANOG-W-4	0.66	64x48	13.42x10.06	18.46x18.10	Parallel/SPI/I2C	White	Monochrome
DLC0069AZOG-W	0.69	96x16	17.26x3.18	26.30x8.00	SPI	White	Monochrome
DLC0091CNOG-W	0.91	128x32	22.384x5.584	30.00x11.50	SPI	White	Monochrome
DLC0095DNOG-2	0.95	96x64	20.14x13.42	25.70x22.20	Parellel/SPI	Color	Passive Color
DLC0096DNOG-W-5	0.96	128x64	21.74x10.86	24.74x16.90	SPI/I2C	White	Monochrome
DLC0112AZOG	1.12	96x96	20.14x20.14	25.80x30.10	Parellel/SPI	Color	Passive Color
DLC0119AEOF	1.19	390x390	30.42	33.22x34.72	MIPI	16.7M	AMOLED,Round
DLC0129AZ0F-1	1.29	128x96	26.28x19.71	33.00x25.80	Parallel/SPI	Color	Passive Color
DLC0130ANOG-W	1.30	128x64	29.42x14.70	34.50x23.00	Parellel/SPI/I2C	White	Monochrome
DLC0130CMOG	1.30	360x360	32.94	35.34x36.07	MIPI	16.7M	AMOLED,Round
DLC0132AZOG-W	1.32	128x96	26.86x20.14	32.50x29.20	Parallel/SPI/I2C	White	Monochrome
DLC0137AZOG	1.37	128x128	24.55x24.56	31.20x33.80	Parellel/SPI	Color	Passive Color
DLC0139BQOG	1.39	400x400	35.40	38.60x40.50	MIPI	16.7M	AMOLED,Round
DLC0141AEOG	1.41	320x360	23.84x26.82	26.04x31.78	MIPI	16.7M	AMOLED
DLC0145BNOF	1.45	160x128	28.78x23.02	35.80x30.80	Parallel/SPI	Color	Passive Color
DLC0146AZOF-1	1.46	128x128	26.279x26.284	33.50x33.50	Parallel/SPI	Color	Passive Color
DLC0150CNOG-W	1.50	128x128	26.86x26.86	33.80x36.50	Parallel/SPI/I2C	White	Monochrome
DLC0154BNOG-W-1	1.54	128x64	35.05x17.52	42.04x27.22	Parellel/SPI/I2C	White	Monochrome
DLC0160AZOG-Y	1.60	128x64	36.45x18.21	41.90x28.00	Parallel/SPI	Yellow	Monochrome
DLC0177AZ0F-1	1.77	160x128	35.02x28.01	42.80x33.50	Parallel/SPI	Color	Passive Color
DLC0223ANOG-1	2.23	128x32	55.02x13.10	62.00x24.00	Parellel/SPI/I2C	B/Y/W	Monochrome
DLC0242BNOG-W-2	2.42	128x64	55.01x27.49	60.50x37.00	Parallel/SPI/I2C	White	Monochrome
DLC0293ANOG-B-2	2.93	20x2	73.52x11.52	84.50x19.28	Parellel/SPI/I2C	Blue	Monochrome
DLC0295AZOM	2.95	1080x1200	50.11x55.68	52.91x62.58	MIPI	16.7M	AMOLED
DLC0550ANOF	5.50	256x64	135.65x33.89	146.00x45.00	Parallel/SPI	B/G	Monochrome
DLC0550AZOM	5.50	1080x1920	68.299x121.421	70.66x128.36	MIPI	16.7M	AMOLED





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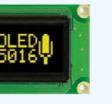














OLED and TFT Display Modules



Specialized in Standard and Custom OLED Modules

Raystar Optronics. Inc., located at Central Taiwan Science Park, is one of the leading OLED display suppliers founded by a group of elites being in the related field for more than 10 years. Its production line includes small to medium size OLED modules for a variety of industrial and consumable applications. Raystar is one of the leading display providers of monochrome character, graphic and alphanumeric OLED panels. Our Portfolio covers all types of PM OLEDs in the size of 0.49 inch upto 5.85 inch in every color variation without a MOQ. TFTs Raystar is also a professional TFT (Thin Film Transistor) Modules Manufacturer. The TFT display modules include TFT LCD displays, TFT displays with resistive or capacity touch screen options and TFT displays with control board, higher brightness or wider viewing angle TFT display modules, monochrome TFT and Bar Type TFT display modules. We can offer customization in backlight or FPC service. Available TFT outlines are 2.4", 2.8", 3.5", 3.9", 4.3", 4.6", 5", 5.2", 5.7", 6.2", 7", 8", 9", 10.1", 10.2", 12.1" and 12.3".

OLED Display Module - COB

Туре	Size (")	Size (cm)	Outline (mm)	View Area (mm)	Active Area (mm)	Pixel Pitch (mm)	Interface
Character	1.20	3.0	58.00×32.00	38.00×16.00	28.16×11.86	0.60×0.70	default 6800, option 8080, SPI
Character	2.29	5.8	80.00×36.00	66.00×16.00	56.95×11.85	0.60×0.70	default 6800, option 8080, SPI
Character	2.29	5.8	85.00×36.00	66.00×16.00	56.95×11.85	0.60×0.70	default 6800, option 8080, SPI
Character	2.29	5.8	85.00×30.00	66.00×16.00	56.95×11.85	0.60×0.70	default 6800, option 8080
Character	2.29	5.8	84.00×44.00	66.00×16.00	56.95×11.85	0.60×0.70	default 6800, option 8080, SPI
Character	3.67	9.3	122.00×44.00	98.00×21.00	91.14×18.98	0.96×1.12	default 6800, option 8080, SPI
Character	3.08	7.8	116.00×37.00	85.00×18.60	77.30×11.85	0.65×0.70	default 6800, option 8080, SPI
Character	2.88	7.3	98.00×60.00	77.00×25.20	70.16×20.95	0.59×0.60	default 6800, option 8080, SPI
Character	2.88	7.3	98.00×60.00	77.00×25.20	70.16×20.95	0.59×0.60	default 6800, option 8080, SPI
Character	5.85	14.9	182.00×38.50	154.40×16.50	148.13×11.85	0.62×0.70	default 6800, option 8080, SPI
Graphic	1.26	3.2	58.00×32.00	38.00×16.00	29.96×11.16	0.60×0.70	default 6800, option 8080, SPI
Graphic	2.40	6.1	80.00×36.00	66.00×16.00	59.95×11.15	0.60×0.70	default 6800, option 8080, SPI
Graphic	2.40	6.1	85.00×36.00	66.00×16.00	59.95×11.15	0.60×0.70	default 6800, option 8080, SPI
Graphic	2.40	6.1	85.00×30.00	66.00×16.00	59.95×11.15	0.60×0.70	default 6800, option 8080
Graphic	2.40	6.1	84.00×44.00	66.00×16.00	59.95×11.15	0.60×0.70	default 6800, option 8080, SPI
Graphic	2.59	6.6	116.00×37.00	85.00×18.60	64.95×11.15	0.65×0.70	default 6800, option 8080, SPI
Graphic	3.84	9.8	122.0×44.0	98.00×21.00	95.94×17.86	0.96×1.12	6800
Graphic	2.44	6.2	98.00×60.00	77.00×25.20	58.95×19.15	0.59×0.60	default 6800, option 8080, SPI
Graphic	2.44	6.2	98.00×60.00	77.00×25.20	58.95×19.15	0.59×0.60	default 6800, option 8080, SPI
Graphic	4.90	12.4	182.00×38.50	154.40×16.50	123.95×11.15	0.62×0.70	default 6800, option 8080, SPI
Graphic	4.86	12.3	180.00×40.00	149.00×23.00	121.90×19.42	1.22×1.22	default 6800, option 8080, SPI
Graphic	2.44	6.2	98.00×60.00	77.00×25.20	58.95×19.15	0.59×0.60	default 6800, option 8080, SPI
Graphic	4.90	12.4	182.00×38.50	154.40×16.50	123.95×11.15	0.62×0.70	default 6800, option 8080, SPI



Туре	Size (")	Size (cm)	Outline (mm)	View Area (mm)	Active Area (mm)	Pixel Pitch (mm)	Interface
Character (W PCB)	1.23	3.1	53.00×20.00	36.00×10.00	30.69×5.94	0.34×0.36	default 6800, option 8080, SPI
Character (W/O FR)	2.26	5.7	68.50×17.50	58.22×13.52	56.22×11.52	0.60×0.70	6800, 8080, SPI, I2C
Character (W PCB)	2.26	5.7	84.00×44.00	58.22×13.52	56.22×11.52	0.60×0.70	default 6800, option 8080, SPI
Character (W/O FR)	2.93	7.4	84.50×19.28	75.52×13.52	73.52×11.52	0.65×0.70	6800, 8080, SPI, I2C
Graphic (W/O FR)	0.71	1.8	13.90×22.00	12.14×16.30	10.54×14.70	0.22×0.23	I2C
Graphic (W/O FR)	0.49	1.2	14.50×11.60	12.58×6.58	11.18×5.58	0.18×0.18	I2C
Graphic (W/O FR)	0.66	1.7	18.46×18.10	15.42×12.06	13.42×10.06	0.21×0.21	6800, 8080, SPI, I2C
Graphic (W/O FR)	0.84	2.1	29.10×9.20	23.10×5.50	21.10×3.50	0.22×0.22	I2C
Graphic (W/O FR)	0.68	1.7	19.80×12.32	17.298×6.418	16.298×5.418	0.17×0.17	6800, 8080, SPI, I2C
Graphic (W/O FR)	1.10	2.8	29.00×22.50	24.54×17.02	22.53×15.01	0.235×0.235	6800, 8080, SPI, I2C
Graphic (W/O FR)	2.23	5.7	62.00×24.00	57.02×15.10	55.02×13.10	0.43×0.41	6800, 8080, SPI, I2C
Graphic (W/O FR)	0.91	2.3	30.00×11.50	24.38×7.58	22.38×5.58	0.18×0.18	SPI
Graphic (W/O FR)	0.91	2.3	30.00×11.50	24.38×7.58	22.38×5.58	0.18×0.18	I2C
Graphic (W/O FR)	1.71	4.3	50.50×15.75	44.22×12.54	42.22×10.54	0.33×0.33	SPI, I2C
Graphic (W/O FR)	2.03	5.2	59.00×18.86	52.535×12.695	50.535×10.695	0.395×0.335	6800, 8080, SPI, I2C
Graphic (W/O FR)	1.54	3.9	42.04×27.22	37.05×19.52	35.05×17.51	0.27×0.27	6800, 8080, SPI, I2C
Graphic (W/O FR)	0.96	2.4	26.70×19.26	23.34×11.46	21.74×10.86	0.17×0.17	6800, 8080, SPI, I2C
Graphic (W/O FR)	0.96	2.4	26.70×19.26	23.94×12.06	21.74×10.86	0.17×0.17	6800, 8080, SPI, I2C
Graphic (W/O FR)	2.42	6.1	60.50×37.00	57.01×28.91	55.01×27.49	0.43×0.43	6800, 8080, SPI, I2C
Graphic (W/O FR)	2.42	6.1	60.50×37.00	57.01×28.91	55.01×27.49	0.43×0.43	6800, 8080, SPI, I2C
Graphic (W PCB)	2.42	6.1	75.00×52.70	57.01×29.49	55.01×27.49	0.43×0.43	default 8080,option 6800, SPI, I2C
Graphic (W/O FR)	2.70	6.9	73.00×41.86	63.41×32.69	61.41×30.69	0.48×0.48	6800, 8080, SPI, I2C
Graphic (W/O FR)	2.70	6.9	73.00×41.86	63.41×32.69	61.41×30.69	0.48×0.48	6800, 8080, SPI, I2C
Graphic (W/O FR)	1.29	3.3	34.50×23.00	31.32×15.61	29.42×14.20	0.23×0.22	6800, 8080, SPI, I2C
Graphic(W/O FR)	0.96	2.4	26.70×19.26	23.74×13.20	21.74×11.20	0.17×0.17	6800, 8080, SPI, I2C
Graphic(W/O FR)	2.70	6.9	73.00×41.86	63.41×32.69	61.41×30.69	0.48×0.48	6800, 8080, SPI, I2C
Graphic (W/O FR)	1.54	3.9	45.24×29.14	37.05×19.51	35.05×17.51	0.274×0.274	6800, 8080, 4-wire, SPI, I2C
Graphic (W/O FR)	1.50	3.8	33.80×36.50	28.86×28.86	26.86×26.86	0.21×0.21	6800, 8080, SPI, I2C
Graphic (W/O FR)	1.18	3.0	36.98×41.23	32.00×32.00	30.00×30.00	0.23×0.23	6800, 8080, SPI, I2C

OLED Display Module - TAB

Туре	Size (")	Size (cm)	Outline (mm)	View Area (mm)	Active Area (mm)	Pixel Pitch (mm)	Interface
Graphic (W/O FR)	2.80	7.1	84.00×25.80	71.10×19.26	69.10×17.26	0.27×0.27	6800, 8080, SPI
Graphic (W/O FR)	3.12	7.9	88.00×27.80	78.78×21.18	76.78×19.18	0.30×0.30	6800, 8080, SPI
Graphic (W/O FR)	5.50	14.0	146.00×45.00	137.65×35.89	135.65×33.89	0.53×0.53	6800, 8080, SPI











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Intelligent Displays for ARDUINO

Showcasing your Pi output

RASPBERRY PI & ASUS Tinker Board

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microLCD Display Modules



1.44"-9.0" | 128x128 - 800x480 px 5V Adaptors: Arduino, Raspberry Pi & ASUS

microOLED Display Modules



0.96"-1.77" | 96x64 - 160x128 px 5V Non-Touch Displays

Integrated Display Solutions



3.5"-5.0" | 480x320 - 480x854 px 5V Panel mountable smart display controller

Wifi Display Solutions



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gen4-loD Display Modules



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Primary Displays for Raspberry Pi



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Primary Displ. for ASUS Tinker Board



4.3"-7.0" | 480x272 - 800x480 px 5V Resistive & Capacitive Touch Displays

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Sound module and camera with different lenses available

Accessories



Programming adaptors, USB cables, bezels for open frame displays

Modules On The Go (MOTG)



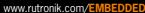




Bluetooth - adaptor PCB available



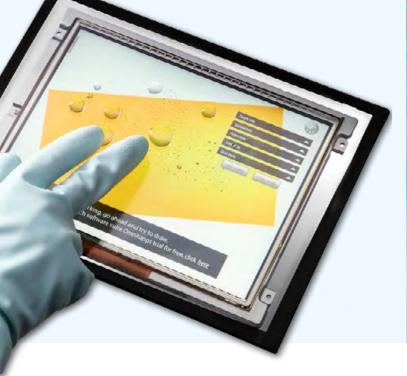




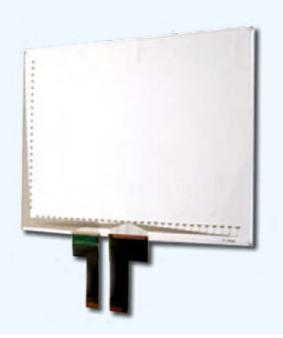
Boards & Systems | Storage | Displays | Wireless













Touch Systems

Resistive Touch Technologies

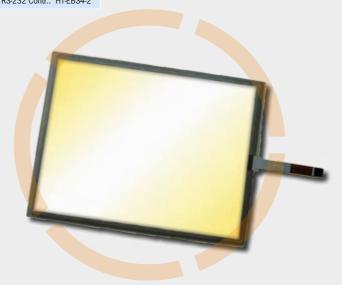
A resistive touch sensor has two layers that are not in contact with each other

- An outside flexible layer, coated on the inside with a conductor, e.g. ITO (Indium Tin Oxide)
- Non-conductive separator "dots", e.g. mica or silica, small enough to not be noticeable
- An inside supporting layer of glass, coated on its face with conductor (ITO)

Around the outside of the viewing area is a printed circuit pattern. When the outside flexible layer is pressed against the inside layer, the resulting voltages can be measured in more than one direction. By comparing these voltages to the starting voltage, the point where the touch happened can be calculated. Resistive sensors are simple and relatively inexpensive. The flex required to push the surfaces together can eventually fail the flexible layer.

The flex requires some pressure, so force is required to make contact. The presence of two layers in addition to the LCD can reduce brightness by 10-20%. On the plus side, a new flexible glass outer layer is now available to improve wear and chemical resistance. Overall, the technology is simple and predictable, so resistive sensors remain the most common form of touch sensor.

4 wire i	resistive	4 wire GI	as / Glas	5 wire	resistive
Inch	cm	Inch	cm	Inch	cm
2.9 - 4	7.4 - 10.2	5	12.7	6.5	16.2
4.3	11	5.7	14.5	7	17.8
5.7	14.5	7	17.8	8.4	21.4
6.4	16.3	8.4	21.3	10.4	26.4
7	17.8	10.4	24.5	12.1	30.7
7.5	19	12.4	30.7	15	38.1
8	20.3	15.1	38.5	17	43.2
8.4	21.3	17.1	43.5	19	48.3
10.4	26.5	Available as		20.1	51
12.1	30.8	and as A0	i/AR type	22	55.9
15	38.1			24	61
17	43.2				ntroller:
19	48.3			RS-232	000UECG Contr.: 000RECG
	er: HT-EBU4-3			EII MID 3	OUNLOG



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Han touch.com

Capacitive Touch Technologies

A capacitive touch sensor is a simple supporting sheet of glass with a conductive coating on one side. Around the outside of the viewing area is a printed circuit pattern. This pattern sets a charge across the surface, which is disturbed by the finger touching the screen. There are various technologies that detect the touch differently: some can even detect near-touches without making contact. All capacitive sensing methods look for electrical disturbance, so the electrical characteristics of the touching object are important. One finger is much like another, but a glove, a stylus or other types of objects may change the response or not respond at all. Capacitive sensors are built right on a single glass layer. They don't break down by from flexing, but they may be subject to abrasion of the ITO coating. The single layer transmits light well, so brightness reduction is only 5-15%. The contact requires no pressure, so the force required to make touch is insignificant.

Projected Capacitive Technology

Projected Capacitive Touch (PCT, also PCAP) technology is a variant of capacitive touch technology. This technology allows two points recognition and light touch inputs. Work with gloves as well as cover glass make flat designs possible. These features make the technology a good choice for industrial and medical applications.

Сар.	ioucii	SAW-	ioucii	IK IC	oucn
Inch	cm	Inch	cm	Inch	cm
5.8	14.7	8.4	21.4	15	38.1
6.8	17.3	10.4	26.4	17	43.2
7.3	18.5	12.1	30.8	19	48.3
8.5	21.6	15	38.1	32	81.3
10.8	27.4	17	43.2	42	106.7
12.4	31.5	19	48.3	Options: AG /	AR, 6mm Glas
15.7	39.9	21	53.3		
17.5	44.5	22	55.9		
19.4	49.3		HAT-EBUS-2		
22.4	56.9	and antivan	ar, AG or AR dalism type		

Han touch.com

HIGGSTEC INC.

Proj. Ca	p. Touch
Inch	cm
5.7	15.5
6.5	16.4
7 wide	17.8
8.4	21.3
9 wide	23
10.4	26.4
12.1	30.8
15	38.1
17	43.2
19	48.3
22 wide	55.9
Controller L avail	

66.8

80.8

Controller: C-3100

26.3

DMC Co., Ltd.

Features

- High durability
- High transmission
- Water resistance
- Two points touch is available
- Input with glove is possible
- High resolution























Passive LCD Modules

Rutronik's application team – the engineering bridge to a wide field of display solutions with an excellent supplier portfolio.

The main area of activities of our display department is to offer customized solutions. Due to our experience in the display market we will provide you with the best solution and the most suitable manufacturers for your requirements.

The philosophy of the display department is to give you our best engineering consultancy in project work. We are the worldwide interface between customers, suppliers, R+D, Quality Management, Production and Purchase Department.

Technology	Dot Color / Background	Features
TN, HTN	black / grey optional other	TN (Twisted Nematic) / HTN (Higher Twisted Nematic) is the most cost-effective technology
STN / grey, silver, blue	dark blue / yellow green	STN (Super Twisted Nematic) twisting angle up to 270° which gives almost ideal steepness of the characteristic optoelectronic curves improvement of the viewing angle
FSTN	black / white	FSTN (Film Super Twisted Nematic) high-contrast black and white representation by utilization of a decelerating film more cost-effective, lighter and flatter than DSTN
Vertical Align- ment	Optional / black	VA, super black background, super wide viewing angle, high contrast ratio
FSC	Optional / positive, negative	FSC (Field Sequential Colour) No need of colour filter, low power consumption
FFSTN	black / white negative	FFSTN (Double Film Super Twisted Nematic) high-contrast black and white negative mode display optimal performance with white or multicolor backlights more cost-effective, lighter and flatter than DSTN ISTN for best contrast through the whole temp. range
CSTN	color	FSTN with color filter mask (passive matrix) passive driven not matrix white LED or CCFL illumination
ASTN	color/dark	compensation retardation film, low transmittance $\&$ high contrast

















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LCD Standard Modules

Liquid crystal displays, in the form of passive matrix LCDs, are increasingly found in all areas of everyday life. Their use is no longer restricted to technical applications. We are able to fulfil your standard passive LCD requirements with a lot of different module types. In which you can choose several individual parameters, like nearly all kinds of backlight colours, different temperature ranges and different technologies.

We cover the most common alphanumeric and graphic LCD sizes. All displays are available in transmissive, transflective and reflective mode.

Passive LCD Modules from Displaytech

Characters x Lines	Model Number	Module Size W x H [mm]	View. Area W x H [mm]
16 x 1	161A	80.0 x 36.0	64.5 x 13.8
16 x 2	162A	80.0 x 36.0	64.5 x 13.8
16 x 2	162B	84.0 x 44.0	65.6 x 16.0
16 x 2	162C	80.0 x 36.0	64.5 x 14.8
16 x 2	162COG	66.0 x 27.7	61.0 x 15.7
16 x 2	162D	85.0 x 30.0	62.0 x 16.0
16 x 2	162E	80.0 x 36.0	65.6 x 16.0
16 x 2	162F	122.0 x 44.0	99.0 x 24.0
16 x 4	164A	87.0 x 60.0	61.8 x 25.2
20 x 2	202A	116.0 x 37.0	85.0 x 19.8
20 x 2	202B	122.0 x 44.0	99.0 x 24.0
20 x 4	204A	98.0 x 60.0	76.0 x 25.2
20 x 4	204B	98.0 x 60.0	76.0 x 25.2
24 x 2	242A	118.0 x 36.0	93.5 x 15.8
40 x 2	402A	182.0 x 33.5	154.5 x 15.8

Displaytech offers a wide variety of standard display products to meet the requirements of your specific application. From monochrome graphic displays to segmented TN LCDs, Displaytech has many standard products that are commercially available off the shelf and suitable for most industrial, medical and consumer products.

Each of the standard products is unique due to the display technology, diagonal size or integrated display controller. To simplify your search for the perfect display, Displaytech provides all documentation relevant to each LCD module on the specific product page. Next to each product you will find the following items: data sheets for both the display and the integrated driver IC.

















LCD Standard Modules

Passive LCD Modules from Displaytech

Dots / Diagonal Size	Model Number	Module Size W x H [mm]	View. Area W x H [mm]
122 x 32	32122A	65.6 x 29.2	54.8 x 19.1
122 x 32	32122B	56.1 x 29.2	49.1 x 19.0
128 x 32	32128A	41.3 x 19.7	36.1 x 9.9
160 x 32	32160A	100.0 x 38.8	80.0 x 20.5
128 x 64	64128K	58.2 x 41.7	50.0 x 25.0
128 x 64	64128KX	58.2 x 41.7	50.0 x 25.0
128 x 64	64128L	68.8 x 49.2	60.6 x 33.1
128 x 64	64128LX	68.8 x 49.2	60.6 x 33.1
128 x 64	64128M	77.4 x 52.4	70.0 x 40.0
128 x 64	64128MX	77.4 x 52.4	70.0 x 40.0
128 x 64	64128N	74.0 x 41.7	50.0 x 25.0
128 x 64	64128P	93.0 x 70.0	70.7 x 38.8
128 x 64	64128Q	75.0 x 52.7	60.0 x 32.5
240 x 64	64240B	180.0 x 65.0	132.6 x 39.0
240 x 64	64240C	144.9 x 56.4	132.6 x 39.0
320 x 240 3.9" QVGA	240320E	91.5 x 70.5	80.55 x 61.1
320 x 240	240320FP	91.4 x 109.7	100.0 x 76.0
320 x 240 4.7" QVGA	240320G	109.7 x 91.4	100.0 x 76.0
320 x 240 3.9" QVGA	240320H	9.0 x 70.5	80.5 x 61.1
320 x 240	240320JP	70.5 x 91.5	61.1 x 80.55
240 x 128	128240A	144.0 x 104.0	114.0 x 64.0
240 x 128	128240C	77.4 x 52.4	70.0 x 35.0
240 x 128	128240D	98.7 x 67.7	92.0 x 53.0

Displaytech offers a full line of monochrome COG and graphic LCD modules with or without your choice of backlight. Our selection of 128x64, 128x32, 128x240 and 240x64 graphic FSTN LCD modules are our most popular! The popularity of these displays allows Displaytech to offer highly competitive pricing and flexible stocking options.



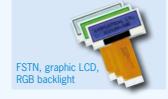








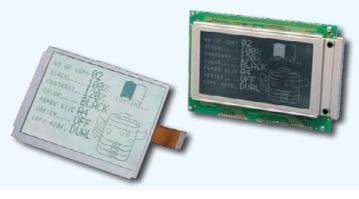








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Custom Design LCD Modules

Custom Design LCD Modules

Customized displays are manufactured according to the specification of our customers. Depending up on the size of the LCD panel and the LCD technology a reasonable minimum order quantity is required.

Module Technologies

Rutronik's partners are implementing a variety of integrated circuit mounting techniques in designs of printed circuit boards used with standard and custom made liquid crystal modules. The company has a full production line for incorporating surface mount technology (SMT), chip on board (COB), tape automated bonding (TAB) and flexible print circuit (FPC). TIANMA contributes solutions to the markets burgeoning demand for chip on glass (COG) technology.

Field Sequential Color (FSC)

With the new FSC-Technology there is no need to insert color filters to portray the colored Icons. In a FSC module a conventional TN-Cell is combined with a RGB Backlight. The 3 colors of the LED Backlight are sequentially switched on.

The frequency of the backlight is synchronous with the frequency of the display segments. As a result you can show up to 8 different colors (black, blue, green, cyan, red, magenta, yellow or white).

Main Advantages of FSC:

- No need of color filters
- Low power consumption
- LCD glass is very economical due to the TN COG technology
- No need of high-end microprocessors

Vertical Alignment

With the Vertical Alignment technology the Liquid Crystal molecules are perpendicular. Vertical Alignment leads to a very dark background and wide viewing angle. Suitable for low and medium information content, automotive, industrial and medical applications.

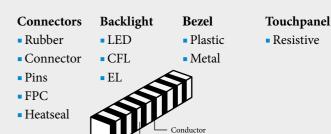
Main Advantages of Vertical Alignment:

- Super black background
- Super high contrast ratio
- Suitable for all kinds of color backlight and white backlight
- Super wide viewing angle • Wide temperature range (-30 °C to 85 °C)

Display Accessories

Rutronik is also able to supply different accessories for your LCDs from selected suppliers, as well as integration of turn key components.

It is possible to add other components like keys, LED or special connectors to a custom design LCD module. With these options Rutronik and its partners can offer the complete solution to customers.



Customized displays are manufactured according to the specification of our customers. Depending upon the size of the LCD panel and LCD technology a reasonable minimum order quantity is required. Our team will consult you with the most fitting supplier for your customized LCD project. We will support you for the whole project-life-time, beginning from the first drawings up to the first samples producion and final mass producion.













Visual Solutions



From commercial displays for digital signage, through to interactive displays for a true pen-on-paper experience, Sharp has a visual solution for every need. Our professional display solutions and video walls are ideal for any environment where clear communication of complex information is essential. Our large format display will get your message across in crowded and busy locations such as shopping malls and transport hubs. And for smaller spaces, we have a range of best-in-class visual business solutions with sizes starting from 32". Whatever your application, need or environment, you'll find a digital display to suit in our range of visual solutions.



PN-40TC1

- BIG PAD for Huddle Office Meeting Spaces and Interactive Retail Signage
- 40" (100.33 cm) size with 1920 x 1080 pixels
- Fast and Responsive PCAP Capacitive 10 point Touch - up to 4 users
- Mini OPS Slot for flexible enhancement
- Sharp Pen Software for intuitive writing, drawing and annotation
- Sharp Touch Viewing Software for organising collaboration data
- Sharp Display Connect for latest BYOD wireless collaboration



Windows Collaboration Display

- Certified for Skype for Business and supported by Microsoft teams
- Integrated microphone, speakers and high-quality camera
- Seamless operation and conferencing with Microsoft Office 365
- Fast 'Plug and play' with single 8 m USB-C connector
- Brilliant eye-catching 4K image content
- Elegant edge to edge highly responsive PCAP 10-point touch
- Smart building management using the data from the IoT sensor hub



PN-86HC1

- 4K BIG PAD for Education, Training and Meeting Rooms
- 86" (217.4 cm) size with 3840 x 2160 pixels
- Fast Infrared (IR) 20 point touch
- Two built-in (10W) stereo loudspeakers which clearly and effectively fill larger rooms
- Integrated SoC Controller player for PC-less Whiteboarding and Media playback
- OPS slot for optional function enhancement

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- Provides a natural 'Pen-on-Paper' experience using a passive pen or finger
- Intuitive control with full bezel button controls and on screen touch menu

Professional Monitors



Our innovative choice of professional smart displays ranges from a conveniently-sized 40" right through to our attention-grabbing 90" large format display. You can bring content to life with our 8K resolution display and see fine details clearly with our Ultra High Definition (UHD) 4K resolution displays. Even our standard High Definition (HD) displays will help your business communicate easily and colleagues to collaborate effectively. We have a solution to suit every application including retail stores, design studios, public spaces, transport hubs, corporate buildings, meetings rooms and more!



PN-R706

- 70" (176.6 cm) display for professional 24/7 signage
- 1920 x 1080 pixels with 700 cd/m²
- Flexible installation with Mini-OPS extension slot
- Contrast 5,000:1
- LED, Edge Lit
- Slim Bezel design with Speakers 10 W + 10 W
- Portrait, Landscape, Face-Up installation support
- Sharp UV²A Display Technology



PN-M501

- 50" (125.7 cm) display for professional 24/7 signage
- 1920 x 1080 pixels with 450 cd/m²
- Powerful and flexible stand-alone operation with embedded Android SoC
- Flexible performance upgrade with Mini-OPS Extension Slot
- · Portrait, Landscape, Face-Up and Face-Down installation support
- Slim Bezel Design with speakers 7 W + 7 W
- Sharp e-Signage S player pre-installed on Android SoC



PN-HW861

- Make a bigger impact with the 86" display
- Showcase images and video in detail with 4K Ultra HD resolution (3840 x 2160 pixels)
- Enhanced and true representation of colour
- Continous display of content during business hours 16/7
- · Show and hear content easily with integrated 4K USB media player and speakers
- Latest HDMI connectivity for 4 K at 60 Hz
- Slim, sleek and elegant design to suit any setting
- Flexible installation in portrait and landscape











Appealing to All Senses **EPSON**EXCEED YOUR VISION **DXODES** BYD **BOSCH EVERLIGHT OSRAM** Melexis muRata **OMRON (infineon** JRO LITEON

SENSIRION THE SENSOR COMPANY life.augmented &TDK TOSHIBA

Rutronik – THE Sensor Distributor

This is our self-conception when it comes to sensors. An industry leading sensor portfolio combined by state of the art products and an exemplified solution selling approach makes it easy for you to realize your sensing application. Let's go and appeal to all senses.

Sensor Products	Bosch AE	Bosch Sensortec	BYD	Comus	Diodes	Epson	Everlight	Infineon	LiteOn	Melexis	Murata	NJRC	Omro	on Osr	am P	anasonic	Rohm	Sensirion	ST	TDK Micronas	Toshiba	Vishay	Sensor Products
MEMS		Sensortec																		Wilcronas			MEMS
Absolute Orientation																							Absolute Orientation
Acceleration	A																		A				Acceleration
eCompass																			7				eCompass
Gyroscope	A I										1								A				Gyroscope
MU (Acceleration + Gyro)	A	_																	Λ Ι				IMU (Acceleration + Gyro)
Microphone	Λ Ι																						Microphone
Environmental				·							· · · · · · · · · · · · · · · · · · ·												Environmental
Air-Flow																							Air-Flow
Gas											1												Gas
Humidity																		A					Humidity
Pressure	A							AII		А	1												Pressure
Temperature																						AII	Temperature
Particulate Matter																							Particulate Matter
Optical																							Optical
Ambient Light												A I		А	1							AII	Ambient Light
Camera Modules																							Camera Modules
Far Infrared/Infrared										AII		A		I A								AII	Far Infrared / Infrared
Fingerprint																							Fingerprint
mage			1																				Image
Proximity				1			1	AI	1	AI				I A	1				A			A	Proximity
Radar								A															Radar
Reflective												A		I A									Reflective
Time-of-flight								A		A									A				Time-of-flight
Transmissive														I A								AII	Transmissive
Ultrasonic											1												Ultrasonio
Magnetic																							Magnetic
Geomagnetic																			1				Geomagnetic
non programmab	ble				1					A										A			non programmable
Hall Linear programmable								AII		A I										A I			programmable Hall Linear
single					A			A		A I					A	A I	A			A I	A		single
Hall Switch dual					1			A I		A I													dual Hall Switch
speed								AI		A													speed
programmable										A										A I			programmable
switch											1												switch
Magnetoresistive 3D switch											1												3D switch Magnetoresistive
iinear								AII															ililear
2D sensor								AI												A I			2D sensor
Multiaxis Hall								AI		AII										A I			Multiaxis Hall
TMR								A												A			TMR
Current																							Current
Hall based ICs										AII										A			Hall based ICs
Sensor Modules																							Sensor Modules

Panasonic













A Automotive qualified preferred



Motion Sensors

Bosch Sensortec – At the Core of Everyday Life

Our portfolio of motion sensors includes products for motion, orientation and gesture detection. Motion sensors are designed for several consumer electronics and IoT applications in the field of smartphones, wearables, smart home, drones, toys, virtual and augmented reality, gaming, as well as industrial applications.

Accelerometers

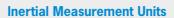
Part Number	Sensing Range (g)	Sensing Axis	Sensitivity (LSB/g)	Output Interface	Bandwidths (Hz)	Supply Voltage (V) Supply Current (mA)		Operating Temp. (°C)	Package Type/ Size (mm)
BMA253	±2, ±4, ±8, ±16	X, Y, Z	1024, 512, 256, 128	SPI, I ² C, 2 digital interrupt pins	8 to 1000	V _{DD} : 1.62 to 3.6 V _{DDIO} : 1.2 to 3.6	6.5 μA @40 Hz data rate (low-power mode) 130 μA @2kHz data rate (full operation)	-40 to +85	2.0x2.0x0.95
BMA280	±2, ±4, ±8, ±16	X, Y, Z	4096, 2048, 1024, 512	SPI, I ² C, 2 digital interrupt pins	8 to 500	V _{DD} : 1.62 to 3.6 V _{DDIO} : 1.2 to 3.6	6.5 μA @40 Hz data rate (low-power mode) 130μA @2kHz data rate (full operation)	-40 to +85	2.0x2.0x0.95
BMA400	±2, ±4, ±8, ±16	X, Y, Z	1024, 512, 256, 128	SPI, I ² C, 2 digital interrupt pins	0.24x0DR or 0.48x0DR (ODR from 12.5800)	V _{DD} : 1.71 to 3.6 V _{DDIO} : 1.2 to 3.6	14 μA (max. performance) < 8 μA (typical use case) < 4 μA Independant of ODR (lower power mode)	-40 to +85	2.0x2.0x0.95
BMA423	±2, ±4, ±8, ±16	X, Y, Z	1024, 512, 256, 128	SPI, I ² C, 2 digital interrupt pins	1.5 to 1600	V _{DD} : 1.62 to 3.6 V _{DDIO} : 1.2 to 3.6	13 μA @50 Hz data rate (low-power mode) 150 μA (full operation)	-40 to +85	2.0x2.0x0.95
BMA456	±2, ±4, ±8, ±16	X, Y, Z	16384, 8192, 4096, 2048	SPI, I ² C, 2 digital interrupt pins	5 to 684 (ODR: 0.8 to 1600)	V _{DD} : 1.62 to 3.6 V _{DDIO} : 1.2 to 3.6	13 μA @50 Hz data rate (low-power mode) 150 μA (full operation)	-40 to +85	2.0x2.0x0.65

Gyroscopes

Part Number	Sensing Range (°/s)	Sensing Axis	Output Interface	Zero Rate Output (°/s)	Turn On Time (ms)	Supply Voltage (V)	Supply Current (mA)	Operating Temp. (°C)	Package Type/ Size (mm)
BMG250	±125, ±250, ±500, ±1000, ±2000	X, Y, Z	for primary UI IF: I ^o C up to 1Mhz 3w/4w SPI 2x digital interrupts for secondary OIS/EIS IF: 3w SPI up to 10MHz	±3	Suspend to normal mode 55 ms (typical) Fast start-up to normal mode 10 ms (typical)	V _{DDIO} 1.2 to 3.6 V _{DD} 1.7 to 3.6	Full operation 850 μA Suspend mode 3 μA Fast start-up 500 μA	-40 to +85	2.5x3.0x0.8



Sensing our world



Part Number	Output Interface	Sensing Range	Sensing Axis	Supply Voltage (V)	Supply Current (mA)	Operating Temp. (°C)	Package Type/ Size (mm)
BMI055	I ² C, SPI, 4x digital interrupts	(A): \pm 2 g, \pm 4 g, \pm 8 g, \pm 16 g (G): \pm 125°/s, \pm 250°/s, \pm 500°/s, \pm 1000°/s, \pm 2000°/s	6-axis	V _{DD} : 2.4 to 3.6 V _{DDIO} : 1.2 to 3.6	Full operation: 5.15 mA Suspend mode: 6 µA	-40 to +85	3.0x4.5x0.95
BMI085	I ² C, SPI, 4x digital interrupts	(A): ± 2 g, ± 4 g, ± 8 g, ± 16 g (G): $\pm 125^{\circ}/s$, $\pm 250^{\circ}/s$, $\pm 500^{\circ}/s$, $\pm 1000^{\circ}/s$, $\pm 2000^{\circ}/s$	6-axis	V _{DD} : 2.4 to 3.6 V _{DDIO} : 1.2 to 3.6	5.15 mA	-40 to +85	3.0x4.5x0.95
BMI088	I ² C, SPI, 4x digital interrupts	(A): \pm 3 g, \pm 6 g, \pm 12 g, \pm 24 g (G): \pm 125°/s, \pm 250°/s, \pm 500°/s, \pm 1000°/s, \pm 2000°/s	6-axis	V _{DD} : 2.4 to 3.6 V _{DDIO} : 1.2 to 3.6	5.15 mA	-40 to +85	3.0x4.5x0.95
BMI160**	I ² C, SPI, 4x digital interrupts	(A): \pm 2 g, \pm 4 g, \pm 8 g, \pm 16 g (G): \pm 125°/s, \pm 250°/s, \pm 500°/s, \pm 1000°/s, \pm 2000°/s	6-axis	V _{DD} : 1.71 to 3.6 V _{DDIO} : 1.2 to 3.6	Full operation: 950 μA Suspend mode: 3 μA	-40 to +85	2.5x3.0x0.8
BMI270	SPI, 2x digital interrupts	"(A): \pm 2 g, \pm 4 g, \pm 8 g, \pm 16 g (G): \pm 125°/s, \pm 250°/s, \pm 500°/s, \pm 1000°/s, \pm 2000°/s"	6-axis	V _{DD} : 1.7 to 3.6 V _{DDIO} : 1.2 to 3.6	Full operation: 685 μA Suspend mode: 5 μA	-40 to +85	2.5x3.0x0.9

Absolute Orientation Sensors

Part Number	Output Inter- face	Linear Acceleration Full Scale (g)	Angular Rate Full Scale (dps)	Magnetic Full Scale Range (gauss)	Resolution	Supply Voltage (V)	Supply Current (Acc+Mag+Gyro) (mA)	Operating Temperature (°C)	Package Type/ Size (mm)
BMX055	I ² C, SPI	(A): ± 2, ± 4, ± 8, ± 16	(G): ± 125°/s, ± 250°/s, ± 500°/s, ± 1000°/s, ± 2000°/s	±1300 μT (x, y axis) ±2500 μT (z axis)	(A): 0.98 mg (G): 0.004 °/s (M): 0.3 μT	V _{DD} : 2.4 to 3.6 V _{DDIO} : 2.4 to 3.6	Gyro @ full operation: 5 mA Acc @ full operation: 130 µA Acc @ wake-up mode: < 1 0µA Magnet sensor @ 10Hz 0DR: 0.5 mA	-40 to +85	3.0x4.5x0.95
BMX160	I ² C, SPI	(A): ± 2, ± 4, ± 8, ± 16	(G): ± 125°/s, ± 250°/s, ± 500°/s, ± 1000°/s, ± 2000°/s	±1300 μT (x, y axis) ±2500 μT (z axis)	(A): 0.061mg (G): 0.004°/s (M): 0.3 μT	V _{DD} : 1.71 to 3.6 V _{DDIO} : 1.2 to 3.6	Gyro @ full operation: 850 μA Gyro + Acc + Geomag: 1585 μA Geomag @ full operation: 660 μA Acc @ full operation: 180 μA Suspend mode: 5 μA Significant motion: 30 μA Step detector: 30 μA	-40 to +85	2.5x3.0x0.95

Magnetometers

Part Number	Sensing Range (gauss)	Sensing Axis	Sensiti- vity (%/K)	Output Interface	Output Noise (mgauss RMS)	Supply Voltage (V)	Supply Current (µA Max)	Operating Temperature (°C)	Package Type/ Size (mm)
BMM150	±13 (x,y-axis) ±25 (z-axis)	X, Y and Z axis	± 0.01	I ² C and SPI (2 interrupt pins)	x, y-axis: 1.0 μT z- axis: 1.4 μT	V _{DD} : 1.62 to 3.6 V _{DDIO} : 1.2 to 3.6	170 μA (low-power preset) 500 μA (normal mode)	-40 to +85	CSWLP- (12 pin) 1.56x1.56x0.6 0.4 mm diagonal ball pitch

⁽A): Accelerometer, (G): Gyro, (M): Magnetometer







Sensing our world

^{**} Queexo FingerSense Compatible



Bosch Sensortec – At the Core of Everyday Life **Smart Sensors**

Our portfolio of smart sensors is specifically designed for always-on sensor applications in smartphones, wearables and tracking devices. It offers flexible, low-power solutions for motion sensing and sensor data processing.



Part Number	Integrated Processor	Software Library	Software	Output Interface	Sensing Range (g)	Bandwidth Typ (Hz)	Current Consumption (mA Typ. @100 Hz ODR)	Supply Voltage (V)	Package Type / Size (mm)
BN0055	32 bit cortex M0+ microcontroller	BSX 3.0 full fusion	n/a	I ² C, UART, HID-I ² C	± 2 g, ± 4 g, ± 8 g, ± 16 g	BSX3 (Fusion) output data rate: 1000, 500, 250, 125, 63, 31, 16, 8	Suspend mode: 40 µA 9DOF @ 100 Hz Output data rate: 12.3 mA	V _{DD} 2.4 to 3.6 V _{DDIO} : 1.7 to 3.6	3.8x5.2x1.13
BMF055	33 bit cortex M0+ microcontroller, 256kB flash memory and 32kB SRAM memory	BSX fusion lite as additional lib. custom programmable.	n/a	I ² C, UART, HID-I ² C	± 2 g, ± 4 g, ± 8 g, ± 16 g	Depends on the custom specific sensor fusion	Depends on the custom specific sensor fusion	V _{DD} 2.4 to 3.6 V _{DDIO} : 1.7 to 3.6	3.8x5.2x1.13
BHA250	32 bit floating-point ARC EM4 MCU running @ 10 MHz 1.6 DMIPS/MHz performance, 3.41 CoreMarks/MHz 96 kByte ROM, 48 kByte RAM shared RAM for FIFO, features & extensions optimized for ultra-low-power sensor data fusion	BSX 3.0 fusion activity recognition, gesture recognition step detector, step counter	n/a	I ² C up to 3.4 MBit/s 3xGPIO, 1xHost-INT	± 2 g, ± 4 g, ± 8 g, ± 16 g	BSX3 (Fusion) output data rate: 200, 100, 50, 25, 12.5	 eCompass @ 100 Hz ODR: 630 μA Hub+Acc @ 100 Hz ODR: 430 μA Activity recognition: 200 μA Significant motion: 100 μA Step detector: 100 μA Suspend mode: 11 μA 	V _{DD} : 1.71 to 3.6 V _{DDIO} : 1.2 to 3.6	2.2x2.2x0.95
BHA260 (upcoming)	32 bit floating-point ARC EM4 CPU with (up to 3.6 CoreMark/MHz) 256 kByte SRAM, 144 kByte ROM	BSX 4.0 fusion activity recognition, gesture recognition step detector, step counter custom programmable	n/a	 Host interface configurable as SPI or I²C 2 master interfaces (1 selectable SPI/I²C and 1 I²C) Up to 12 GPIOs 	± 2 g, ± 4 g, ± 8 g, ± 16 g	BSX4 (Fusion) output data rate: 800, 400, 200, 100, 50, 25, 12.5, 6.25, 3.125, 1.5625	Fuser2 (running CoreMark) • long run mode (20 MHz): 950 µA • turbo mode (50 MHz): 2.8 mA Sensor algorithm oepration (incl. Sensor) • significant motion: 32 µA • step counter: 46 µA • activity recognition: 77 µA • Standby current: 8 µA	1.8	2.7x2.6x0.8
ВН1160	32 bit floating-point ARC EM4 MCU running @ 10 MHz 96 kByte ROM, 48 kByte RAM	BSX 3.0 fusion activity recognition, gesture recognition step detector, step counter	n/a	I ² C up to 3.4 MBit/s 3xGPIO, 1xHost-INT	(A): ± 2 g, ± 4 g, ± 8 g, ± 16 g (G): ± 125°/s, ± 250°/s, ± 500°/s, ± 1000°/s, ± 2000°/s	BSX3 (Fusion) output data rate: 200, 100, 50, 25, 12.5	• full 6DoF PDR: 1.3 mA • full 6DoF Fusion @ 100 Hz ODR: 1.2 mA • full 9DoF Fusion @ 100 Hz ODR: 1.3 mA • significant motion: 128 μA • step detector: 131 μA • suspend mode: 11 μA	V _{DD} : 1.71 to 3.6 V _{DDIO} : 1.2 to 3.6	3.0x3.0x0.95
BHI260 (upcoming)	32 bit floating-point ARC EM4 CPU with (up to 3.6 CoreMark/MHz) 256 kByte SRAM, 144 kByte ROM	BSX 4.0 fusion activity recognition, gesture recognition step detector, step counter custom programmable	n/a	Host interface configurable as SPI or I ² C master interfaces (selectable out of 2xSPI master and 2xI ² C master) Up to 25 GPIOs	(A): ± 2 g, ± 4 g, ± 8 g, ± 16 g (G): ± 125°/s, ± 250°/s, ± 500°/s, ± 1000°/s, ± 2000°/s	BSX4 (Fusion) output data rate: 800, 400, 200, 100, 50, 25, 12.5, 6.25, 3.125, 1.5625	Fuser2 (running COreMark) Iong run mode (20 MHz): 950 µA turbo mode (50 MHz): 2.8 mA Sensor Fusion (Hub+IMU) operation (calculating Game Rotation Vector) 800 Hz ODR: 1.2 mA 100 Hz ODR: 1.0 mA Standby current: 8 µA	1.8	4.1x3.6x0.83

(A): Accelerometer, (G): Gyro, (M): Magnetometer

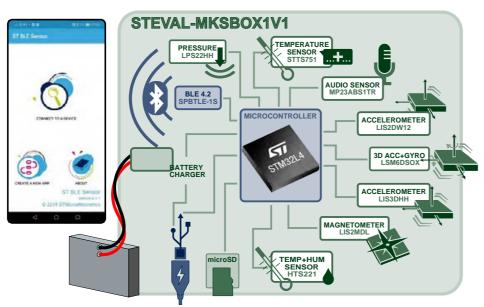












SensorTile.Box STEVAL-MKSBOX1V1



The STEVAL-MKSBOX1V1 (SensorTile.box) is a ready-to-use box kit with wireless IoT and wearable sensor platform to help you use and develop apps based on remote motion and environmental sensor data, regardless of your level of expertise.

The SensorTile.Box board fits into a small plastic box with a long-life rechargeable battery, and the ST BLE sensor app on your smartphone connects via bluetooth to the board and allows you to immediately begin using the wide range of default IoT and wearable sensor applications.

In expert mode, you can build customs apps from your selection of SensorTile.Box sensors, operating parameters, data and output types, and special functions and algorithms available. This multi sensor kit therefore allows you to design wireless IoT and wearable sensor applications quickly and easily, without performing any programming.

SensorTile.Box includes a firmware programming and debugging interface that allows professional developers to engage in more complex firmware code development using the STM32 open development environment (STM32 ODE), which includes a sensing AI function pack with neural network libraries.

Description	Туре
Low-voltage local digital temperature sensor	STTS751
iNEMO 6DoF inertial module	LSM6DSOX
3-axis MEMS accelerometer	LIS2DW12
3-axis digital output accelerometer	LIS3DHH
Digital 3-axis magnetometer	LIS2MDL
Digital nano pressure sensor	LPS22HH
MEMS analog bottomport microphone	MP23ABS1
Digital sensor for relative humidity and temperature	HTS221
Bluetooth smart connectivity v4.2	(SPBTLE-1S)
Programming and debugging interface for professional firmware development	Other

You can download the free ST BLE sensor app on your smartphone and almost immediately begin commanding the board with any of the following applications with ST high-precision sensors on the board:

■ Barometer app

allows you to configure the STTS751 temperature, LPS22HH pressure and HTS221. Humidity sensors to monitor environmental information in real time on your smartphone, or collect and graph the data against time on a plot screen.

Compass and level app

allows you to configure the LSM6DSOX accelerometer and gyroscope and LIS2MDL magnetometer sensors to monitor real time bearing and inclination sensor feedback data and plot the information over time.

Step counter app

allows you to configure the LSM6DSOX accelerometer to monitor you walking and running speeds and plot the information over time.

Baby crying app

allows you to configure the MP23ABS1 microphone sensor to detect human voice events such as a baby crying and send an alert to your smartphone as well as activate a LED on the sensor board.

Vibration monitoring app

allows you to configure the LSM6DSOX accelerometer and set up your board to "learn" the normal operation of motorized domestic or industrial equipment, and then monitor the same equipment for anomalous vibration for predictive maintenance purposes.

Data recorder and vehicle/goods tracking app

allows you to select and configure appropriate environmental and motion sensors to log the transportation and storage conditions that selected merchandise is subject to over time.

Compensated magnetometer app

allows you to build additional apps from the magnetometer output and a sensor fusion algorithm to compensate for disturbances from external magnetic-fields



MEMS Sensors for Smart Industry 4.0

High-Performance & Ultra-Low-Power Sensing Solutions

ST's broad range of sensors includes 3-axis miniaturized accelerometers, 6-axis inertial modules, magnetometers/eCompass and pressure sensors. Scalable modules with up to 6-axis (3-axis accelerometer + 3-axis gyroscope or 3-axis magnetic, 3-axis magnetic, 1 pressure or temperature) with drivers as well as ST's open.

Key Applications

- Predictive maintenance and early failure detection
- Industrial IoT and connected devices
- Robotics, automation and drones
- Power saving and motion-activated functions
- Inertial navigational systems and motion tracking
- Antenna and platform pointing, leveling and stabilization
- Precision inclinometer and leveling instruments
- Appliances
- Optical image and lens stabilization
- Anti-tampering in smart meters
- Positional and distance sensor
- Presence detection, magnetic switch
- Variable magnetic-field monitoring
- Asset and parcel tracking, monitoring and shock detection and logging
 Building and structure monitoring

Benefits of 10-Year Product Longevity Commitment Program



Part No.	Description	Key Parameters	Package
IISDWB	Ultra-wide bandwidth, low-noise 3-axis digital accelerometer	• User-selectable full-scale: $\pm 2/\pm 4/\pm 8/\pm 16$ g • Ultra-wide and flat frequency response range: from dc to 5 kHz ± 3 dB point) • Ultra-low-noise density: down to 90 μ g/ \sqrt{Hz} in 3-axis mode /IlS3DWB 65 μ g/ \sqrt{Hz} in singleaxis mode	LGA-14L 2.5x3x0.83 mm
IIS2DH	3-axis accelerometer with digital output	3 μA consumption at 10Hz ODR; 185 μA consumption at wide bandwidth and ODR 5.3 Khz	LGA-12L 2.0x2.0x1 mm
IIS2DLPC	Ultra-low-power high-performance three-axis linear accelerometer with digital I ² C/SPI output interface	 ±2g/±4g/±8g/±16g full scale Ultra-low power consumption: 50 nA in power-down mode, below 1 μA in active low-power mode, 120 μA in high-performance mode 10000 g high shock survivability 	LGA 12L 2x2x0.7 mm
ISM330DHCX	System-in-package featuring a high-performance 3D digital accelerometer and 3D digital gyroscope tailored for Industry 4.0 applications.	 accelerometer with selectable full scale: ±2/±4/±8/±16 g 3D gyroscope with extended selectable full scale: ±125/±250/±500/±1000/±2000/±4000 dps Machine learning core and smart embedded functions and interrupts: tilt detection, free-fall, wake-up, 6D/4D orientation, click and double-click and high shock survivability 	LGA 14L 2.5X3X.83 mm
ISM330DLC	iNEMO inertial module: 3-axis accelerometer and 3-axis gyroscope	Rate noise density in high-performance mode (HPM) Gyroscope: 3.8 mdps/\day{Hz; Accelerometer: 90 ug/\day{Hz}	LGA-14L 2.5x3x0.83 mm
IIS3DHHC	High-performance 3-axis inclinometer with digital output	Meas. range: FS \pm 2.5 g offset change with temp <0.4 mg/C Noise density: 45 μ g/ \sqrt{Hz}	CC LGA-16 5x5x1.7 mm Ceramic
IIS2MDC	High-accuracy, ultra-low-power, 3-axis: Digital output magnetometer	± 50 gauss magnetic dynamic range. 3 magnetic-field channels noise 3mGauss (rms)	LGA-12 2.0x2.0x0.7 mm
ISM303DAC	eCompass 3-axis magnetometer+3axis accelerometer High-performance, low-power, compact	3-axis mag. FS ± 50 Ga and 3-axis axl FS ± 16 g High-resolution, high-frequency and low-power modes	LGA-12L 2.0x2.0x1 mm











iNEMO-Inertial Modules



iNEMO inertial modules are inertial measurement units (IMU) which integrate complementary types of sensors to offer more compact, robust, and easy-to-assemble solutions compared to discrete MEMS products.

iNEMO System-in-packages (SiP) combine accelerometer, gyroscope and magnetometer in a monolithic 6-axis or 9-axis solution. The integration of multiple sensor outputs bring motion sensing systems to the level of accuracy required for the most demanding applications, such as enhanced gesture recognition, gaming, augmented reality, indoor navigation and localization-based services. To further save power at system level, ST have designed iNEMO inertial modules with an embedded machine learning core. The MLC runs an in-sensor classification engine, offloading the main processor to either run different tasks or to be put to sleep and save power, while the built-in sensors identify motion data.

LSM6DSOX - Motion Sensor with Machine Learning for High-Accuracy, Battery-Friendly Activity Tracking

The LSM6DSOX is a system-inpackage IMU featuring a 3D digital accelerometer and a 3D digital gyroscope boosting performance and enabling always-on low-power features for an optimal motion estimation and user experience.

The LSM6DSOX contains a decision-tree and a machine learning core to classify motion data based on known patterns. Relieving this first stage of activity tracking from the main processor saves energy and accelerates motion-based apps such as fitness logging, wellness monitoring, personal navigation and fall detection.

Features

- Machine learning core (MLC) for advanced motion recognition and classification
- Finite state machine (FSM) for up to 16 custom movement recognition in low-power mode
- Dedicated OIS or control core with AUX interface
- I3C interface
- Data acquisition from up to 4 external sensors (sensor hub)
- High-accuracy, HW configurable, step counter 2.0
- Up to 9kB FIFO sensor data in compressed mode (3.5 kB uncompressed)

Applications

- Motion tracking and gesture detection
- Sensor hub
- Indoor navigation
- IoT and connected devices
- Smart power saving for battery-operated devices
- EIS and OIS for camera applications:
- Forklift/robots and machine control
- Vibration monitoring and compensation

Motion Sensors

Accelerometers

ST's state-of-the-art MEMS accelerometers include analog and digital sensors featuring up to ±400 g acceleration full scale and from 1.71 to 3.6 V supply voltage. Accelerometers have advanced power-saving features that make them suitable for ultra-low-power applications. These features include low-power mode, auto wake-up function and a FIFO buffer that can be used to store data, thus reducing the host processor loading and system power consumption. The small size and embedded features of ST's accelerometers make them an ideal choice for wearable applications and where long battery life is required.



Features

- Low-power consumption and smart ultra-low-power operating modes including always-on
- High-resolution: accuracy and stability
- Smart embedded features for less power hungry systems
- Ultra compact devices in packages smaller than 4 mm³
- Selectable full-scale up to 16 g
- Advanced digital features
- Pin-to-pin compatible product family



Part Number	Description	Power cons. in PD Low-Power Mode Normal Mode (μΑ)	Key Parameters	Package Size (mm)
LIS2DW12	3-axis accelerometer, 12 to 14 bit resolution	0.05 0.38 @1.6Hz, 3 / 16 @50Hz 120 in HPM @50Hz	32-level, FIFO, self test, temp sensor, high-resolution very low-power	LGA-12, 2x2x0.7
LIS2DH12	3-axis accelerometer, 8 to 12 bit resolution	0.5 2 @1Hz, 6 @ 50Hz, 11 @50Hz	32-level, FIFO, self test, temp sensor, 12-bit resolution, low-power, cost-effective	LGA-12, 2x2x1
LIS2DE12	3-axis accelerometer, 8 bit resolution	0.5 2 @1Hz, 6 @50Hz	32-level, FIFO, self test, temp sensor, 8 bit resolution, low-power	LGA-12, 2x2x1

Digital Compasses

ST's digital compasses include combo solutions, with an accelerometer and magnetic sensor integrated in a single LGA package and standalone magnetometer, to give the possibility of designing a solution locating the magnetic sensor in the best position on the board in order to minimize magnetic interference.

Part Number	Full Scale	Noise Density (Typ.)	Package Size (mm)
LSM303AGR	2, ±4, ±8, ±16 g, ±50 gauss	220 μg/√Hz, 3 mgauss	LGA-12, 2x2x1
LSM303AH	±2, ±4, ±8, ±16 g, ±50 gauss	120 μg/√Hz, 3 mgauss	LGA-12, 2x2x1
LIS2MDL	±50 gauss full scale	3 mgauss	LGA-12, 2x2x0.7

Features

- Ultra-compact high-performance magnetometer module
- Wide magnetic sensor dynamic range and ultra-low magnetic offset
- Pin-to-pin compatible product family
- Embedded self test and temp. compensated



,	ney i eatures
l	Ultra-low-power, high-perform., 3D digital accelerator sensor and 3D digital magnetic sensor
l	Ultra-compact, high-perform. e-compass 3D accelerometer and 3D magnetometer module
.7	3-axis magnetometer standalone, power consumption (@ODR=20Hz): 200 μA in high-resolution, 50 μA in low-power & 2 μA in power down

iNEMO® Inertial Modules

iNEMO System-in-packages (SiP) combine accelerometer, gyroscope and magnetometer in a monolithic 6-axis or 9-axis solution. The integration of multiple sensor outputs bring motion sensing systems to the level of accuracy required for the most demanding applications, such as enhanced gesture recognition, gaming, augmented reality, indoor navigation and localization-basd services.

- Always-on 3D accelerometer and 3D gyroscope
- Android M compliant
- Pedometer, step detector and step counter
- Rate noise density 4mdps/ $\sqrt{\text{Hz}}$ (high perf. mode)
- Embedded self test and temperature sensor

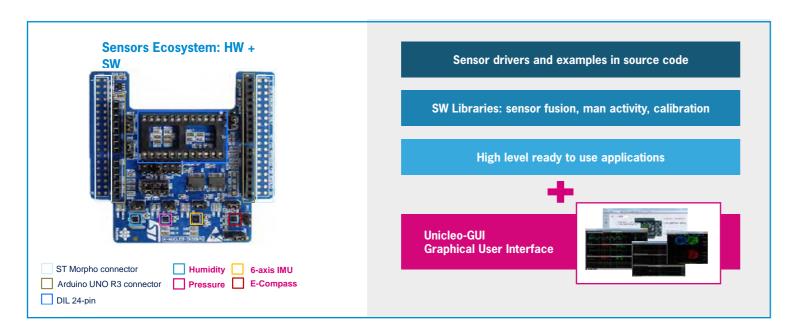
		Common Features	Current Consumpt. (μA)				
Part Number	General Description	 Sensing Axes: X, Y, Z, Yaw, Pitch, Roll Package (mm): VFLGA 2.5X3X0.86 14L Angular Rate Range (°/s) typ: 2000 Range (g) typ: ±2; ±4; ±8; ±16 Supply Voltage (V) min.: 1.71 / typ.: 1.8 to 3.6 	Normal Mode) typ	High-Perfor- mance Mode typ	Low-Power Mode typ	Power Down Mode) typ	
LSM6DSRX	iNEMO inertial module: 3D accel	erometer and 3D gyroscope with embedded machine learning core.Digital output	700	1200	290	3	
ASM330LHH	Automotive 6-axis inertial modul	e: 3D accelerometer and 3D gyroscope	1300		-	3	
ISM330DHCX	iNEMO inertial module: always-or	-	-	350	100		
LSM6DSL		ent unit (IMU), for smart phones and battery operated IoT, garning, wearable and power and high-accuracy. Digital output	450	650	290	3	
LSM6DS0		ent unit (IMU), with advanced digital function, finite state machine. For battery and consumer electronics. Digital output. Low-power consumption applications		550	26	3	
LSM6DSR	iNEMO inertial module: 3D acce	lerometer and 3D gyroscope. Digital output for high-accurracy applications	700	1200	290	3	
LSM6DSOX		ent unit (IMU), with Machine Learning Core, Finite State Machine and advan- le acceleration range of ±2/±4/±8/±16 g and an angular rate range of 000 dps	-	0.55 mA	-		







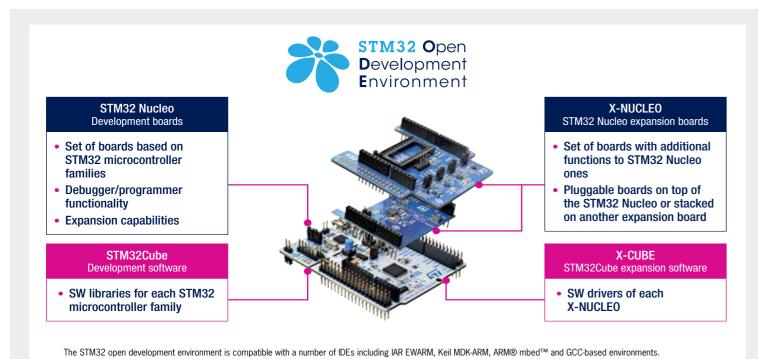




Design Support



ST has a wide product portfolio for wearable applications and provides solution to solve the most complex design challenge: Single product evaluation boards, fast prototyping and development boards, solution evaluation boards and software development tools.



Product Evaluation Boards

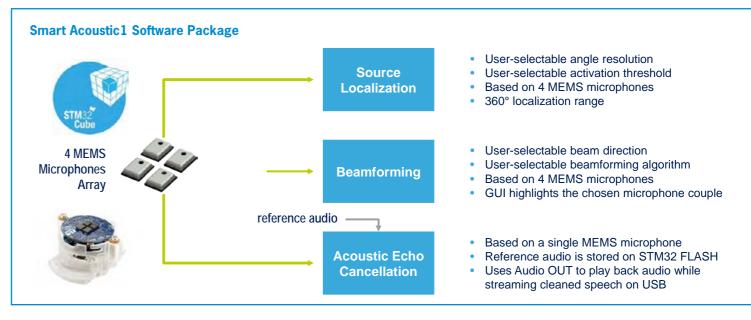
ST proposes a wide range of evaluation boards that may be used to perform a comprehensive evaluation of ST's products reducing your development time. For MEMS and Environmental sensors, ST features the X-NUCLEO-IKS01A3 and X-NUCLEO-IKS02A1 boards which are compatible with the Arduino UNO R3 connector layout. Both boards interface with the STM32 microcontroller via the I²C pin, and it is possible to change the default I²C port. The X-NUCLEO-IKS01A3 is a motion MEMS and environmental sensor evaluation board and feautures motion, humidity, temperature and pressure sensors.

The X-NUCLEO-IKS02A1 is an industrial motion MEMS Sensor expansion board and it embeds industrial motion sensors and the IMP34DT05 digital microphone.

STM32 Open Development Environment

The STM32 open development environment is a fast and affordable way to prototype and develop innovative applications with state-of-art ST components based on the STM32 32-bit micro controller family and a comprehensive set of functions for sensing, connectivity, power, audio, motor control and more.

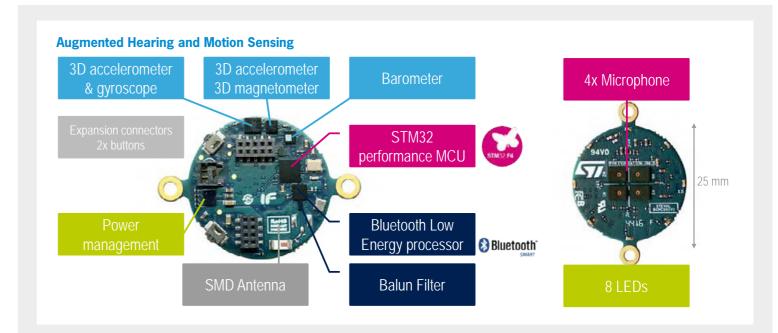
www.rutronik.com/EN



BlueCoin Development Kit



The STEVAL-BCNKT01V1 integrated development and prototyping platform for augmented acoustic and motion sensing for IoT applications builds on the listening and balancing capabilities of the human ear.



MEMS Microphones

Voice control is a wide spreading trend across many portable applications, making the interaction easier, faster and smoother. It enables fashionable designs by reducing the number of button.

Features

- Tiny packages
- Low-power consumption
- High-performance
- Solution to integrate more sensors in a single package



Part Number	General Description	Package	Output Type	Port location	Signal to noise ratio (dB)*	Sensitivity (dBFS)	Frequency response	Power sup- ply rejection ratio	Supply Voltage (V) min	Supply Voltage (V) typ	Supply Voltage (V) max
IMP34DT05	MEMS audio sensor omnidirectio- nal digital microphone for industrial applications	HCLGA 4MM X 3 MM X 1.00 MM MICRO	Digital	Тор		-26 dBFS ±3 dB	20Hz-20Khz	-72	1.6	1.8	3.6
MP23ABS1	High performance MEMS audio sensor single ended analog bottom-port microphone	RHLGA 2.65X3.5X1.08(MAX) MM 4L	Analog	Bottom	64	-38 dBV ±1 dB	20Hz-20Khz	60	1.52	2.75	3.6
MP34DT05-A	MEMS audio sensor omnidirectio- nal digital microphone	HCLGA 4MM X 3 MM X 1.00 MM MICRO	Digital	Тор	64	-26 dBFS ± 3 dB	20Hz-20Khz	-72	1.6	1.8	3.6
MP34DT06J	MEMS audio sensor omnidirectio- nal stereo digital microphone	HCLGA 4MM X 3 MM X 1.00 MM MICRO	Digital	Тор	64	-26 dBFS ± 1 dB	20Hz-20Khz	-72	1.6	1.8	3.6

*A-weighted @ 1 Khz









Our portfolio of environmental sensors includes barometric pressure sensors, as well as integrated environmental sensors. These integrated environmental sensors combine barometric pressure, relative humidity, gas and ambient temperature sensing functions. Environmental sensors are ideally suited for indoor air quality measurement, sport & fitness monitoring, weather forecast, home automation control, internet of things, GPS-enhancement and indoor navigation.

Humidity and Gas

Part Number	Description	Output Interface	Measurement Range	Power Consumption	Supply Voltage (V)	Operating Temperature (°C)	Package Type/ Size (mm)
BME280	The unit combines individual high linearity, high-accuracy sensors for pressure, humidity and temperature.	I²C, SPI	Humidity 0100% rH Pressure 300 1100 hPa Temperature -40 85°C	Sleep mode 0.1 μA 1.8 μA @ 1Hz (H,T) 2.8 μA @Hz (P, T) 3.6 μA @ 1Hz (H, P, T)	V _{DDIO} 1.2 to 3.6V V _{DD} 1.71 to 3.6V	-40 to +85	2.5x2.5x0.93
BME680	The unit integrates for the first time low-power and highly accurate gas, pressure, humidity and temperature sensors in one tiny package.	l²C, SPI	Gas 0 to 500 IAQ (equivalent to 0.2 to 20 mg/m³ TVOC levels) Humidity 0 to 100 % rH Pressure 300 to 1100 hPa Temperature -40 85°C	Sleep mode 0.15 μA 2.1 μA @ 1Hz (H,T) 3.1 μA @ 1Hz (P, T) 3.7 μA @ 1 Hz (H, P, T) 0.09 - 12 mA (P/H/T/Gas) depending on operation mode	V _{DDIO} 1.2 to 3.6V V _{DD} 1.71 to 3.6V	-40 to +85	3.0x3.0x0.93

Barometric Pressure Sensors

Part Number	Pressure Range	Pressure Type	Digital Interface	Supply Voltage (V)	Supply Current (mA)	Operating Temperature (°C)	Package Type/ Size (mm)
BMP280	300 1100 hPa	В	I ² C and SPI	V _{DDIO} : 1.2 to 3.6 V _{DD} : 1.71 to 3.6	2.74 μA @ 1 Hz	-40 to +85	2.0x2.5x0.95
BMP388	300 1250 hPa	В	I ² C and SPI	V _{DDIO} : 1.2 to 3.6 V _{DD} : 1.65 to 3.6	2.7 µA @ 1 Hz	-40 to +85	2.0x2.0x0.75





Digital Barometric Air Pressure Sensor

Infineon's digital barometric air pressure sensors are best choice for enhanced navigation experience, activity level monitoring, gesture recognition and weather monitoring just as well as for mobile applications and wearables.

DPS310

DPS310 provides ultra-high-precision up to ± 5 cm and ± 0.06 hPa relative accuracy. The pressure sensing element is based on a unique capacitive principle, which is totally different from piezoelectric technology employed in most of the pressure sensors available in today's market. The capacitive technology enables high-accuracy during temperature changes, which is important for smartphones, wearable and personal navigation devices.

Target Aplications

- Internet of things
- Wearable electronics e.g. health and sports gadgets
- Indoor navigation floor detection
 e.g. in shopping malls and parking garages
- Outdoor navigation in personal navigation devices
- Dead-reckoning e.g. in tunnels
- Local weather station

Application Benefits

- Ultra-high-precision
- High measurement accuracy over wide pressure and temperature range
- Easy implementation due to compact size
- Low system level energy consumption due to FIFO

DPS422

The DPS422 is a monolithic chip solution and ultra-small critical area (sensitive area) and offers robustness against environment. It is capable of measuring both pressure and temperature. Pressure sensing is carried out using a capacitive sensor element, guaranteeing high-accuracy over temperature. The small 2.0x2.5x0.73 mm package makes the DPS422 ideal for mobile applications and wearable devices

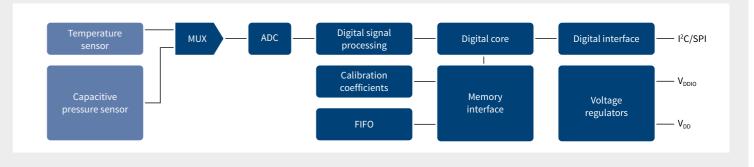
Specifications

Key product features	DPS310 DPS422			
Operating pressure range	3001200 hPa			
Operating temperature range	-40	.85°C		
Pressure level precision	< 0.5 Pa	0.5 Pa		
Temperature accuracy	0.5°	< 0.4°C		
Pressure temperature sensitivity	0.5 F	Pa/K		
Measurement time, low power mode	3 ms			
Average current consumption, low power mode, 1 Hz	3 μΑ			
Standby current	< 1 µA			
Supply voltage	V _{DDIO} : 1.2 – 3.6 V	; V _{DD} : 1.7 – 3.6 V		
Operating modes	Command (manual), background (automatic), standby			
Interface	I ² C and SPI, both wit	th optional interrupt		
Package	8 pins LGA: 2.0 x 2.5 x 1.0 mm	8 pins WLGA 2.0 x 2.5 x 0.73 mm		

Orderable Part Number

- >> DPS310: DPS310XTSA1
- >> DPS422: on request

Functional Block Diagram











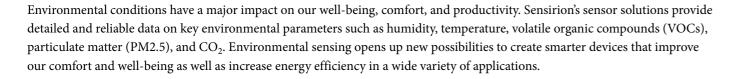


VOC **RH/1**



Environmental Sensing





Particulate Matter Sensor SPS30

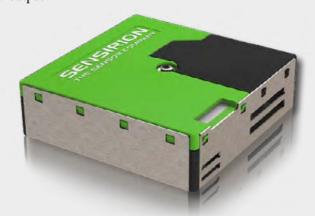
The SPS30 particulate matter (PM) sensor represents a new technological breakthrough in optical PM sensors. Its measurement principle is based on laser scattering and makes use of 's innovative contamination-resistance technology. This technology, together with highquality and long-lasting components, enables accurate measurements from the device's first operation and throughout its lifetime of more than eight years. PM2.5 and PM10 refer to particulate matter with particle diameter up to 2.5 microns and 10 microns, respectively, and are among the most dangerous air pollutants. Due to their small size, PM2.5 particles can travel deep into the human lung and cause a variety of health issues; for instance, by triggering asthma attacks or contributing to cardiovascular disease. The SPS30 will enable the implementation of innovative air quality monitoring devices that prevent air pollution damage.

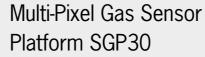
Features

- Unique long-term stability due to 's innovative contamination-resistance technology
- Advanced particle size binning provided through calibrated digital output
- Mass concentration: PM1.0, PM2.5, PM4 and PM10
- Number concentration: PM0.5, PM1.0, PM2.5, PM4 and PM10
- Small, ultra-slim package

Applications

- Air purifiers
- HVAC equipment
- Demand-controlled ventilation systems
- Air conditioners
- Air quality and environmental monitors
- Smart home and IoT devices

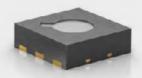




The multi-pixel gas sensor platform SGP creates new possibilities for the measurement of indoor air quality. The SGP offers a complete gas sensor system integrated into a very small 2.45x2.45x0.9 mm DFN package featuring an I2C interface and fully calibrated air quality output signals. Sensirion's MOXSens® Technology provides the SGP with an unmatched robustness against contamination by siloxanes resulting in unique long-term stability and accuracy. The SGP further combines multiple metal-oxide sensing elements – the pixels - on one chip to provide more detailed air quality signals. The unprecedented combination of long-term stability and multi-pixel technology makes the SGP a perfect choice for indoor air quality monitoring in mobile, smart home and appliance applications.

Features

- Outstanding long-term stability based on Sensirion's MOXSens® Technology
- Calibrated indoor air quality signals
- SGP30: tVOC, CO₂eq
- SGPC3: tVOC (ultra-low-power consumption)
- Very small DFN package and I²C interface



Temperature Sensor STS3x

The STS3x is Sensirion's newest highaccuracy digital temperature sensor series. The STS3x temperature sensor utilizes the industry-proven CMOSens® Technology and wins over users with its increased intelligence, reliability, and improved accuracy specifications. The STS3x temperature sensor gives a fully calibrated, linearized, and supplyvoltage-compensated digital output and has an outstanding accuracy of up to ±0.1°C (typical). There are three versions available: the standard version, STS31, guarantees an accuracy of ±0.2 °C over a temperature range of 0 to 90 °C, while the low-cost version, STS30, has an temperature range of 0 to 65 °C. The highend version STS35 is the most accurate temperature sensor available with an accuracy of ±0.1 °C over a temperature range of 20 to 60 °C.

Features

- Compact package: 2.5x2.5x0.9 mm
- Wide supply voltage range: 2.15 5.5 V
- Alert function, two user selectable I²C addresses
- Outstanding accuracy of up to ±0.1°C (typical)



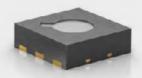
CO₂ and RH/T Sensor Module SCD30

CMOSens® Technology for IR detection enables highly accurate carbon dioxide measurement at a competitive price. Along with the NDIR measurement technology for CO2 detection, a best-in-class Sensirion humidity and temperature sensor is also integrated on the same sensor module. Ambient humidity and temperature can be outputted by Sensirion's algorithm expertise through modeling and compensating of external heat sources without the requirement for any additional components. Thanks to the dual-channel principle for the measurement of carbon dioxide concentration, the sensor compensates for long-term drifts automatically by design. The very small module height allows easy integration into different applications.

Features

- Outstanding stability due to compensation of long-term drifts by dual channel principle
- Three sensor signals based on Sensirion CMOSens® Technology
- Absolute carbon dioxide concentration
- Relative humidity and temperature
- Small form factor and thinnest package















SENSIRION

THE SENSOR COMPANY



32X24 Pixel Thermal Imager MLX90640 & MLX90641 - Infrared Array

See the Unseen

Like the pit viper, get access to the thermal world around you. This thermal camera sensor includes optics, a calibrated I²C output and comes in two resolutions:

- 16x12 pixels (MLX90641)
- 32x24 pixels (MLX90640)

- Measures calibrated object temperature between -40 to 300 °C
- Typical target object temperature accuracy of ± 1 °C
- Two different field of view (FoV) options: 55°x35° or 110°x75° (wide angle)
- Low-noise equivalent temperature difference (NETD) 0.1K RMS at 4Hz refresh rate
- Enhanced thermal stability (MLX90641)
- Extended operating temperature range (MLX90641: -40 to 125°C)
- Programmable refresh rate (0.5 ... 64 Hz)
- I²C compatible digital interface
- No re-calibration needed
- 4-pin TO39 package including optics
- Evaluation board available

Applications

- People detection, for example in building automation systems
- Fire detection/prevention
- Industrial and cooking applications
- Surveillance and air conditioning systems
- Automotive interior comfort (MLX90641)

Analog Ratiometric / PWM MLX90340 - Position Sensor

Flexible Sensing for Industrial Solutions

The MLX90340 is an absolute position sensor based on the Melexis Triaxis® Hall technology targeted for various applications in consumer and industrial markets. With a reduced set of core parameters compared to other Triaxis sensors in the portfolio, the MLX90340 only targets the essential: position sensing with the greatest ease of designing a magnet. It still offers the best flexibility to measure a 360 degrees rotational (end-of-shaft or through-shaft) and up to a +/- 20 mm linear magnet movement.

Features

- Absolute position sensor (± 1° accuracy) 12 bits resolution
- Programmable linearization algorithm: arbitrary points (4 points) or 17 points piecewise linear output compensation
- Programmable magnetic mapping XY, XZ, YZ
- 5 V supply
- Magnet field range from 20 to 70 mT
- SOIC-8 package and redundant TSSOP-16 package
- Temperature range: Heavy-duty industrial [-40 to 150 °C] -Industrial [-40 to 85 °C] - Consumer [-20 to 85 °C]
- Ratiometric analog output or PWM open-drain/ push-pull output [100 Hz to 1 kHz]
- 4 different pre-programmed analog version [90, 180, 270, 360°]

Applications

- Motorcycle
- Heavy-duty industrial
- Consumer



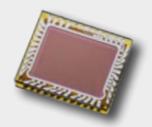
QVGA Time-of-Flight Chipset

MLX75024 & MLX75123 - Real-Time- 3D Imaging with Time-of-Flight Sensor

The MLX75024 time-of-flight sensor together with the new MLX75123 companion chip provides enhanced performances with backward compatibility with the previous QVGA ToF Sensor MLX75023. The MLX75024 ToF sensor supports up to QVGA resolution with a two times higher sensitivity and has a built-in temperature sensor for easier system calibration. The new MLX75123, which controls the ToF sensor, the illumination unit and delivers the data stream to the host processor, has now four general purpose outputs and a new power-up control circuit to further simplify the design of a very compact 3D camera.

MLX75024 ToF Sensor

- 1/3" optical time-of-flight sensor $(4.8x3.6 \, \text{mm})$
- QVGA resolution, 320x240 pixels with selectable gain
- Up to 600 Hz raw correlation frame rate @ 40 MS/s, Tint = 100 s
- BGA package 6.6x5.5x0.6 mm with anti-reflective coating
- Demodulation frequency up to 40 MHz
- Embedded temperature sensor



MLX75123 Companion Chip

- Programmable modulation frequencies to avoid module-to-module crosstalk
- Up to 8 raw phases per frame
- Pre-processed difference & sum output modes to reduce the data bandwidth
- Continuous or triggered operation modes
- Region-of-interest (ROI) selection and binning
- Per-phase statistics & diagnostic
- 4 general-purpose output
- 12-bit parallel camera interface up to 80 Mpix/s
- Configurable over I²C up to 400 kHz
- Chipset is available for automotive (-40/+105) and industrial (-20/+85) temperature ranges



Evaluation Board

The EVK75024 is available to evaluate the MLX75024 & MLX75123 ToF chipset under extreme background light conditions. The flexible design enables any designer to develop the necessary system know-how and experience for use in their application. Its modular concept allows to use the chipset board standalone and combine it with the user's illumination and image processing solution.













OMRON







HVC-P2 (Human Vision Components)

Benefits

- People's conditions recognizable simply by mounting an HVC on equipment, regardless of the CPU performance of a customer's equipment, simply mounting an HVC on the equipment enables the customer to obtain the results of advanced image processing as a sensor output.
- Full range of functions, ten different sensing functions are incorporated to recognise the intentions and conditions of people from a variety of perspectives.
- High-precision: accurate recognition of people's conditions and intentions is enabled under a variety of situations in which a customer's equipment is used

Specifications

Part Number	B5T-007001-010
Horizontal Detection Area (angle of view)	50 deg: 54°±3°; 90 deg: 94°±5°
Vertical Detection Area (angle of view)	50 deg: 41°±3°, 90 deg: 76°±5°
Detection Distance (differs per function)	3.2-16.7 m (HVC-P2 50 deg), 1.6-8.6 m (HVC-P2 90 deg)
Dimensions (WxLxH)	$45 \times 45 \times 8.2$ mm (main board for both types), $25 \times 25 \times 8.7$ mm (camera board 50deg type), $25 \times 25 \times 15.7$ mm (camera board 90deg type)

Outdoors

- Estimate interest and purchase behaviour of people to store goods of interest
- Vending machines recommending drinks to people

Home

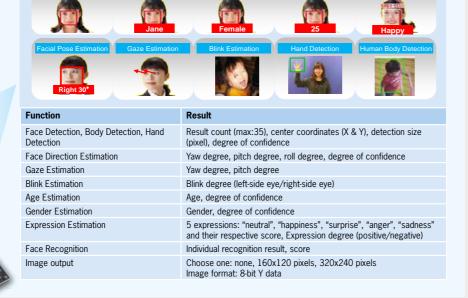
- Home appliances matching movement of people
- AC units targeting people
- Robots matching people
- Lights targetting only people

Workplace

- AC units targeting people
- Lights targeting only people
- Hands free machine operation
- Doors opening to registered people

Main Features

- Camera module angle of view: 2 models (50deg. and 90deg.) available
- Multiple functions (10 functions): Body detection, face detection, hand detection, face direction estimation, gaze estimation, blink estimation, age estimation, gender estimation, expression estimation and face recognition
- User friendly: easy implemenation through UART or USB



Transmissive Optical Sensors

The new TCUT transmissive sensors in a compact transmissive sensor include two infrared emitters and three or four phototransistor detectors, located face-to-face in a surface mount package.

3-Channel Transmissive Optical Sensor for "Turn and Push" Encoding

TCUT1630X01

Features

- Combines infrared emitter and three phototransistors
- Dimensions: 5.5x5.85x7 mm
- AEC-Q101 qualified
- Gap (in mm): 3
- Aperture (in mm): 0.3
- Typical output current under test: $IC = 1.3 \, mA$
- Emitter wavelength: 950 nm
- Operating temp.: -40 to +105 °C
- Moisture sensitivity level (MSL): 1

Applications

- Sensors for motion, speed, and direction
- Steering angle detection (ESP)
- Sensors for "turn and push" encoding
- Position sensors in climate control panels

4-Channel Transmissive Optical Sensor for Absolute and Incremental Encoding

TCUT1800X01

Features

- Combines two infrared emitters and four phototransistors
- Dimensions: 5.5x5.85x7 mm
- AEC-Q101 qualified
- Gap (in mm): 3
- Aperture (in mm): 0.3
- Typical output current under test: IC = 1.3 mA
- Emitter wavelength: 950 nm
- Operating temp.: -40 to +105 °C
- Moisture sensitivity level (MSL): 1

Applications

- Optical encoders that requires high-resolution (can detect up to 16 positions)
- Ignition locks and adaptive headlights
- Encoder for interior turn knobs (climate panel, e-shifter, iDrive)
- Control system valve or vane feedback position sensing



Fully Integrated Proximity & Ambient Light Sensors

Featuring Filtron technology, the sensor combines photo detectors for proximity and ambient light, a signal conditioning IC.

New Fully Integrated Automotive Grade Proximity and Ambient Light Sensor for Gesture Recognition

VCNL4035X01

Features

VEML6030

- Offers excellent background light cancellation capabilities
- AEC-Q101 qualified
- Supports I²C bus communication interface
- High object detection distances up to 500 mm
- Ambient light photo-diode offers detection from 0.004 lx to 16 klx
- High ALS accuracy of ± 10 %
- Excellent temperature compensation: -40 to +105 °C
- Proximity function uses intelligent cancellation to eliminate cross-talk
- Supply voltage range of 2.5 to 3.6 V
- I²C bus voltage range from 1.8 to 5.5 V
- A 16-bit ADC, and a driver for up to three external IREDs in one compact 4x2.36x0.75 mm surface-mount package.

















One Hyperflexible Product Family -**Exactly Matches your** Requirements



Micropower Triaxis Magnetometer MLX90393 - World's Smallest 3D Magnetometer for Position Sensing

The MLX90393 is offering maximal flexibility at minimal size. With its 3x3 mm or 2.5x2 mm footprint, it can fit in the tiniest of assemblies. It provides a digital output proportional to the sensed magnetic flux density along the 3 perpendicular axes of symmetry of the sensor.

But the miniature sensor is mostly characterized by the fact that it can interchange measurement speed for both current consumption and noise on the digital output signal, making it the raw building block for any magnetic sensing application up to 85°C. An external microcontroller can then combine the measurement data in order to define the position of the magnet with respect to the sensor. All this at a selectable dutycycle of 0.1 to 100%.

Features & Benefits

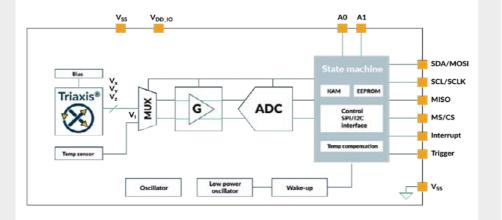
- Micropower (2.2 3.6 V, 2.5 μA idle current)
- Low-voltage I/O (1.8 V V_{dd})
- SPI (3+4-wire) & I²C interface, slave node
- 16-bit XYZ magnetic and thermal measurement
- QFN3x3 package, 16 leads
- UTDFN-8 2.5x2 mm
- In-application programmable (gain, mode, axes, ...)
- Ta = -20 ... 85 °C





HMI: Human-Machine Interface

The MLX90393 lends itself for a wide variety of human-machine interfaces such as joystick (gimball, ball & socket) with push detection, rotary knobs with push function and linear strokes by levers or sliding switches.



Applications

■ Gauss-meter

Joystick w/push

Home security

■ Rotary knob w/push

HMI

Sensing element for the internet of things (IoT)

■ Impeller-based meters 360° impeller position

• Meter mechanical counter digit readout

• General tri-axial anti tampering detection

■ Tamper proof door/window opening detection

detection incl. anti tampering

■ Lever/slide switch linear stroke

Valve position, industrial sensing

Robotics & factory automation

MLX92211/21/31/32/41/42- Programmable & Pre-programmed

of versions at a great price.

Hall Latch & Switches

Melexis presents a revolutionary concept: a perfectly customized Hall latch or switch for your applications. A virtually unlimited set

Programmable

You programme the latch/switch.

Available Types

- 2-wire latch/switch: MLX92242
- 3-wire latch/switch: MLX92232

Benefits

- Rapid prototyping
- High-accuracy



Key Applications

- Smart appliances and consumer devices
- Building automation and energy
- Industry and medical
- Automotive and transportation

Pre-Programmed

Melexis programmes the latch/switch.

Available Types

- 2-wire latch: MLX92221
- 2-wire switch: MLX92241
- 3-wire latch: MLX92211
- 3-wire switch: MLX92231

Benefits

- Drop-in replacements and second sourcing
- Total cost of ownership (TCO) optimization

Evaluation Tool

- Key Specifications
- Wide magnetic latch range: ±0.4 mT to ±80 mT
- Wide magnetic switch range: ±1.5 mT to ±66 mT
- Programmable hysteresis: 0 mT to 36 mT
- Programmable magnet T_C coefficient: 0 to -2000 ppm/°C
- Wide operating voltage range: from 2.7 V to 24 V













High-Precision and Robust Multi-Purpose Linear Hall Sensors For Distance and Small Angle Measurements

HAL 18xy Universal and Cost-Effective

HAL188x/HAL1890 are entry-level linear HALL-Effect sensors with ratiometric linear analog or SENT output (SAE J2716 Rev. 4). They offer a cost-effective solution for small distance or angle measurement. HAL 1880 and HAL 1890 are programmable. HAL 1881-1883 are pre-programmed.



HAL/C 83x Robustness Proven in Use

This family brings over 10 years knowhow and a proven-in-use quality experience. It offers high temperature stability, EMC robustness with HAC830 and flexibility thanks to selectable output (Analog & PWM) for HAL835.



HAC830

Proven Linear Technology in smallest form factor on the market including capacitors

HAL/R 24xy Versatile and High-Precision

The versatile HAL/R 24x5 family offers extended measurement for distance up to two times magnet length & angle up to 180° and stateof-the-art diagnostic functions for applications under stringent conditions. Single and dual versions in different packages are offered.







Device	Characteristics	Output	Package
HAL 1880	± 40 to ± 160 mT magnetic range	Analog (10-bits)	TO92UA
HAL 1881-HAL 1883	± 50 to ± 100 mT magnetic range	Analog (10-bits)	TO92UA
HAL 1890	± 40 to ± 160 mT magnetic range	SENT (SAE J2716 Rev. 4) (10-bits)	TO92UA
HAL 830/HAC 830	± 30 to ± 150 mT magnetic range	Analog (12-bits)	T092UT/T092UP
HAL835	± 15 to 150 mT magnetic range	Analog (12-bits) & PWM (125Hz, 11bits)	T092-UT
HAL2420	± 25 to 200 mT magnetic range	Analog (12-bits)	TO92-UT, SOIC8
HAL2425	Programmable temperature compensation	Analog (12-bits) with 16 programmable set points	T092-UT, S0IC8
HAL2455	for sensitivity and offset continuous self-test	PWM (2kHz, 12-bits) with 16 programmable set points	T092-UT, SOIC8

Target Applications

Throttle

- Pedal EGR
- TransmissionGear position sensor
- Joystick





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Multi-Axis Sensor

For Direct Angle and Linear Position



MICRONAS

MICRONAS

HAL 37xy/HAR 37xy/HAC 37xy

Key Features

- Unique "Virtual Offset Feature" to
- reduce magnet size & cost
- Accuracy of <0.5 % full scale for linear or angular measurements
- No output linearization required for rotary applications
- High ESD protection according to stringent requirements of the automotive industry - ESD protection 8 kV (active Pins)
- Wide junction temp. range from -40 to 170 °C
- SOIC-8 SMD and TO92UG four pin l eaded package
- TO92UF package with caps
- "Open source" programming interface & software
- ISO 26262 Ready

Additional Features

- Supply voltage range 4.5 V to 5.5 V
- Programming via sensors output TTL-Level (0 V... 5 V)
- Memory w. redundancy & lock function
- AEC-Q100 qualification

Various Safety Features

- Wire-break & Over/Undervoltage
- Full signal path & memory supervision
- Overflow and state machine self-test

HAC 37xy SOP

HAC 37xy Integrated Caps in robust

and compact single mold leaded

Magnet lost detection





package TO92UF

Device Number	Output Format	Magnetic Field Axis	Accuracy [%FS]	Min. Magnetic Field Amplitude [mT]	Setpoints	Magnetic Setup
HAL/HAR/HAC3725	Analog	XY	± 0.75		33	End of shaft
HAL/HAR/HAC3726		YZ	**			Off-axis or linear position
HAL/HAR/HAC3727		XZ	**	± 20		Off-axis or linear position
HAL/HAR/HAC3735	PWM or SENT SAE-J2716	XY	± 0.5 %	± 20		End of shaft
HAL/HAR/HAC3736		YZ	**			Off-axis or linear position
HAL/HAR/HAC3737	Rev. 2010 XZ		**			Off-axis or linear position

^{**} Available on request. Depends on magnetic setup

Target Applications

Clutch position

■ EGR Valve

- Turbo-charger actuators
- Transmission
- Chassis position sensors
- Fuel level
- Various valves for engine management







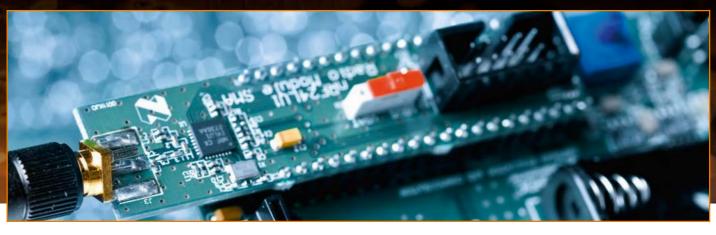


Turbo-charger



Linecard Wireless

Make your application smart by connecting it wirelessly to the Internet of Things. RUTRONIK EMBEDDED has the newest solutions for using a smartphone, WiFi access point or























silex



57



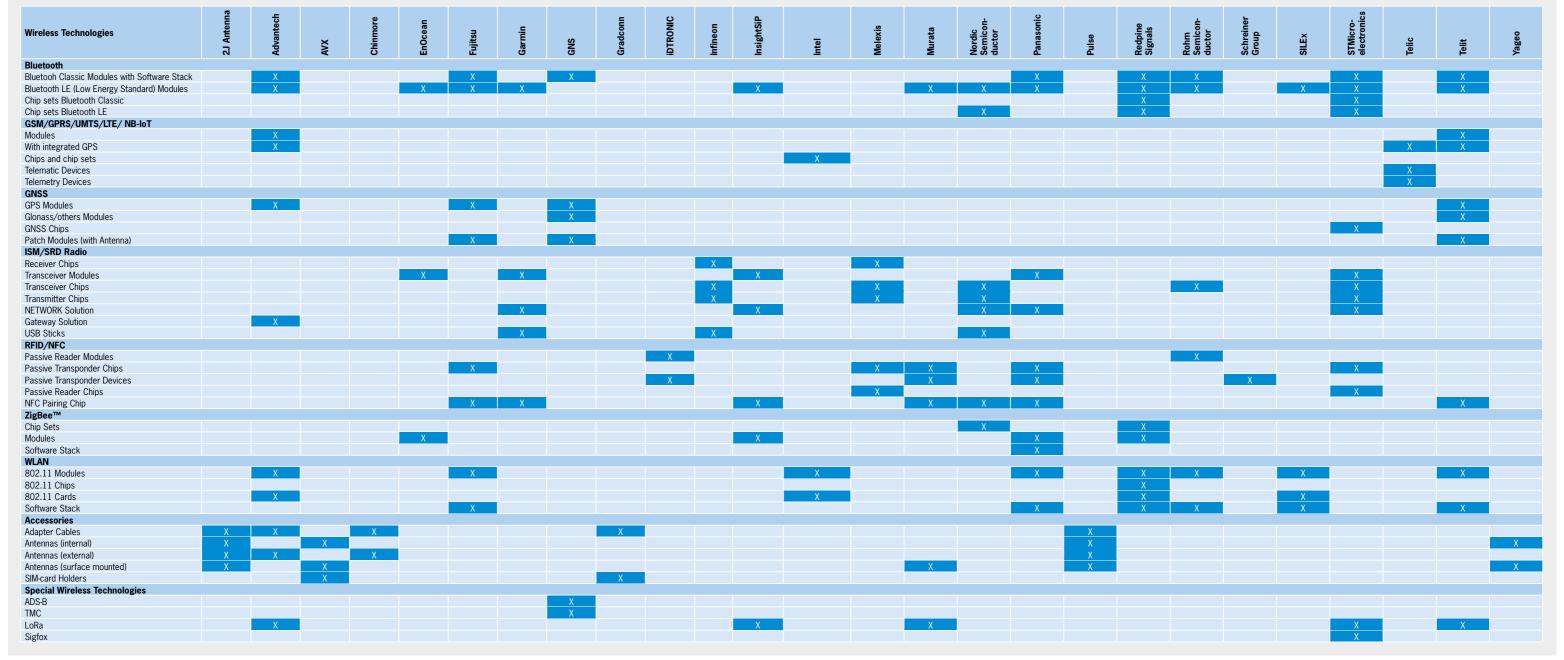
Telic Telit YAGEO







	a mobile communication network as gateway for your device. Our understanding of the right wireless
so	lution covers hardware, drivers or transmission protocol, application profiles, security aspects, certifications
long-ter	rm considerations as well as political aspects regarding standards, compatiblity and consortia.















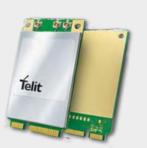
Cellular Data Cards mPCle and M.2 (NGFF)



The robust line from Telit of high-speed industrial-grade PCI-SIG® standards-based modules come in the architecture your project needs whether it be to enable mobile computing, networking, or industrial IoT. The plug-and-play design simplifies integration and is available in two form factors: Mini PCI Express (mPCIe) and M.2.

Dimensions & Key Features

- mini PCIe full-size single-sided
- M.2 (NGFF) 42 mm
- Industrial temperature range: -40 to 85 °C
- Optional GNSS
- Certified with regulatory bodies and mobile operators worldwide



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mPCIe and M.2 Modules in Global Variants

Telit Card	Description	Region	Technology
FN980m	M.2 dual-side, up to 5.7 Gbps Downlink, 7x Carrier Aggregation DL (2x UL), MIMO, 256 QAM, VoLTE, full GNSS support	Europe, North America, APAC	5G (eMBB)
LM960	Mini PCle Data Card, up to 1.2 Gbps Downlink, 5x Carrier Aggregation DL, 4x4 MIMO, full GNSS support	Worldwide	LTE Cat 18
LM940	Mini PCle Data Card, up to 600 Mbps Downlink, 3x Carrier Aggregation DL, MIMO, 256 QAM, full GNSS support	Worldwide	LTE Cat 11
LE910C4	Mini PCle Card, up to 150 Mbps Downlink, MIMO, VoLTE, full GNSS support	Europe, North America, Latin America, APAC, China, India	LTE Cat 4
LE910C1	Mini PCle Card, up to 10 Mbps Downlink, MIMO, VoLTE, full GNSS support	Europe, North America, Latin America, APAC	LTE Cat 1
ME910C1	Mini PCle Data Card, up to 1 Mbps Downlink, GNSS optional	Worldwide	LTE-M / NB-IoT

FN980m Advanced LTE/5G M.2 Data Card





Enabling a new generation of 5G state-of-the-art data cards featuring Sub-6 and mmWave technologies with LTE, WCDMA & GNSS support. Industrial-grade M.2 form factor suitable - among others - for following applications: High Power Fixed Wireless access, enterprise routers and gateways, indoor/outdoor CPE, video broadcasting & surveillance. Support of Qualcomm QTM525 & QTM527 mmWave antennas.

Features & Specifications

- 5G Sub-6 and mmWave FDD and TDD, SA & NSA operations
- 5G core network Opt. 3a/3x and Opt. 2
- 4G: 7CA, up to 20 layers DL / 3CA UL, 256 QAM DL/UL
- 3G: HSPA+ Rel. 8 (DL/UL 42/11 Mbps)
- GNSS: gpsOne Gen9 L1 band on dedicated RF connector, L5 shared with cellular
- Voice support: VoLTE, VoNR (under evaluation), PCM audio over USB
- 4 antenna connectors for LTE/Sub-6
- 4 mmWave antennas supported
- 5G FR1 Bands: n1, n2, n3, n5, n7, n12, n14, n20, n28, n30, n41, n66, n71, n77, n78, n79
- 5G FR2 Bands: n257, n258, n260, 261
- LTE Bands: 1, 2, 3, 4, 5, 8, 9, 12, 13, 14, 17, 18 19, 20, 26, 28, 71, 25, 66, 39, 29 (DL), 30, 32, 7, 38, 40, 41, 42, 43, 46 (LAA), 48 (CBRS), 34, 27
- 5G 4x4 MIMO support on bands n1, n2, n7, n66, n3, n77, n78, n79, n41 and n30

- **4**G 4x4 MIMO support on bands 32, 4, 66, 3, 2, 25, 1, 30, 40, 41, 7, 43, 42, 46, 48
- WCDMA Bands: 5, 8, 3, 4, 2, 1, 9, 19
- FOTA Support
- Dimensions: 30 x 50 x 3.5mm
- Data throughput with 5G: up to 5.5 DL / 2.7 UL Gbps
- Operating temperature range: -40°C to +85°C
- 1.8/3 V SIM Interface
- Interfaces: USB 3.1 gen2, 2.0 and PCIe gen3
- Drivers support: Windows 10, Linux
- Supply voltage: 3.3 VDC
- Approvals: RED & GCF (planned), others (under evaluation)

Key Benefits

- Standard M.2 (NGFF) Data-card form factor
- 4G/5G 3GPP Release 15
- 4G Cat. 20 up to 7x Carrier Aggregation
- 3G HSPA+ 3GPP Release 8
- State of the art GNSS receiver













Cellular Data Cards

LM960 – Advanced LTE Data Card



The LM960 Mini PCIe data card delivers high speed data rates via Advanced LTE and offers a cellular connection for products in network appliance environments. This data card is well-suited for products that demand high throughput such as routers, mobile gateways and access points, to provide the most advanced 4G LTE connectivity, ensuring a rich and seamless user experience. Based on LTE Category 18, the LM960 mPCIe data card achieves download rates up to 1.2 Gbps. It supports 4x4 MIMO, 5x downlink carrier aggregation and 2x uplink carrier aggregation. The product supports multiple RF frequency bands and band combinations to accommodate global deployments.

Key Benefits

- Standard Mini PCIe Data-card form factor
- LTE Cat 18: high-speed with data rates of up to 1.2 Gbps download and 150 Mbps upload
- Full GNSS support: GPS, GLONASS, Galileo, Beidou
- Data only card

Features & Specifications

- Form Factor: PCI Express Mini Card type (mPCIE)
- Dimension: 50.95 x 30 x 2.8mm
- Chipset: Qualcomm SDX20
- Global SKU
- 4x4 MIMO
- 5x DL Carrier Aggregation
- 2x UL Carrier Aggregation
- Support for CBRS Band
- LAA up to 60MHz

Application Fields

- Routers
- Mobile Gateways
- Access Points



- Support for Firstnet B14
- Full GNSS support GPS, GLONASS, Galileo, Beidou
- RF Bands:
- LTE FDD: B1, B25(B2), B3, B66(B4), B26(B5), B7, B8, B12(17), B13, B14, B20, B28, B29(DL), B30, B32(DL), B71
- LTE TDD: B38, B39, B40, B41, B42, B46(DL), B48
- WCDMA: B1, B2, B4, B5, B8
- Temperature Range: -40 to +85°C
- Operating Voltage: 3.1V 3.6V
- Interfaces: Standard mPCIe interface, USB 2.0/3.0, Dual SIM, GPIOs
- Approvals: FCC/IC, PTCRB, CE/GCF, AU

LM940 - LTE Cat 11 Mini PCle Data Card



The Telit LM940 LTE Cat 11 data card delivers high-speed data rates via Advanced LTE and offers a cellular connection for products in network appliance environments. This data card is well-suited for products that demand high throughput such as routers, mobile gateways and access points.

Based on LTE Category 11, the LM940 mPCIe data card achieves download rates up to 600 Mbps supported by the 3GPP release 11 with MIMO and LTE Carrier Aggregation. The product supports multiple RF frequency bands and band combinations to accommodate global deployments. Furthermore the LM940 offers full GNSS support with GPS, GLONASS, Galileo and Beidou.

Features & Specifications

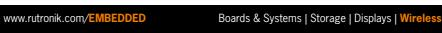
- LTE Bands:
- 1-5, 7, 8, 12, 13, 17, 20, 25, 26, 28, 29, 30, 38, 40, 41, 66
- Data Throughput:
- Up to 600 Mbps Downlink & 75Mbps Uplink
- Operating Temperature: -40 °C to +85 °C
- Interfaces: mPCIe, USB 2.0/3.0, Dual SIM, GPIOs, DVI
- 32 bit ARM Cortex-A7 up to 1.19 GHz running the Linux operating system
- GNSS: GPS, Glonass, BEIDOU, Galileo
- Certifications: FCC/IC/PTCRB/GCF/RED/RCM
- Dimension: 50.95 x 30 x 2.8 mm
- Standard Mini PCIe Data card form factor
- LTE Cat 11: Exceptionally high-speed with data rates of up to 600 Mbps download and 75 Mbps upload

- Full GNSS support
- Increased connectivity performance with Carrier Aggregation 3CA, MIMO and 256 QAM
- Up to 4 independent firmware images selectable at boot to support different network operator requirements
- 3G fallback technology
- USB drivers for Windows 7, 8x, 10 and Linux (Kernel 4.10)
- Oberating voltage: 3.1-3.6V
- Network carriers: AT&T, Sprint, T-Mobile US, Verizon





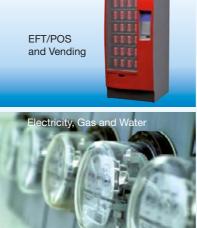
















LE910C4 & LE910C1 Mini PCle



Advanced LTE Cat. 4 and LTE Cat. 1 mPCle Cards

The LE910Cx series Mini PCIe (mPCIe) modules are optimized for LTE low category networks and are available in single mode and 3G/2G fallback options. In addition to VoLTE support, the LE910Cx series are swappable with other modules in the xE910 mPCIe family.

The LE910Cx series has an additional GNSS Receiver integrated. It comes with built in UDP/TCP/FTP and SMTP stacks. Both, LE910C1 and LE910C4, can be controlled over AT commands according to 3GPP TS 27.005, 27.007 as well as Telit Custom AT commands. They operate at a temperature range from -40 to +85°C and support several interfaces, like GPIOs, USB 2.0 HS, UART, 1.8/3V SIM and RF pad, RX Div. & MiMO pad.

The Mini PCIe Cards have following country approvals: FCC/IC, PTCRB, GCF, RCM, Jade/Telec, RED

Application Fields

Ideal platform for IoT applications, mobile data and computing devices with ultra-compact design and extended operating temperature range.



Version	LE910C1- NA	LE910C1/ C4-AP	LE910C1- NS	LE910C1/ C4-EU	LE910C1/ C4-NF	LE910C1- SA	LE910C1- SV	LE910C1- ST	LE910C1/ C4-LA	LE910C4- CN
Market	North America (AT&T)	APAC (Telstra/ NTT-Docomo)	North America (Sprint)	EMEA	North America (Public Safety, AT&T, FirstNet, T-Mobile, Verizon)	North America (FirstNet, AT&T)	North America (VZW)	North America (TMO US)	LATAM	China, India
4G Bands	B2, B4, B12	B1, B3, B5, B8, B9, B18 (B26), B19, B28	B2, B4, B5/ B26, B12, B25	B1, B3, B7, B8, B20, B28A	B12, B14, B4, B2, B5, B13, B66, B71	B4/66, B2, B12, B14	B4, B13	B4/66, B2, B12, B71	B1-5, B7, B28	B1, B3, B5, B8, B38-41, B34, B39
3G Bands	B1, B2, B4, B5, B8	B1, B5, B6, B19, B8	-	B1, B3, B8	B2, B4, B5		-		B1, B2, B4, B5	B1, B8
2G Bands	B2, B3, B5, B8	-		B3, B8	-	-	-		B2, B3, B5, B8	B3, B8

M2M Terminals



GSM and **UMTS** Terminals for M2M Applications

Telic's GSM and UMTS terminals are targeted towards professional and industrial M2M applications which require wireless connectivity provided in a robust and reliable casing.

Key Benefits

- By integrating terminals from Telic, you can fully focus on the core competencies required in your specific application area and avoid the cost of developing, testing and certifying terminal related
- Easily swap 2G, 3G with 4G terminals when required by having a real migration path for these mobile network technologies

Key Features

- Modules based on Telit or Cinterion
- Dual band and quad band support for 2G (GSM/GPRS)
- Dual band or penta band support for 3G (UMTS and HSPA/HSPA+)
- Industry standard RS232 interface on all products
- Ultra-low power consumption mode in selected products for battery-powered applications

Categories	Features	GT910 G	HT910 E	HT910 G	LT910 E	NT910 G
Modules	Supplier	Telit	Telit	Telit	Telit	Telit
Category	Product Category	Basic 2G	UMTS/HSPA	UMTS/HSPA	LTE/GSM/GPRS	LTE-M/NB-IoT
General	Part Number	06308	06301	06303	06307	06311
	2G Frequency Band	2G Quad	2G Dual (900/ 1800 MHz)	2G Quad	2G Dual (900/1800 MHz)	2G Quad
	3G Frequency Band		3G Dual (900/ 2100 MHz)	3G Penta		
Air Interface	HSPA DL		7.2 Mbit/s	21 Mbit/s		
Air iiiteriace	HSPA UL		5.7 Mbit/s	5.7 Mbit/s		
	LTE DL				10 Mbit/s	300 kbps
	LTE UL				5 Mbit/s	375 kbps
	RS232 Interface	D-Sub (9-pin)	D-Sub (9-pin)	D-Sub (9-pin)	D-Sub (9-pin)	D-Sub (9-pin)
	USB 2.0	Mini-USB	Mini-USB	Mini-USB	Mini-USB	
	Audio (analog)					Mini-USB
Interfaces	Antenna	FME	FME	FME	FME	FME
	LEDs	1 GSM + 2 Configurable	1 GSM + 2 Configurable	1 GSM + 2 Configurable	1 GSM+ 2 Configurable	1 GSM + 2 Configurable
	Robust 1.8/3 V SIM Card Holder	•	•	•	•	•
	Programmable		Python	Python	AppZone	AppZone
Software	Firmware Update	Serial/FOTA	FOTA	FOTA	FOTA	FOTA
	TCP/IP Stack	•	•	•	•	•
l	Analog Inputs		1	1	1	1
nput/ Outputs	Digital Inputs					
ouquio	Outputs		1 (optional)	1 (optional)	1 (optional)	1 (optional)
	Voltage Range	5V - 36V	5V - 32V	5V - 32V	5V - 32 V	5V - 32V
Electrical	Standby (@ 12V)	≈ 19 mA (*)	≈ 20 mA (*)	≈ 23 mA (*)	~12 mA (*)	~12 mA (*)
Characteristics	Low Power Mode (@ 12V)	~2 mA (*)	≈ 10 mA (*)	≈ 11 mA (*)	~ 2 mA (*)	~ 2 mA (*)
	Operating Temp.	-30 to +75°C	-30 to +80°C	-30 to +80°C	-30 to +80°C	-30 to +75°C
Hardware Characteristics	Size			77 x 66 x 26mm		
Ondi dotto iotico	Weight	91g	91g	91g	91g	91g
	CE	•	•	•	•	•
Certificates	e1	•				
	FCC	•				

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EWM-C141M201E





EWM-G109H01E



Cellular Mini PCle Data Cards

EWM-C117FL

Wide-Temp 4G/LTE, Full-size Mini PCle Card

Features

- 4G/LTE Bands Cat. 4, 3G UMTS/ HSPA, 2G GSM/GPRS/EDGE
- HSDPA 7.2Mbps, HSUPA 5.76Mbps
- U-blox TOBY-L2
- Operating temperature: -40 to +85 °C
- PCI Express mini-card rev. 1.2
- 2 RF Antenna Coaxial Connectors
- Windows 7/8.x/10, WinCE 5.0/6.0, Linux 2.4.x/2.6.x, Mac
- 50.85 x 29.9 x 6.2 mm

EWM-C141M201E

4G / LTE M.2 Card

Features

- M.2 Key-B Card
- LTE CAT4
- 4G LTE FDD:
- **1**, 3, 5, 7, 8, 20, 28,
- 3G bands:
- 1, 5, 8,GPRS: 850(B5), 900(B8), 1800(B3),1900(B2)
- Intel 7120M Chipset
- FDD LTE Max150Mbps(DL) / 50Mbps(UL)
- USB 2.0 Interface
- Dimension: 30 x 42 x 3.2mm
- Tx Power / Rx Sensitivity
- Tx: 33 dBm Rx: -110 dBm

EWM-NB147F01E

LTE Cat M1 / NB-IoT Full size mini PCle Card

- u-blox SARA-R410-02B LTE Cat M1 / NB1 engine.
- Bands = 1, 2, 3, 4, 5, 8, 12, 13, 17, 18, 19, 20, 25, 26, 28 (and band 39 in M1-only)
- Build-in micro SIM card holder
- Low idle mode current

- Standard mini PCIe full-size 30 mm x 50.95 mm
- Temperature range: -40 to +85°C.
- Manufactured in ISO/TS 16949 certified production sites.
- Mini PCIe Signal Type USB2.0.

EWM-G109H01E

Embedded Multi-GPS/ **GNSS Module**

ADVANTECH

Features

- Half-size Mini PCIe card
- Multi-GNSS (GPS, GLONASS, BeiDou Galileo, QZSS and SBAS)
- Receiver Type
- 72 Channels
- GPS/QZSS L1 C/A, GLONASS L1 L10F, BeiDou B1, SBAS L1 C/A: WAAS/EGNOS/MSAS,
- Galileo-ready E1B/C
- Time-To-First-Fix
- (GPS + GLONASS)
- Cold Start: 26 s ■ Hot Start: 1.5 s
- Aiding Start: 2 s
- Sensitivity (GPS + GLONASS) Tracking & Navigation: -167 dBm
- Reacquisition: -160 dBm
- Cold Start: -148 dBm
- Horizontal Pos. Accuracy SBAS: 2.0 m
- Time Pulse Config.: f=0.25...10 MHz
- Dynamics < 4 g
- Operating Temperature -40 to +85 °C

www.rutronik.com/El



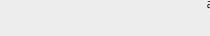
EWM-G110H01E

Industrial GPS USB Half Mini PCI-E Card

Features

- ■72-channel u-blox M8 engine
- GPS/QZSS L1 C/A,
- GLONASS L1 L10F,
- BeiDou B1, SBAS L1 C/A: WAAS/EGNOS/MSAS, Galileo-ready E1B/C.
- U-Blox M8 position engine with over 2 million effective correlators featuring < 1 s acquisition, -160 dBm cold start acquisition sensitivity and 20 Hz update rate.
- Supports u-blox' Assist Now Online / Assist Now Offline / AssistNow Autonomous A-GPS services and is OMA SUPL / 3GPP compliant
- Open sky cold start 26 second / Aided starts 3 second
- SBAS: WAAS, EGNOS, MSAS
- Accuracy 2.5 m CEP
- RoHS compliance
- ■1 USB 2.0
- PCI-Express Mini or Half Mini Card form factor





GNSS USB Receiver with

Telit SI 869 Receiver

Features

2JR02ba2

- Interface: USB 2.0
- Cable length: up to 10 m
- Impedance: 50 Ohm
- Polarization: RHCP
- Gain: 3dBiC
- Voltage supply: 3.7 V to 6 V
- Current: 65 mA Max.
- Operating temperature: -45 °C to +85 °C













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WiFi



WiFi



EWM-W170H01E

IEEE 802.11 ac/a/b/g/n Half-size Mini PCle Card

Features

- Main Chipset: QCA 9377-7
- Interface: PCI Express mini-card rev. 1.2
- Data Rate: Up to 433 Mbps
- Security: WEP 64/128-bit, WPA, WPA2
- OS Supported: Windows 7/8.1/10
- Operating temperature: -20 to +70 °C

EWM-W162M201E

Low Cost Extended Temperature IEEE802.11 a/b/g/n/ac + Bluetooth 4.2 2x2 MIMO M.2 Card

Features

- Main Chipset: Marvell 88W8897P
- Interface: PCI Express
- WLAN Signal Protocol: PCIe Differential
- Bluetooth Signal Protocol: USB Differential
- Data Rate: Up to 866.7 Mbps
- Security: 64/128 bit WEP, WPA, WPA2
- OS Supported: Linux
- Operating temperature: -30 to +85 °C

SX-PCEAN2

802.11 a/b/g/n Mini PCle Radio Module with Industrial Temperature Support

Features

- Atheros AR9582 [commercial] / AR9592 [Industrial] highly integrated chip set
- IEEE 802.11a/b/g/n compliant 2.4/5 GHz dual band
- 2x2 MIMO performance with data rate up to 300 Mbps
- PCI Express Mini Card 1.2 compliant
- Supports open source ath9k driver
- Linux supplicant available on request for WPA/WPA2-PSK & 802.1x EAP
- Customized Driver development available on request
- Freescale i.MX 6 support
- IEEE 802.11e QOS support available
- IEEE 802.11e QOS support

SX-PCEAC

802.11a/n/ac PCI Express Wireless LAN Module

Features

- Qualcomm Atheros QCA9880 chipset
- 3x3 SU-MIMO enhances high speed and stability
- IEEE 802.11ac(Wave1)/ a/n/e/h/i
- Wide band 80 MHz mode
- Silex Linux reference driver with IEEE802.11x EAP support
- High density modulation mode (256QAM)
- Max data transfer rate: 1.3 Gbps

EWM-W168H01E

802.11 a/b/g/n/ac +Bluetooth 4.2 Half-size Mini PCle Card

Features

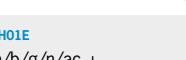
- IEEE 802.11 a/b/g/n/ac + Bluetooth 4.2 HS standard
- Realtek RTL8822BE-VG Chipset
- WiFi: PCI-e BT:USB Interface
- Windows 7/8.1/10 ■ 2Tx/2Rx
- Up to 866.7 Mbps Data Rate
- WEP/WPA2, WAPI, 802.11i
- Operating temperature: 0 to 70° C
- 26.65 x 29.85 x 3.95 mm

EWM-W190H01E

802.11 a/b/g/n/ac +Bluetooth 4.2 2T2R Mini PCle Card

Features

- Microsoft Windows/Linux/Android Support
- Support for BT & WLAN Co-existence
- RoHS Compliance
- Frequency Band(2.4/5GHz)
- WPA, WPA2 security support
- Bluetooth V4.2, V4.1, V4.0 LE, V3.0+HS, Bluetooth V2.1+EDR system, version 1.1, 1.2 and 2.0
- Two-stream spatial multiplexing up to 867Mbps data rate
- Output power up <=+10 dBm
- -40 to +85 °C operating temperature



















WiFi



SX-SDMAC

802.11 a/b/g/n/ac Plus Bluetooth SDIO Wi-Fi Module

Features:

- Based on the QCA9377-3 Chipset
- Dual Band SDIO Wi-Fi Module with 802.11ac WLAN plus BT 4.1
- Link Rate up to 433 Mbps
- Bluetooth 4.1 BR/EDR/LE Smart Ready
- SDIO 3.0 WLAN Host Interface
- Pin Compatibility with SX-SDMAN Offers an Upgrade Path
- FCC/IC/ETSI/TELEC Modular Certification



SX-SDMGN-2830

Low Power embedded 802.11b/g/n SDIO Module

Features:

- IEEE 802.11b/g/n conformity (2.4 GHz)
- Single stream 1 x 1 SISO technology and 20MHz bandwidth mode. (Throughput up to 72.2Mbps)
- Low Power Consumption / Small Form Factor
- Data rates of 1 54 Mbps for 802.11b/g, 7.2 - 72.2 Mbps for 802.11n
- Support SDIO 2.0 as host interface for wireless LAN
- Supports TDMA/FDMA Bluetooth Coexistence
- 40 pin connector
- Upgrade Path to Dual-Band Solution



SD-320AN

Wireless Serial Device Server

Features

- Device Interface: Single serial port: RS-232
- Industry-leading security including WPA, WPA2, and WEP, plus 802.1x authentication with the most commonly used EAP types
- Dual band IEEE 802.11a/b/g/n support on the SD-320AN allows communication in the 2.4 GHz and 5 GHz bands. Radio interference in the commonly used 2.4 GHz band can be avoided by utilizing 5 GHz.
- Virtually any client device can remotely control and monitor your serial devices including computers (Windows, Mac, Linux), mobile devices (Android, iOS), and virtual servers (VMware, Citrix, Microsoft Terminal Server and Hyper-V).
- No special drivers or applications serial devices: Drivers and appliwhen the serial device is directcomputer will continue to work connected to the SD-320AN.

are needed to use the cations that worked ly connected to the across the network



SX-ND-4350WAN

Wireless Network Display Adapter

Features

- Wireless LAN access point
- Immediate response to touch input and Video, without visible latency
- Bidirectional data transfer with various USB devices
- Software that allows to search for NetDA devices, connect to and disconnect from monitor and query connection status
- Screen Sharing to any browser in same network

SX-ND-4350WAN is an interactive display adapter, and also functions as a wireless access point.

The product connects to the network and the display in a presentation or classroom environment.



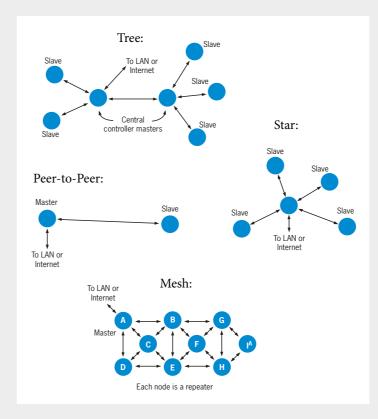




What is ANT™

ANT™ is a practical wireless sensor network protocol. It offers an ultra-low-power, short-range wireless technology running on the 2.4 GHz ISM band. It handles peer-to-peer, star, tree and fixed mesh topologies. Application examples for ad-hoc mesh techniques are also available.

More Information www.rutronik-tec.com/ant



ANT USB Stick – ANT USB-m

Key Benefits

- The ANTUSB-m is a USB dongle that provides a quick and easy solution for Windows PC, Mac and Android equipment with an USB type A port to connect to ANT wireless networks
- Provides enhanced ANT core features, such as proximity search and frequency agility
- Up to 8 ANT channels available
- WHQL certified Windows driver for Windows XP, Vista, 7 and 8
- No driver installation required on Mac OS X10 and above

Key Features

- 78 selectable RF channel
- ANT channel combined message rate up to 190 Hz (8byte data playload)
- Minimum message rate per ANT channel 0.5 Hz
- Burst transfer rate up to 60 Kbps (true data throughput)
- -40 °C to +85 °C operating temperature

Application Fields

Applications running on computers or equipment often act as the hub node of a network. Through the use of the ANT USB stick the application can receive, store, analyze and display data collected from ANT sensors or other wearable or portable hub devices, e.g. watches and bike computers.

The application may also serve as the gateway to the Internet for cloud computing.

The ANTUSB-m is a miniature design. When plugged in, the majority of the body is buried inside the computer or equipment.

























Intel Dual Band Wireless-AC M.2 Cards

Devices with Intel® Wireless-AC-technology inside (802.11ac) offer up to three times higher data rates, a better network coverage and the possibility to connect more devices to one network, compared to other WiFi solutions.

More Speed

Up to six times faster, speedy enough to stream multiple Blu-Ray quality videos, Netflix movies and YouTube videos simultaneously

More Capacity

Up to three times the capacity, so your WiFi can handle more users, more devices, more high-quality video streaming and bigger downloads

More Coverage

Better speeds and reliability at greater distances from your WiFi Access Point, so you stay connected in more places

More **Battery Life**

Transfers data more quickly, so your devices use less power and last longer between charges.

Intel Dual Band Wireless-AC 9260

Compared to the WiFi 5 solutions (IEEE 802.11 ac), WiFi 6 solutions (IEEE 802.11 ax) provide higher data rates, lower latency and longer battery lifetime.

The AX200 is coming with a PCIe interface for WiFi and a USB interface for Bluetooth 5. The AX201 is a CRF (Companion RF) module hat uses the Intel proprietary interface (CNVio2) and therefor can be only used with selected Intel chipsets and platforms. Both the Intel WiFi 6 AX200 and AX201 support 2x2 WiFi 6 technology including new features as Uplink/Downlink OFDMA, 1024QAM and data rates up to 2.4 Gbps which results in smooth streaming of high resolution videos, fewer dropped connections and faster connections farther away from the router and in dense environments.

Туре	Intel WiFi 6 AX200	Intel WiFi 6 AX201				
Code Name	Cyclone Peak 2	Harrison Peak 2				
Estimated SW Support until	Q4	2025				
TX/RX Streams	2	x2				
Bands	2.4 GHz, 5 GHz, 160 MHz					
Max Speed	2.4 Gbps					
Integrated Bluetooth	V5					
Form Factor	M.2 2230; M.2 1216 (SMD)					
Supported Operating System	Windows 10, 64-bit, Google Chrome OS, Linux					
System Interface Type	PCle (WiFi), USB (BT) CNVio2					

Applications

- Consumer Transportation /
- Surveillance PCs / Laptops
- Medical devices
- POS / Kiosk
 - Digital Signage

Logistics



Intel Dual Band Wireless-AC 9260

The Intel Dual Band Wireless-AC 9260 supports the WLAN Standard IEEE 802.11ac and is the first WLAN module providing Gigabit Wi-Fi speeds with 1.73Gbps when using 160MHz channels. Fast downloads and longer battery life times are therefore possible. The Bluetooth v5 functionality offers 4x the range of Bluetooth v4.2 at the same power consumption, 2x speed and better broadcasting functionality. Improved Gigabit download speed is provided in combination with Intel Core processors. Simultaneous data transmission from one access point to multiple clients and 3x better downlink network capacity are possible due to downlink MU-MIMO.

Features

- WLAN standard IEEE 802.11ac
- Bluetooth v5
- Form factor: M.2 card
- Dimensions: 22mm x 30mm x 2.4mm
- Operating Temperature: 0 to +80 °C
- Security features:
- WPA / WPA2 / 802.1X authentication

(intel)

- 64bit and 128bit WEP / 128bit AES-CCMP encryption
- TX/RX is 2×2
- Up to 1.73Gbps
- Interfaces: PCIe, USB
- Operating Systems: Microsoft Windows 10* OS, Linux, Chrome
- Supported under vPro
- FCC / IC / CE certified

Intel Dual Band Wireless-AC 9560

The Intel Dual Band Wireless-AC 9560 supports the WLAN standard 802.11ac and the Bluetooth version 5, which provides higher range (4x), faster transmission speed while reducing power consumption. Due to MU-MIMO and 160MHz channels with 1.73Gbps the Wireless-AC 9560 provides increased speed, fast downloads and long battery life.

Features

- WLAN standard 802.11ac
- Bluetooth v5
- Form factor: M.2 card
- Operating temperature: 0 °C to +80 °C
- Security features: WPA, WPA2, AES-CCMP
- TX/RX: 2×2
- Up to 1.73 Gbps
- uFL antenna connector
- Interfaces: PCIe, USB
- Operating systems: Microsoft Windows 10, Linux (limited feature support), Chrome
- FCC / IC / CE certified



Intel Dual Band Wireless-AC 8265

The Intel Dual Band Wireless-AC-8265 supports the WLAN Standard IEEE 802.11ac and the Bluetooth version 4.2. The 4th Generation of Intel Wireless Technology provides improvements in speed, capacity and coverage as well as battery lifetime. The module offers up to three times faster speed in bigger distance to the router, up to three times better network coverage and three times larger capacities as the downlink MU-MIMO allows a parallel connection of more devices to one network. Furthermore the Wireless-AC offers a longer battery lifetime due to a faster data transfer.

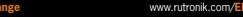
Features

- WLAN standard IEEE 802.11ac
- Bluetooth v4.2
- Form factor: M.2 card
- Operating Temperature: 0 to +80 °C
- Security features:
- WPA / WPA2 / 802.1X authentication
- 64 bit and 128 bit WEP / 128 bit AES-CCMP encryption
- Full support for latest Microsoft Windows 10 OS
- uFL antenna connector
- Interfaces: PCIe, USB
- FCC / IC /
- CE certified
- TX/RX is 2×2
- Up to 433 Mbit/s
- Up to 867 Mbps

















Transponder Applications Examples

ISO and Hybrid Cards
Available 125 kHz, 13.56 MHz
and UHF IC technologies.
Cards can be customized with
different personalization and encoding options.

Smartlabels and Tickets Adhesive labels 13.56 MHz and UHF, CD/DVD labels and paper tickets.



Freq. IC Version

EM4200

EM4450/4550

NXP Hitag 1

NXP Hitag 2

NXP Hitag S256

NXP Hitag S2048

NXP Mifare Ultralight (UL)

NXP Mifare Classic Mini

NXP Mifare Classic 1K

NXP Mifare Classic 4K

NXP Mifare MF1S20 (mini)

NXP Mifare MF1S50 (1K)

NXP Mifare MF1S70 (4K)

NXP Mifare DESFire EV1 (2K)

NXP Mifare DESFire EV1 (8K)

NXP I-Code SLI

NXP I-Code SLI-S

LEGIC MIM256

LEGIC MIM1024

LEGIC Advant 1024

LEGIC Advant 2048

TI Tag-it HF-I

STM SRI512

STM LRI2K

STM SRI4K

NXP NTAG203

UHF U-Code Gen2

Alien UHF Higgs 3 Gen2

NXP Mifare Ultralight (UL) C

Atmel Temic 5567

Special Tags

On-metal tags, high temperature tags, UHF hard tags, nail tags, etc





IDTRON

and personalized.

Disctags
These tags are all available with different diameters, with printing and with/withou centre hole.

Passive RFID Transponders – Overview

With its large portfolio of chips iDTRONIC covers the total

frequency bandwith of LF, HF and UHF RFID Transponders.

ISO-Standard

ISO 11785 (FDX-B)

ISO/IEC 11784/785

ISO 11784 / 85

ISO 10536.1

ISO 10536.1.

ISO 11784 / 85

ISO 11784 / 85

ISO 14443 A

ISO 15693

ISO 15693

ISO 14443 A

ISO 14443 A

ISO 14443 / 15693

ISO 14443 / 15693

ISO 15693

ISO 14443 B

ISO 15693

ISO 14443 B

ISO 18000-60

ISO/IEC 14443A

ISO/IFC 18000-60

ISO 14443 A (1-3)

ISO 14443 A (1-3)

ISO 14443 A (1-3)



Memory Cap.

8 Byte

125 Byte

28 Byte

256 Byte

32 Byte

32 Byte

256 Byte

64 Byte

192 Byte

320 Byte

1024 Byte

4096 Byte

320 Byte

1024 Byte

4096 Byte

2048 Bytes

4096 Byte

8192 Byte

128 Byte

256 Byte

256 Byte

1024 Byte

256 Byte

128 Byte

256 Byte

64 Byte

256 Byte

512 Byte

168 Byte

64 Byte

16 Byte

RFID

RFID Stick Reader Evo

The RFID Stick Reader EVO is a compact RFID reader and writer with adjustable performance. Its practical USB interface is used for the fast transfer of data as well as the power supply. Thanks to the IP40 protection class, it can withstand dust and other foreign objects up to 1 mm.



Product Features

- Dimensions: 83.5 x 36 x 11.2 mm
- Housing-Material: ABS
- Power Supply: 5V DC, via USB
- Operating Systems: Windows XP, Vista, 7, 8, 8.1, 10
- Antenna: integrated
- Interface: USB VCP, HID

The RFID Stick Reader EVO is Available in the Following Versions

FreqRange	Frequency	Standard
UHF	868 – 916 MHz	Standard ISO 18000-6C incl. Class 1 Gen 2
HF	13.56 MHz	ISO 14443 A/B, ISO 15693 MIFARE Family

Desktop Reader EVO

iDTRONIC's Desktop Reader EVO is an easy-to-use RFID Reader/Writer which uses the USB 2.0 interface for high-speed data transfer. A Multi-LED illuminated frame is included, turning on during reading process. It comes with a full SDK and a MS Windows based application SW. Additionally, Keyboard Emulation (KEMU) is optional for all Versions.

Product Features

- Dimensions: 125 x 70 x 26 mm
- Housing-Material: ABS
- Power Supply: 5 V_{DC}, via USB
- Operating Systems: Windows XP/7, Linux
- Antenna: Integrated
- Interface: USB 2.0, cable length 1.2 m

The Desktop Reader EVO is Available in the Following Versions

FreqRange	Supported Standards / Card Types
UHF	ISO 18000-6C incl. Class1 Gen2
HF	MIFARE® Classic 1K, 4K; MIFARE Ultralight®; MIFARE Pro; AT88RF020; 66CL160S; SR176; SRIX4K (TYPE-B); I-Code2; TI RFid Tag-it HF-I; EM4135; EM4034 Read only UID of all other ISO 14443A/B, ISO 15693 cards
LF	ISO 11784, ISO 11785
LEGIC	ISO 14443A/B; ISO 15693; LEGIC Prime/Advant
TEMIC	TEMIC 55x7

BLUEBOX Professional RFID

BLUEBOX professional RFID is a family of highly sophisticated RFID controllers, readers, antennas and solutions allowing easy system integration.

BLUEBOX Unique Advantages:

- Ruggedized product design and enclosures (All components minimum IP65 or IP54)
- Available for
- UHF 860-960 MHz (ISO18000-6C, EPC Class1 Gen2),
- HF 13.56 MHz (ISO15693, ISO14443, ISO 18000-3) and
- LF 125 kHz (ISO18000-2, ISO11784/11785)
- Solutions for Near Field, Short-, Mid- and Long-Range appl.
- Contr. with integr. antenna or for running 1, 2 and 4 antennas
- Extended range of application specific antennas
- Outstanding read / write performance and reading distances
- Possibility of using different RFID standards in parallel in one application
- Multiple Interface Options (RS232/485, Ethernet, Profibus, etc.)
- Integrated Webserver for remote access to Controller
- Suitable for Stand-Alone operation
- Integrated I/O ports
- Micro SD slot for memory extension
- Diagnostic interface
- Several Standard Read Modes like Buffered Read Mode, Scan Mode, Notification Mode, RSSI Mode
- Unique SDK for all BLUEBOX products
- BLUEBOX SHOW applications software
- M12 connections for trouble-free and secure connection and installation (optional RJ45 for UHF CX Controller)













Various other short range, mid range and long range Antennas

FreqRange	Desktop Reader	Various Controller with integrated Antenna	Various Controller with up to 4 ports for external Antenna	M30 Cylindrical Reader (metal)	Various M18/M30 Cylindrical Antennas	Various other short range, mid range and long range Antennas
LF Reading Distance	Up to 10 cm	Up to 15 cm	Up to 30 cm	Up to 8 cm	Up to 11 cm	Up to 23 cm
HF Reading Distance	Up to 15 cm	Up to 15 cm	Up to 15 cm	Up to 12 cm	Up to 6 cm	Up to 30 cm
UHF Reading Distance	Up to 30 cm	Up to 3 m	Up to 10 m	up to 50 cm*	Up to 20 cm	Up to 10 m

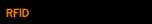


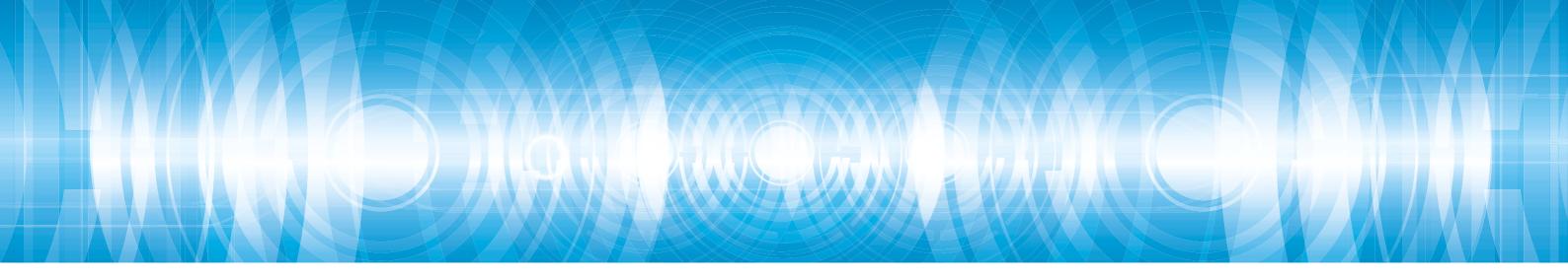












Internal Antennas

	Part	Picture			;	Stan	daro	t											
Manufacturer			GSM / 2G	UMTS / 3G	LTE / 4G	5G (Sub6Ghz)	ISM Standard	Bluetooth	WLAN	GNSS	Antenna Type	Frequencies	Peak Gain (dBi)	Efficiency (%)	Size (mm)	Polarization	Cable Length (mm)	Connector	Impedance
												868 MHz	2.7	58				U.FL	
	2JF0415P						х				FPC / Adhesive	915 MHz	3.6	77	25 x 70 x 0.2	Linear	100	com- pati- ble	50
	2 1502020-	A STATE OF THE PARTY OF THE PAR							Ţ		FDC	2.4 GHz	3.2	>50%	22.4 x	Linnan	100	U.FL/	F0
	2JF0302Pa								X		FPC	5 GHz	5.0	>64%	20.6 x 0.2	Linear	100	I-PEX	50
ล		_										968-960 MHz	1.5	58%					
	2JF0424P	til.	х	х							FPC	1710-2170 MHz	3.1	74%	136.8 x 32.6 x 0.2	Linear	150	U.FL / I-PEX	50
												2500-2700 MHz	3.5	61%	02.0 X 0.2			II EX	
												968-960 MHz	1.2	56%					
	2JP0424P		х	х							FPC	1710-2170 MHz	4.0	66%	113 x 8.5 x 0.8	Linear	100	U.FL / I-PEX	50
												2500-2700 MHz	5.6	78%	х 0.0			II EX	
	WxP3015W08								х		FPC	2.4-2.48 GHz	< 3.0	65%	30 x 15.5	Linear	100	U.FL com-	50
<u>.8</u>	WXI 3013W00								, and		110	5.15-5.85 GHz	< 6.7	61%	x 0.8	Lilicai	100	pati- ble	30
AVX ethertronics												698-960 MHz	*	7400%	50.6				
e	1002289		X	Х							FPC	1710-2690 MHz	•	5800%	53.6 x 25.1 x 0.2	Linear	25	U.FL / I-PEX	50
	1052630003	_	x	X							FPC / Adhesive	824-960 MHz	2.2	*	106.7 x	Linear	200	U.FL/	50
	1032030003		^	Î	^						11 C/ Adilesive	1710-2690 MHz	3.0		13 x 0.1	Lilleal	200	I-PEX	30
	479501011	1					х		x		FDC / Adhanisa	2.4 GHz	3.0	>80	35.9 x	Linear	150	U.FL/	50
	479501011	11					۸	^	^		FPC / Adhesive	5 GHz	4.8	>75	15.9 x 0.1	Lillear	150	I-PEX	50
molex	1052620001						v				FPC / Adhesive	868 MHz	0.4	*	79 x 10	Linear	100	U.FL/	50
Ě	1032020001						^				FFC / Adilesive	915 MHz	1.4		79 x 10 x 0.1	Lillear	100	U.FL / I-PEX	50
	2084820150						v	v	x		FPC / Adhesive	2.4 GHz	3.2	62% (Port1), 72% (Port2)	55.2 x 19.2 x	Linear	150	U.FL / I-PEX	50
	2004020130	//					Х	X	X		TT C / Autresive	5 GHz	5.7	70% (Port1), 66% (Port2)	0.16	Linear	130	I-PEX	30
												1561 MHz	0.9	>72	40.4 x				
	2065600100									Х	FPC / Adhesive	1575 MHz	1.0	>72	40.4 x 15.4 x	Linear	100	U.FL / I-PEX	50
		1										1602 MHz	1.37	>73	0.1			H LA	
													-						

	Part	Picture			S	tan	dard	t											
Manufacturer			GSM / 2G	UMTS / 3G	LTE / 4G	5G (Sub6Ghz)	ISM Standard	Bluetooth	WLAN	GNSS	Antenna Type	Frequencies	Peak Gain (dBi)	Efficiency (%)	Size (mm)	Polarization	Cable Length (mm)	Connector	Impedance
												2.4 GHz	2.6	>55					
	2069950150	-					X	х	x		FPC / Adhesive	5 GHz	3.4	>71	20.5 x 20.5 x 3	Linear	150	U.FL / I-PEX	50
												698 MHz	1.8						
molex	1462340100		Х	х	х						FPC / Adhesive	1500 MHz	2.8	>70	140 x 20 x 0.1	Linear	100	U.FL / I-PEX	50
Ε												2.7 GHz	5.0		X U.1			I-PEX	
		_										824 MHz	0	>30					
	2072350100		X	х	х						FPC / Adhesive	1710 MHz	4.3	>60	40.4 x 15.4 x 0.1	Linear	100	U.FL / I-PEX	50
		生化										880-960 MHz	1	50				U.FL	
	W3915		х	х						х	PCB	1710-2170 MHz	2	75	74 x 19	Linear	100	com- pati-	50
		1										1565-1605 MHz	0.5	55				ble	
												2400-2500 MHz	4	50				U.FL	
	W3334B0150						х	х	x		Adhesive	4900-6000 MHz	5.5	70	4.3 x 15.3 x 0.1	Linear	150	com- pati- ble	50
Pulse												698-960 MHz	1.9	45					
Ē												1400-1600 MHz	2.5	53	20 100			U.FL	
	W3554B0140		Х	х	Х						FPC / Adhesive	1710-2690 MHz	3.2	66	30 x 120 x 0.2	Linear	143	com- pati-	50
												3300-3800 MHz	3.3	57				ble	
												4900-6000 MHz	3.5	37					
	W3312XXXXXX						х				FPC / Adhesive	863-928 MHz	0.8	45	75 x 15	Linear	100	U.FL com- pati- ble	50
	ANTX100P001B24553							v	x		PCB	2400 - 2500 MHz	4.6	81	50 x 10 x	Lincor	100	U.FL / I-PEX	50
Yageo	ANTATUUPUUTB24553							X	Х		PUB	5150 - 5875 MHz	3.9	62	0,95	Linear	100	I-PEX	50
Υag	ANTX100P001BWPEN3			v							PCB	850-960 MHz	5.1	68	50 x 10 x	Lincor	100	U.FL /	50
	VIAIVIOOLOOIDMAENS		X	X							FUD	1800-2100 MHz	5.0	76	0,95	Linear	100	I-PEX	50

*Not specified by supplier

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External Antennas

					St	tanda	ard												_
Manufacturer	Part	Picture	GSM / 2G	UMTS / 3G			ISM Standard	WLAN	GNSS	Antenna Type	Frequencies	Peak Gain (dBi)	Eff. (%)	VSWR	Size (mm)	Polarization	Cable Length (mm)	Connector	Impedance (Ohm)
	2J3704M	1	x	х						Magnetic	824 - 960 MHz	~1.7	~49	~1.6:1	30.9 x 71.5	Linear	3000	SMA-Male	50
		A								Mount	1710 - 2170 MHz	~0.3	~28	~1.8:1	30.9 x 71.5	Linear	3000	SMA-Male	50
	2J6604B		х	х			х	x	L	Body Mount	824 - 2400 MHz	~2.2	*	<2.6:1	77.4 x 15.9	Linear	2500	FME-Female	50
	2J6200PF		x	Х					x	Adhesive Mount	824 - 960 MHz	~1.5	~43	~1.6:1	Ø77 x 12	Linear	3000	SMA-Male	50
										WOUTE	1710 - 2170 MHz	~0.5	~32	~2.4:1					
	2J6602B						x x	x		Screw Mount	2410 - 2490 GHz	~4.9	~48.7	~1.5:1	Ø77.3 x 15	Linear	3000	RP-SMA-Male	50
		7									4920 - 5925 GHz	~4.5	~29.2	~1.5:1					
	2J5115-XXX	1				1	x			Adhesive Mount, Flexible	433/868/ 915 MHz	3,4	62,4	1,2	122 x 14 x 6	Linear	3000	multiple connectors available	50
	2J0102	1								Connector	2410 - 2490 GHz	~4.0	~60	~1.4:1	56 v 0 5	Linnar		RP-SMA-Male	50
	2J0102						х	X		Mount	4920 - 5925 GHz	~5.2	~83	~1.7:1	56 x 9.5	Linear	-	KP-SMA-Male	50
											698 - 960 MHz	~-0.8	~35	~2.8:1	Ø77.3 x 65.5				
	2J6A24BA		х	х	x					Screw Mount	1710 - 2170 MHz	~2.5	~51	~1.7:1	Ø77.3 x 65.6	Linear	3000	SMA-Male	50
											2500 - 2700 MHz	~3.4	~49	~1.3:1	Ø77.3 x 65.7				
											698-960 MHz	~1.0	~47	~1.9:1					
	2J3024M		х	х	х					Magnetic Mount	1710 - 2170 MHz	~2.4	~39	~1.5:1	Ø31 x 72	Linear	3000	SMA-Male	50
		•									2500 - 2700 MHz	~2.1	~36	~1.3:1					
_	2J6700B	•	х	Х			X	x	x	Body	824 - 2170 MHz	2.2 max	*	<2:1	77.3 x 36.5	Hori- zontal	2500	C1(Mobile): FME-Female;	50
2		1/								Mount	1575.42 MHz	*	*	<1.2:1		RHCP		C2 (Navigation): SMA-Male	
	2J0B15						X			Connector Mount	433/868/ 915 MHz	1.2	69.3	1.8	44-48 x 19,1 x 9	Linear	-	SMA-Male-R/A	50
											698-960 MHz 1710 -	~2.9	~55.6	~2.2:1					
									П		2170 MHz	~3.2	~56.0	~1.2:1				SMA-Male	
	21000000									Adhesive	2500 - 2700 MHz	~2.1	~38.7	~2.2:1	00 76 16	Linear	2000		F0
	2J6050PGF		X	Х	X		Х	X	X	Mount	2410 - 2490 MHz	~3.2	~50	~1.3:1	80 x 76 x 16		3000	RP-SMA-Male	50
		III							П		4920 - 5925 MHz	~4.2	~30	~1.3:1				THE CHARTHAIC	
									П		1575 - 1606 MHz	*	*	<=1.4:1 dB		RHCP		SMA-Male	
											698-960 MHz	2.6	56	2.1:1					
	2J7624B	48	х	х	x		x x	x	X	Screw	1710 - 2170 MHz	3.2	56	1.8:1	Ø50 x 50.08	Linear	3000	SMA-Male	50
		700								Mount	2500 - 2700 MHz	1.4	38	2.5:1					
											617-960 MHz	0.4	~50	1.6					
	2jw1483			Ų	х					Connector	1427 - 2690 MHz	0.6	~52	1.7	192 ×	Linear		SMA-Male	50
	2JW1403		X	Х	^	X				Mount	3300 -	1.6	~28	6.3	20 × 18	Lineai		JIVIA-IVIAIC	30
											3800 MHz 617-960 MHz	1.1	~37.1	2.0					
											1427 -	0.5	~43.3	2.6					
	2JW1183-C952B		x	х	х	x				Connector Mount	2690 MHz 3300 - 5000 MHz	0.3	~35.1	2.3	135×19×10	Linear	-	SMA-Male	50
											5150 -	1.6	~41.9	2.2					
		_									5925 MHz 698-960 MHz	0.4	~62	2.4					
	0 114/01/04									Connector	1710 -	2.6	~75	1.6	171, 20, 12.0	Lies		(DD)0444 44 1	F0
	2JW0124		X	Х	X					Mount	2170 MHz 2500 -				171×38×13.8	Linear	-	(RP-)SMA-Male	50
		7									2700 MHz	1.3	~50	2.2					

					Star	ndar	d												=
Manufacturer	Part	Picture	GSM / 2G	UMTS / 3G	5G (Sub6Ghz)	ISM Standard	Bluetooth	WLAN	GNSS	Antenna Type	Frequencies	Peak Gain (dBi)	Eff. (%)	VSWR	Size (mm)	Polarization	Cable Length (mm)	Connector	Impedance (Ohm)
s	1002857								X	Helical	1575 MHz	~3.0	27	2.0:1 max	Ø15.0 x 34.93	RHCP	-	SMA-Male	50
AVX ethertronics	9000984	/				x				Screw Mount	790 MHz 868 MHz 915 MHz	~2.2 ~2.2 ~3.4	40 80 75	2.0:1	196 x 13	Linear		SMA-Male	50
¥	X9001546	1	x :	x x						Connector Mount	698-960 MHz 1710 - 2690 MHz	*	~40 ~50	*	168×18	Linear	-	SMA-Male	50
	AA-C02MT07FME -397		x							Magnetic Mount	900 MHz 1800 MHz	~0.45	75 48	1.26:1 1.69:1	Ø26.7 x 79	Linear	3000	FME-Female	50
	AA-C13M05SMA -1107	-	x							Magnetic Mount	900 MHz 1800 MHz	~1.71	60 63	1.85:1 1.69:1	Ø52.2 x 343.7	Linear	3000	SMA-Male	50
	EM- B10.0X106-069						x	x		Connector Mount	2.4 GHz	~3.5	45	1.7:1	Ø67.5 x 108.0	Linear	-	SMA-Male	
	EM-W117G-2ANT -240	_				х				Connector Mount	868 MHz	0~3	٠	2.0:1	Ø37 x 112.6	Vertical	-	SMA-Male	50
iore	GS-10D174MCX -198								X	Adhesive Mount	1575.42 MHz	~3.8	*	2.0:1	38.2 x 34.2	RHCP	300	MCX-Male	50
chinmore	CA-C09-1SMAM -094		x							Adhesive Mount	840-960 MHz 1760 - 1860 MHz	~3.06	59 88	1.72:1 1.30:1	129.5 x 22.8	Linear	3000	SMA-Male (90°)	50
	EM-B9.3X33.0-168						х	х		Connector Mount	2.4 GHz	1.3	*	2.0:1	Ø9.4 x 33	Vertical	-	SMA-Male	50
	EM-9.10X55.8-058		x :	x						Connector Mount	824-960 MHz 1710 - 2170 MHz	~2.3	*	2.5:1	Ø6.5 x 56.6	Vertical	-	SMA-Male	50
	EM-W79B- 7ANT-108	7	x :	x						Connector Mount	824 - 2170 MHz	~2.8	*	5.6:1	Ø9.3 x 114	Vertical	-	FME-Female	50
	CA-									Adhesive	900 -	~1,78	42	1.36:1	100 5 00 0	Linnan	2000	EME Famala	F0
	CA- CO9-1FMEF-019			X						Mount	1800 MHz	~4.77	81	1.45:1	129.5 x 22.8	Linear	3000	FME-Female	50
											824 - 1710 MHz	~0.5	21						
molex	2068663000			x			x	х	х	Adhesive Mount	1575 MHz	~2.7	23	3 max	Ø77 x 15	Linear, RHCP	3000	FAKRA	50
											2.4 GHz	3.0	27						
		11								Connector	2.4-2.5 GHz	1.9	>80						
	W5028x	11				X	X	X		Connector Mount	5.15-5.85 GHz	3.8	>50	*	Ø10 x 128	Vertical	-	RP-SMA-Male	50
0										0	698-960 MHz 1400 -	2	58	3 max				TNICAAL	
Pulse	W5084x	-	X	х						Connector Mount	2690 MHz 3400 - 3700 MHz	5	78 60	3.6 max 3 max	228.84	Vertical	-	TNC-Male/ SMA-Male	50
	W5017	11				x				Connector Mount	868-928 MHz	0.9	70	2.5 max	179	Vertical	-	SMA-Male	50













Linecard **Electromechanical Components**

On request, RUTRONIK EMBEDDED will also put together individual kits for you which precisely meet the specific needs of your application. In addition to the primary components, these also contain all necessary inverters, cables, connection solutions and power supplies. We adapt the peripheral products precisely to your requirements, thereby offering you in cooperation with our partners a tailored solution for your system.

Batteries, Thermal Management, Fuses & Relays

Electromechanical Components	3M	Adam lech	Alysium	Amphenol	Assmann WSW	AVX	CER	Conquer	Coto	Delta	Diptronics	Eaton	EEMB	Finder	Fischer Elektronik	Fujitsu	Gradconn	InnoTane	JAE	Jamicon	Keystone	Knitter-Switch	Kyocera	Littelfuse	Lumberg	Lutronic	MPE Garry	Nexem	NF Forward	Omron	Panasonic	Preci-Dip	Pulse	Renata	RF Plast	Saft	Samsung SDI	Sauro	Schurter	Siba Sumida	
Batteries	.,,			_				, ,		_	_						_			•	_	_	_	_			-	_	-	_	_				_	٠,	٠,	٠,	,	, .	i
Lithium Ion																																					χ				
Lithium Polymer													Χ																					X							
Nickel Batteries (NiMH, NiCd)																															Χ										
Lead Acid																															Χ										
Lithium Metal													Χ																		Χ			Χ		Χ					
Alkaline																															Χ						П				
Battery Holder		X																			χ													Х							
Thermal Manageme	ent																																								
AC Fans		Х																		Χ																					
DC Fans		χ								Χ										χ																					
CPU Cooler		Х								Χ																															
Blowers		Х								Χ										χ																					
Heatsinks					χ					χ					X																				Χ						
Heat Contacting Foils	Χ														X X			X													Χ					Т					
Heat Pads	X														Χ			Χ													X										
Fuses																			_																						Ī
5x20 Fuses								X				Χ												Χ															Х	Х	
6.3x32 Fuses								X				χ												Χ															X	Х	
Automotive Fuses																								Χ																	
Subminiature Fuses								Χ				χ												Χ															Х	Χ	
SMT Fuses								X				Χ												Χ															Х	Х	
Resettable Fuses								X				Χ												Χ															Х		
Fuseholders 5x20								X				Χ												Χ															X	Х	
Relays																																									
Signal Relays													П	χ	-	Х	Х	1										Χ		χ)								i
HF Relays																Χ	Х													Χ			>	(
Power Relays														Χ		X	X											Χ	Х	χ)	(
Automotive Relays													T		ı	X X X	X	1										X		^											
Security Relays														Χ			Х													χ											
Photomos Relays									Χ																					χ											
Solid State Relays)	<									Х	1											Χ	^											
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Reed Relays)	(Χ															X																	
Reed Switch)	(7.															X X X																	
Proximity							>	(
Tilt & Tip-Over																																									
Switches																																									
Timer Relays														Χ																			>	(
Industrial Relays														X			X	1											Χ)	(
Sockets														X			X												X	Χ			\ \	1							



Switches, Connectors, Cables & Terminal Blocks

Electromechanical Components	3M	Adam Tech	ADDA	Amphenol	Assmann WSW	AVX	C&K	Comus	Conquer	Delta	Diptronics	Eaton	EEMB	Fischer Elektronik	Fujitsu	Gradconn	HongFa	InnoTape	JAE	Jamicon	Keystone Knitter-Switch	Kvocera	Littelfuse	Lumberg	Lutronic	MPE Garry	Nexem	NF Forward	Omron	Panasonic	Preci-Dip	Pulse	Renata	RF Plast	Saft	Samsung SDI	Sauro	Schurter	Siba	Sumida
Switches																																								
Automotive Switches							Χ				X										>									Χ										
Tact Switches							Χ				Х										>								X X	Χ								Χ		
DIP Switches							Χ				Χ										>								Χ											
Slide Switches							Χ				Χ										>																			
Pushbutton Switches							Χ				Χ										>																	Χ		
Rotary Position Switches							Х														>																			
Rotary Coded Switches							Χ				Χ										>								Χ											
Encoder Switches							X														>									Χ										
Toggle Switches							Χ														>																			
Membran Keypads																					X																	Χ		
Rubber Keypads																					>																	X		
Navigation Switches							Χ				Χ										>																			
Industrial Switches							X														<i>></i>																	Χ		
Rocker Switches							X))								Χ											
Detect / Micro Switch							X				Χ										>								X	Χ										
Interconnect Solution	ns /	Conr	1ect	ore			7.				Λ.																		· ·											
Board to Board	X		.000	Х	Y	Х										Χ			Χ			X		Χ	7	X					χ									
Wire to Board	X	Y		X	X	Y										Λ			X			^		Y	>	X					^									
Wire to Board Wire to Wire	X	X X		X	X	X X													X					X																
Crimp Terminals	^	X		X	\ \ \ \ \	^													Χ					^	>															
FFC/FPC		Х	_	(X	X														Х			Χ			>															
				X	_														٨			^	•			X					Χ									
Socket		X			\ \ \ \ \																				_	_					_	/								
USB		X		X	X																				>							X X								
USB Type C	V	X X X		X		. V										. V			X						>							X.								
Memory	Χ	X		X		Х										Х			X						>															
Audio/Video		X		Х	Х														Χ					Χ)						٠,									
Modular Jacks		Χ		Χ	Х																				>							X								
Power Inlet, Power		V		V	x																																			
Outlet, IEC 60320,		X		X	^																					X														
Valve D-Sub		Χ		X	Х																				_															
		Х		X	X																				>							v .								
High Speed FAKRA				X	^																										•	X								
	Χ	X		X	Х	V)	7														
DIN 41612	٨	^		^	^	Х																																		
DIN Connector, Mini I/O, Chinch, Military, Tool, Audio, DC Power		Х		Х	Х																			Χ																
Circular Connectors																																								
M8, M12, others		Х		Х	Х																				X															
EV charging AC, DC, Combined		Х		X												V			X																					
Coaxial Connector		X)	X												Χ								V	>												V-			
Terminal Blocks		Х		Χ	Х																			Χ													Χ			
Accessory like Jumper, Cap, Holder, Clip		х																								X														<
Customized Connect.		Χ		Y	Х	У										Χ			X							У														
Tools		A		X	А	71										-/\			X					Χ	>															
Cable & Cable Asser	mhly			Λ															Λ					Λ																
Round Cable	Jıy		7	X	Y																																			
Flat Cable	Χ		-	, ,	X																																			
FFC/FPC	٨	Χ	7	X	_																	Χ			>														1	X
Accessory like		Λ		Λ ,	Λ																	^																		
Cable Tie Standard Assembly,					Х																																			
PnP cable (like Patch Cable)		Х	>	(X														X						>															
Customized Assembly		Χ)	(X	χ											χ			χ						>															











Electromechanical Components

I/O Connector

Amphenol ICC **USB Type-C Connector**

Features

- Similar size as Micro USB
- Tailored for emerging product designs
- Supports high speed transmission up to 10Gb/s
- Up to 10,000 mating cycles
- Extended 5A current rating for USB Power delivery

Benefits

- Reversible plug and cable orientation for better user experience
- Smaller connector size saves space
- Meets USB power delivery protocol
- Supports audio and video signal output with alternate mode

Wire-to-Wire Connector

Amphenol

Heavymate, MPN Series C146

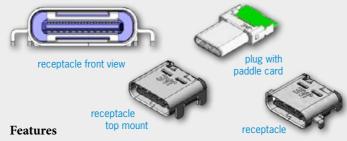


- Hybrid interconnection
- High current up to 250 A
- Pole size from 3 up to 280 poles
- Voltage up to 1000 V
- IP65 to IP68
- High corrosion resistance
- Superior contact technology (Radsok & stamped contacts)
- Very robust & vibration proof housing

I/O Connector



DX07 – USB Type-C Connector



- Reversible plug that enables insertion and removal in the right side up or up side down orientation
- Supports USB 3.1/3.2 transmission speeds of up to 20 Gbps
- Maximum 5 A of power
- Includes plugs, receptacles and harnesses -2 waterproofed versions available

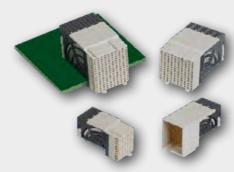
Benefits

- Design for high mechanical strength
- Lock structure with high durability
- 2-row SMT type space-saving contact mounting area (pure and hybrid)
- Availlable in on-board, mid-mount and vertical type

Board-to-Board Connector

Amphenol ICC

Airmax Backplane Connectors



Features

- Up to 25 Gbs per differential pair
- Over 10 years history of high volume production
- Full product platform (right angle, coplanar, orthogonal, cable.
- PCIe, CompactPCI, SAS, SBB, SSI, OIF 25G, QPI 8G

Benefits

- Front housing provides guidance and protect pins
- Standard guidance and power modules can be placed as needed
- Rear plastic organizers unitize the block
- Enhanced for optimized cost & improved performance

Wire-to-Board Connector





Series 70-9296

Single contacts

- Flat
- Coplanar
- Low cost
- PCB mating

• Gas tight

Series 00-9296

Poke Home Vertical Top Entry

Unique 1-piece vertical WTB to compete with 2-piece



Series 9176-500

Single IDC contact

Low costSingle



Series 9176-700

Capped IDC

Simplifies Integrated cap assembly



Series 70-9159

- Single 2pc contacts ■ Flat
- Coplanar
- Low cost

PCB mating

Amphenol

High-Power Connectors

RADLOK™

Features

- DC Voltage Rating: 1000 V;
- Current Rating: 70 A - 400 A
- Tool-Free Mechanical Locking
- High cycle durability (500 mating cycles)
- Operating temperature -40 °C to +125 °C

Benefits

• Quick locking feature to replace a

- Pre-assembled & supplied with cable
- Reliable, easy to install, rugged, and cost effective
- Colors: orange, red, and black

FFC Cable & Connector Solutions



- 1.25 mm / 1.0 mm / 0.5 mm
- Shielding for high frequency applications

Features

Pitch:

ALYSIUM

- High density
- Reduced connection costs
- Custom design
- Easy to insert

Modular Jacks

MTJ Series



Features

- Voltage rating up to $150 \, \mathrm{V}_{\mathrm{AC}}$
- Current rating up to 1.5 A
- Contact resistance: Max. $20 \text{ m}\Omega$ (initial)
- Operating temperature: -40°C to +85°C



Benefits

- Magnetic and ferrite-filtered types available
- Single, stacked or ganged

Amphenol

molex

- Through-hole or SMT
- 4, 6, 8, and 10 positions available mounting

Memory & Media Card Reader

Features

- Operating temperature: -20°C to +60°C
- Mechanical lifetime 300,000 mating cycles
- SMT and TMT available
- Secure contact to all cards designed according to ISO 7816

Benefits

- Highly reliable data transmission
- Landing, self-cleaning contacts
- Suitable for automatic reflow process or wave soldering
- Correct orientation of SIM card

Memory & Media Card Reader

Features

Anti-stubbing contact terminal design

- Free insertion and withdrawal of microSD card
- Compact size with small footprint and low profile height
- Card polarization feature
- Pull-lever and push-pull card eject options
- Multiple PCB hold-down points

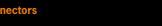
Benefits

- Prevents microSD card from becoming stuck when inserted incorrectly into the micro SIM slot
- Prevents contact stubbing and ensures smooth insertion and withdrawal of the card

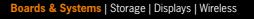


















Electromechanical Components

Power Supply Connector



Power In- and Outlets IEC 60320

Features

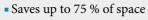
- Design: Inlet, outlet, combi/multi
- Mounting: Horizontal, vertical, bottom, snap-in, rewireable cable connector
- Cable termin.: Screw, quick connection, solder lug
- Board termin.: Through hole
- Voltage selector: With, without
- Rated current: 2.5 A, 6.3 A, 10 A (15 A acc. UL), 16 A (20 A acc. UL)
- Configuration: C8, C14-C18, C20-C24,

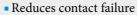
Industrial Mini I/O Connector

Features

- Voltage rating: 30 V / Current rating: 0.5 A
- Operating temperature: -40 °C to +85 °C
- Durability: up to 1,500 mating cycles

Benefits





- Protects plug from accidental pulling and unplugging
- More compact size compared to conventional RJ45
- Ensures high temperature resistance

Amphenol ICC

Time-Lag (T) versions

Precise, low power dissipation, resistant to vibrations and pulses

Applications

Type

USFF 1206, USF 1206, USI 1206, UST 1206,

USF 0603, USF 0402

Features and Benefits

Secondary protection on SMDSensors **PCBs** Lighting

Numerous current ratings from 50 mA to 25 A

Super-Quick-Acting (FF), Quick-Acting (F) and

• High breaking capacity of up to 600 A (internal tests)

• High rated voltages up to 125 V_{AC} / V_{DC}

Industrial electronics

Mobile devices

protection

Smart meters

Battery protection

Semiconductor

Main Filter



1-Stage Filter for 1- and 3-phase Systems **DIN Rail Mounting**



Description

- Chassis: DIN rail montage
- Line filter in industrial version, 1 stage, high attenuation
- Especially effective against asymmetrical interferences in the frequency range
- From 100 kHz up to 30 MHz
- Easy and time saving handling

Characteristics

- Protection against interference voltage from the mains
- Possible interferences generated in the equipment are strongly attenuated
- Especially designed for electric switch and control cabinets
- Suitable for use in equipment according to IEC/UL 60950

Approvals

- VDE Certification
- UL File

Relays

Industrial Relays















OMRON

Focus at Rutronik is the Power Relay Group

Rutronik offers a broad range of high quality products for all applications as well as special approved parts for white good applications, home automation, renewable energy, and industrial exercise. Our suppliers provide all approvals like UL, VDE, CSA, TÜV etc. We offer different contact materials so you can select the best solution for your need. All available coil voltages can be offered.

Applications

- Fans (motors)
- Door motors
- Alarm lighting Contact loads
- Pump motors
- Heater element Lighting applications Smart meter
- White goods







Switches

DIP & Code Switches

C&K Components is a leader in interface and switch technology. C&K offers more than 55,000 part numbers that are built, priced and delivered as standard catalog items, including tactile, navigation, detect, toggle, rocker, pushbutton, rotary, key, slide, DIP, thumbwheel and illuminated switch products, along with smart card and high-reliability connectors. C&K has built its reputation as a customerfocused organization, providing superior support, flexibility and solutions at competitive prices. Whether it's a standard, special or custom product, C&K will deliver a cost-effective component for all application-specific requirements.

CRD Series

10mm DIP Coded Rotary Switches

- Process sealed withstands soldering and cleaning
- Thru-hole & surface mount models
- Crisp, positive detent ensures actuation
- Computer & peripherals
- RoHS compliant
- Mechan. life: 30,000 steps min.
- Operating temperature:
- -20 °C to 85 °C

RTE Series

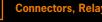
Low Profile Rotary DIP Switches

- Miniature size with robust metal cover
- 2, 3, 4, 10 and 16 positions
- Variety of codings available
- Vertical and reverse versions
- RoHS compliant
- RTE02/03:
- 1,500 actuations;

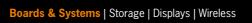








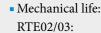












RTE04/10/16:

20,000 actuations

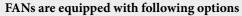
Electromechanical Components

Brushless Fans Provide Cooling Solutions for **Embedded Systems**

Kaimei Electronic Corp. has been designing, developing and manufacturing a broad line of AC and DC fans since 1990 and distributing them worldwide under the brand name Jamicon.

Kaimei Electronic Corp. has ISO 9001 and ISO14001 certificated manufacturing facilities in their home country of Taiwan as well as in China and Malaysia. In order to provide their services to various industries, recently their Shenzhen factory has obtained certification of TS16949 in 2014.

As the electronics industry matured and diversified, Jamicon always upholds its strict quality control policy. We value our customers needs and will continually develop the products that meet your expectation.



- Auto-Restart
- Speed Control
- PWM
- Connector: Housing Molex 470541000 compatible parts, Pitch: 2.54 mm

Features

- Operating Temperature: -10 °C to +70 °C
- Storage Temperature: -40 °C to 70 °C
- Safety Certificate: UL, CUL, TÜV, CE
- Insulation resistance: More than 10M ohm at 500 V.D.C. between lead and housing
- Dialectric strength: 700 V.A.C for 3 sec (max. 5 mA between lead and housing)







- Exceptional airflow performance and high static pressure
- Locked Motor protection: designed to meet UL, CUL, TÜV
- Polarity protection: reverse connection at the rated voltage will not cause any damage
- 2 Ball Bearing (very long life time)

Model No.	JF0825B1EK01CCGJKR	JF0925B1EK00CCGJKR	KF1225B1LK02CCGJJR
Dimension (mm)	80x80x25	92x92x25	120x120x25
Туре	DC	DC	DC
Voltage (V)	12	12	12
Bearing	2 Ball	2 Ball	2 Ball
Airflow (CFM)	18.93	30.86	56.29
Noise (dBA)	13.9	23.1	27.2
Speed (RPM)	1500	1700	1500
Input Power (W)	0.72	1.08	1.56
Input Current (A)	0.06	0.09	0.13
Cable Length (mm)	290+-10 mm	285+-10 mm	265+-10 mm
Rutronik No.	FAN4030	FAN4031	FAN4032

Cases

Aluminum & Design Cases

Features

- Extremely low losses of air due to optimized fin geometry
- Milled flat semiconductor mounting surface
- Segment cooling aggregates
- Miniature cooling aggregates
- Heatsink cooling aggregates
- Hollow fin cooling aggregates with axial fan
- High performance brazed cooling aggregates
- High performance heatsinks with hollow fin profile
- High performance cooling aggregates with radial fan
- Protection grid for fans

fischer elektronik to cool to protect to connect

Aluminum Cases

- Shell and extruded assembled cases
- Combination cases
- Tube cases
- Heat dissipation cases
- Miniature Aluminum cases
- Customized cases

Design Cases

- Aluminum cases with plastic design elements
- Cases with high IP-protection
- Cases for heat dissipation
- Large selection between different sizes and options
- Customizing and individual configuration

ASSMANN

Heatsinks

Heatsinks with Solder Pin



- With solder pin
- Retaining spring for transistors
- Delivered in black anodized finish
- Thermal resistance 6 to 16K/W

Attachable Heatsinks



- For TO-220 packages
- For TO-220 packages with straight solder pin
- For TO-220 packages with angled solder pin
- Thermal resistance >16K/W

Small Heatsinks



- Heatsinks for IC-module
- U-heatsinks for transistor TO-220 packages
- Special heats. for TO-220/SOT-32 packages
- SMD heatsink for D-Pak packages
- Stamped finger-shaped heatsinks
- Thermal resistance > 16K/W







Stamped CPU heatsink Stamped CPU heatsink +

Stamped CPU Heatsink

For PGA (pin grid array), BGA (ball grid array) and other high power components.

The new development series is a combination of cross-cut and finger-shaped heatsinks. Optimally used to mount the heatsink on the PCS via "Push Pins".

Advantages

The advantage of this new heatsink design improves the air convection.

Optional

- Alternative material thickness
- Modifications of all dimensions and perforations
- Special surface treatments
- Customer made heatsink attachement methods











Electromechanical Components

Batteries

Lithium Metal Coin Cells

Features	Benefits
Wide portfolio of coin sizes and	Different ways of contac-
variety of pin types	ting at different space
	Long-term energy,
 Low self discharge rates 	reliability and storability
 High energy desities up to 	
375 Wh/kg	
 Wide temperature range 	
Direct support at the world	High quality, best tech-
leading manufacturer of lithium metal coin cells	nical solution, safety and conformity
Unique diversity of technologies	Special series for lasting
,	back-up (BR), rechargeable
	usage (VL,ML,MT), high
	temp. up to 125°C (BR-A)



Туре	Primary	Battery		Rechargeable Battery	
	CR	BR	VL	ML	MT
Material Anode	MnO2	(CF)n	V205	LixMnOy	LixOy
Material Kathode	Li	Li	LiAl	LiAl	LixTiOy
Nom. Voltage (V)	3.0	3.0	3.0	3.0	1.5
Operating Temp. Range (°C)	-30 to +60	-30 to +80	-20 to +60	-20 to +60	-10 to +60
Self-discharge (per year) under standard conditions	1.0 %	1.0 %	2.0 %	2.0 %	2.0 %
Average Discharge Voltage (V)	-	-	2.85	2.5	1.2
Charge Voltage (V)	-	-	3.25 to 3.55	2.8 to 3.2	1.6 to 2.6
Cut-off Voltage (V)	2.0	2.0	2.5	2.0	1.0
Charge-discharge Cycles	-	-	1,000 charge/discharge partly (charge/discharge for 10% of discharge depth)	1,000 charge/discharge partly (charge/discharge for 10% of discharge depth)	500 charge/discharge up to 1V or discharge limit voltage (charge/discharge for 100% of discharge depth)















Faster. Easier. Just more personal. rutronik24.com



Committed to excellence



USA

Dallas

Rutronik Inc.

75093 Plano, TX

California

Tel +1 469 782 0900

95119 San Jose, CA

Tel. +1 669 247 5098

01742 Concord, MA

Massachusetts

Mexico

Shenzhen

Shanghai

Chengdu

Shanghai 201204

Tel. +86 21 38 86 78 88

International Center,

Tel. +86 28 8651 2664

54/F, Hopewell Centre

Mong Kong

International Branches

2745 North Dallas Parkway

Parkway Centre III, Suite 660

6203 San Ignacio Ave., Suite 110

300 Baker Avenue, Suite 300

Rutronik Mexico S.A. DE C.V.

PISO 11-C, Colonia San Pablo,

Room 807, No.98 Fuhua 1 Road

Tel. +86 755 21 37 60 00

Fax +86 755 21 37 60 01

Futian District, 518048 Shenzhen City

Room 1010, Dongchen Tower, No. 60

Room 709, Building G, China Overseas

No. 333 Jiaozi Avenue, 610041 Chengdu

Rutronik Electronics Asia HK Ltd

183 Queens Road East, Wan Chai

Rutronik Electronics Singapore Pte. Ltd.

Hong Kong, Tel. +852 3602 3135

Office No- 201, Regus, 2nd Floor

Bangalore-560068, India

Tel +91 9880146135

Bommanahalli Bangalore Kamataka

Mudan Road, Pudong New District

Corporativo Blanco 76130 Querétaro, Tel. +52 442 103 1805

European Branches

Austria

Rutronik Elektronische Bauelemente Ges. m. b. H. Durisolstraße 11 4600 Wels Tel. +43 7242 449 01

Belgium

Rutronik Belgium BVBA Keppekouter 1 Ninovesteenweg 198 9320 Erembodegem-Aalst Tel. +32 53 73 99 71

Bulgaria

Rutronik Elektronische Bauelemente GmbH Blvd. Nikola Vaptzarov 35 Business Center Lozenetz Floor 1, Office Nº 1B 1407 Sofia Tel +359 2 974 86 46

Czech Republic

Rutronik Elektronische Bauelemente CZ s.r.o.

Pražákova 1008/69, 15, floor 639 00 Brno Tel. +420 5 4 54 24-681

Prague

Na Pankraci 1638/43 140 00 Praha 4 Tel. +420 2 33 34 31 20

Denmark

Rutronik Electronics Denmark ApS Herstedøstervej 27-29 2620 Albertslund Tel +45 7020 1963

Rutronik Elektronische Bauelemente GmbH Riia 142 50411 Tartu Tel. +372 6500620

Hinland

Rutronik Elektronische Bauelemente GmbH Malminkaari 5 00700 Helsinki Tel. +358 9 32 91 22 00

France

Rutronik S.A.S 6, Mail de l'Europe 78170 La Celle St Cloud Tel. +33 1 30 08 33 00 rutronik_sas@rutronik.com

Bordeaux

Tel. +33 5 57 26 40 00

Grenoble

Tel. +33 4 76 61 00 90

Le Mans

Tel. +33 2 43 78 16 97

Tel +33 4 72 76 80 00

Tel. +33 2 23 45 14 40

Strasbourg Tel. +33 3 88 78 12 12

Hungary Rutronik Magyarország Kft. Alíz utca 1, 1117 Budapest Tel. +36 12 31 33 49

Italy
Rutronik Italia S.r.l. Via Caldera 21 Centro Direzionale S.Siro 20153 Milano (MI) Tel. +39 02 4 09 51-1 italia_MI@rutronik.com

Bologna

Tel. +39 051 64 63 20 1

Florence

Tel. +39 055 8 82 73 32

Padua

Tel. +39 049 869 78 00

Rome

Tel. +39 06 228 782-1

Tel. +39 011 9 02 20 00

Lithuania

Rutronik Elektronische Bauelemente GmbH Jonavos g. 30, 44262 Kaunas Tel. +370 37 261780

Netherlands

Rutronik Elektronische Bauelemente GmbH Takkebiisters 51a 4817BL Breda Tel. +31 76 57 230 00

Rutronik Elektronische Bauelemente GmbH Olaf Helsets vei 6, 0694 Oslo Tel. +47 22 76 79 20

Poland

Rutronik Polska Sp. z o.o. ul. Boikowska 37 44-101 Gliwice Tel. +48 32 461 20 00

ul. Batorego 28-32 81-366 Gdynia Tel. +48 58 7 83 20-20

ul. Broniewskiego 3 01-785 Warszawa Tel. +48 22 462 70-50

Portugal
Rutronik Elektronische Bauelemente GmbH Travessa Joaquim Sá Leonardo 85 4760-042 Vila Nova de Famalicão Tel. +351 252 312-336/337

Rutronik Elektronische Bauelemente GmbH Strada Divizia 9 Cavalerie 64 300254 Timişoara Tel. +40 25 6401240

Bucuresti

Tel. +40 21 3000141

Russia

Rutronik Beteiligungsgesellschaft mbH

Moscow

Leningradskoye Hwy, 57, Kor.2 125195 Moskwa Tel. +7 499 9633184

Saint Petersburg Naberezhnaya Reki Moyki 58 Office 609 191186 Saint Petersburg Tel. +7 812 321-63-68

Serbia
Rutronik Elektronische Bauelemente GmbH Maglajska 24a, 11000 Belgrade Tel. +381 (11) 40412 90

Slovakia

Rutronik Elektronische Bauelemente GmbH, o.z. 97401 Banská Bystrica Tel. +421 48 472 23-00

Slovenia

Rutronik Elektronische Bauelemente GmbH Motnica 5 1236 Trzin Tel. +386 1 5 61 09 80

Spain

Rutronik España S.L.

Barcelona

C/ Tarragona 149-157, 6° 2a 8014 Barcelona Tel. +34 93 444 2412

Madrid

C/ Santa Leonor 65, Avalon Parque Empresarial, Edificio A, Pta 4a, 28037 Madrid Tel. +34 91 3 00 55 28

San Sebastian

Pº Ubarburu 39 - Polígono 27 office 303 20014 Donostia Tel. +34 943 5095-00

Sweden

Rutronik Nordic AB Kista Science Tower Färögatan 33, 16451 Kista Tel. +46 8 50 55 49 00

Switzerland

Rutronik Elektronische Bauelemente AG

Volketswil

Brunnenstrasse 1 8604 Volketswil Tel. +41 44 9 47 37 37

Rutronik Elektronische Bauelemente GmbH

Barbaros Mahallesi, Ardic Sokak, Varyap Meridian G2 Blok, No.: 09

34746 Bati Atasehir, Istanbul rutronik_tr@rutronik.com

United Kingdom

& Ireland

Rutronik UK Ltd.

Headquarters UK

The Valley, Bolton 1-3 Courtyard, Calvin Street BL1 8PB, Lancashire, UK Tel. +44 1204 602200

Whitehill Way Windmill Hill Business Park SN5 6OR Swindon Tel. +44 1793 441885

Malaysia

India

26/1 Hosur Road

Rutronik Electronics Singapore Pte. Ltd. 73-3-1, Ideal @ The One, Jalan Mahsuri, Bayan Lepas 11950 Penang Tel. +60 124 280 181

Singapore
Rutronik Electronics Singapore Pte Ltd 10 ANG MO KIO Street 65 Techpoint #06-02A 569059 Singapore Tel. +65 6932 9778

Taiwan

Rutronik Electronics Asia HK Ltd

3F., No. 183, Zhouzi Street, Neihu District Taipei City 11493, Taiwan Tel. +886 2 2659 5889

Thailand

Rutronik Electronics Singapore Pte Ltd

2/1 Soi Rom Klao 25/2 Rom Klao Road, Khlongsamprawet Ladkrabang 10520 Bangkok Tel. +66 2 737 6423

more information, please contact our sales team. Prolongacion Tecnologico Norte 950B int. 1 JO2 ENG | KNA | Specifications subject to change without notice. Please note, there could be some limitations for some franchised product lines in several countries. For Rutronik Electronics (Shenzhen) Co., Ltd

Germany – Headquarters

Rutronik Elektronische Bauelemente GmbH | Industriestraße 2 | 75228 Ispringen / Pforzheim Tel. +49 7231 801-0 | Fax +49 7231 82282 | E-Mail: rutronik@rutronik.com | www.rutronik.com

Justus-von-Liebig-Straße 7 12489 Berlin Tel. +49 30 8 09 27 16-0

Radeburger Straße 172 01109 Dresden Tel. +49 351 20 53 30-0

Flughafenstraße 4 99092 Erfurt Tel. +49 361 228 36-30

Frankfurt

Frankfurter Straße 151 c 63303 Dreieich Tel. +49 6103 270 03-0

Basler Landstraße 8 79111 Freiburg Tel. +49 761 61 1677-0

Hamburg

Neue Gröningerstraße 10 20457 Hamburg Tel. +49 40 3 59 60 06-20

Rendsburger Straße 32 30659 Hannover Tel. +49 511 228507-0

Amselstraße 33

68307 Mannheim Tel. +49 621 76 21 26-0

Landsberger Straße 392

81241 München Tel. +49 89 88 99 91-0

Nürnberg

Südwestpark 10/12 90449 Nürnberg Tel. +49 911 688 68-0

Brockweg 133

33332 Gütersloh Tel. +49 5241 23271-0

Ratingen Gothaer Straße 2 40880 Ratingen Tel. +49 2102 99 00-0